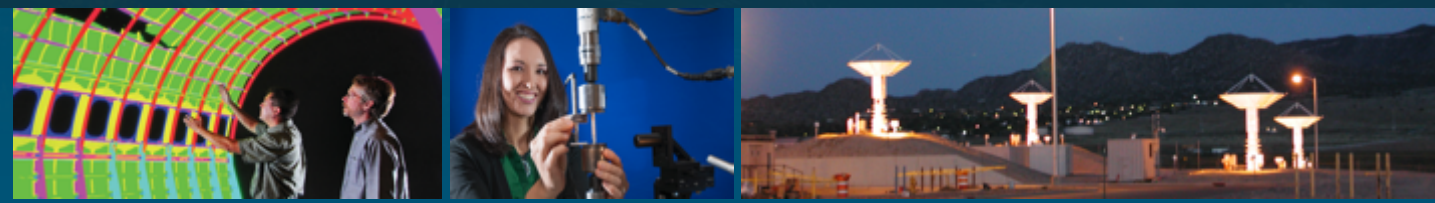




How MBSE is Reducing the Duration of the Nuclear Weapon Development Lifecycle



PRESENTED BY

Anthony Matta – Manager, Model Based Systems Engineering

- Casey Noll
- Erik Olson
- Ryan Coleman



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Sandia National Laboratories (SNL) Enterprise Pillars



The Foundation

Nurture and advance our capability-based science and engineering foundation through innovation to enable more agile and effective fulfillment of Sandia's nuclear weapons mission



Flexible and Responsive (Sustained) Deterrence

Strengthen the U.S. nuclear deterrence posture in an uncertain and rapidly changing global environment



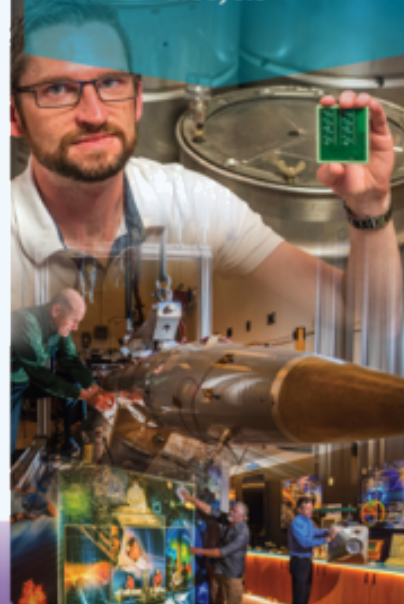
Nuclear Enterprise Assurance

Ensure research, design, development, production, testing, storage, packaging, transportation, maintenance, surveillance, dismantlement, and disposal for all current and future weapons are resilient to subversion attempts



Integrated Weapon and Physical Security

Create system solutions based on intelligence-informed threat assessments that provide security for U.S. nuclear weapons throughout their lifecycle



Stockpile Evaluation and Assessment

Drive agile, sustainable, forward looking assessment of U.S. nuclear weapons safety, security, and effectiveness through engagement and application of Sandia's broad capabilities



PEOPLE, FACILITIES, AND TECHNICAL CROSS-CUTS

Current Stockpile, Nuclear Triad, & Design



Principles



ALWAYS perform when intended



NEVER at any other unapproved time



Unique Nuclear Weapon Activities



Warhead systems engineering & integration



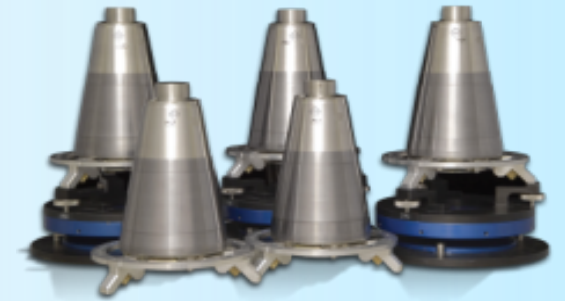
Design agency for Non-nuclear components

Gas transfer systems



Radar

Safety systems



Arming, fuzing & firing systems

Multi-disciplinary capabilities required for design, qualification, production, surveillance, experimentation/computation

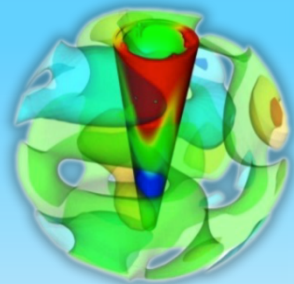
Major environmental test facilities & diagnostics



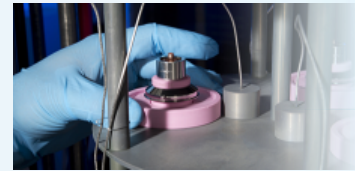
Materials Science



Light initiated high explosive



Computational analytics



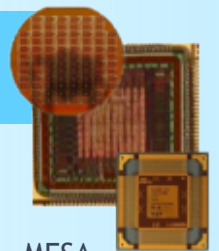
Neutron generators

Production agency

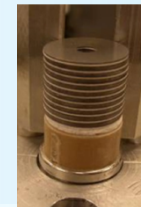
Sandia External Production



Neutron generators



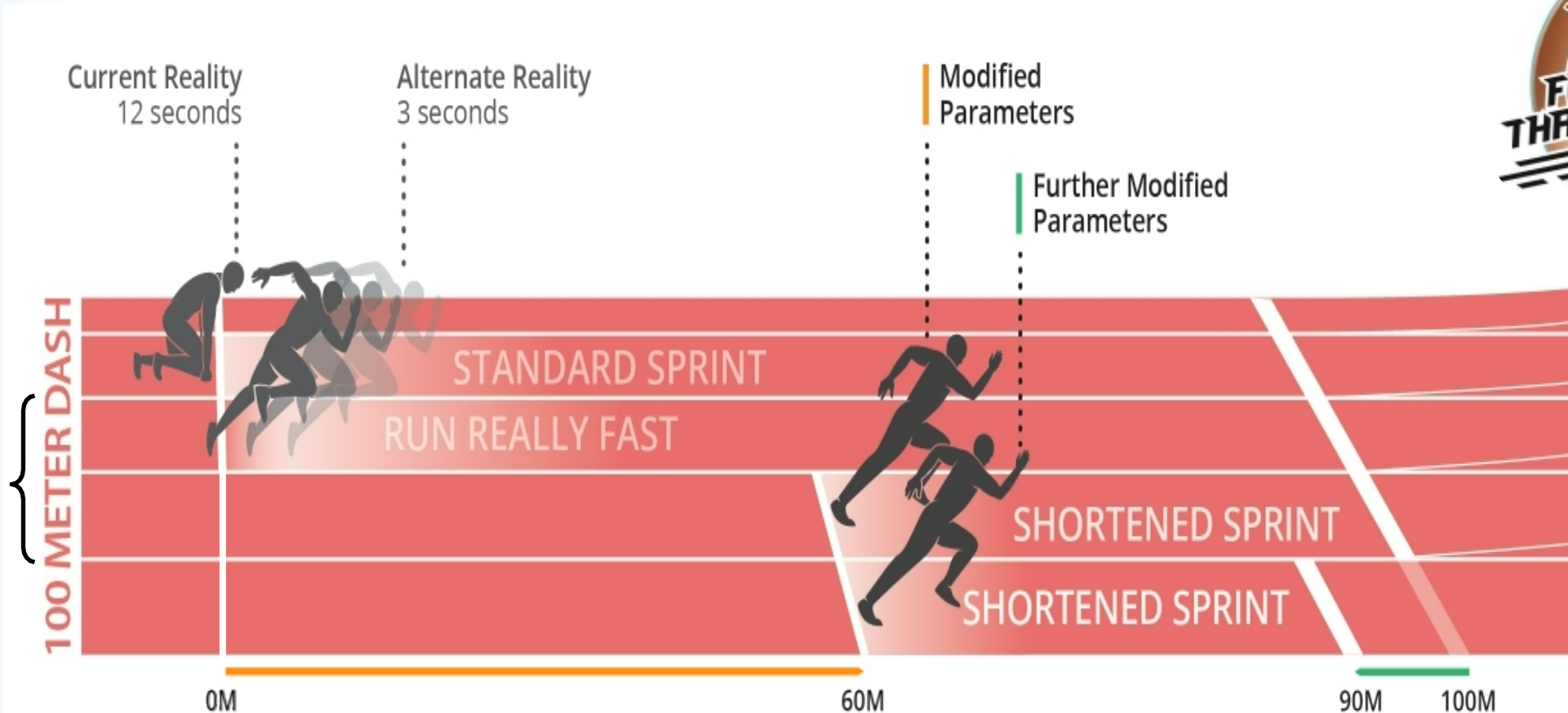
MESA microelectronics



Thermal battery back up



Two methods toward achieving the dramatic speed up:

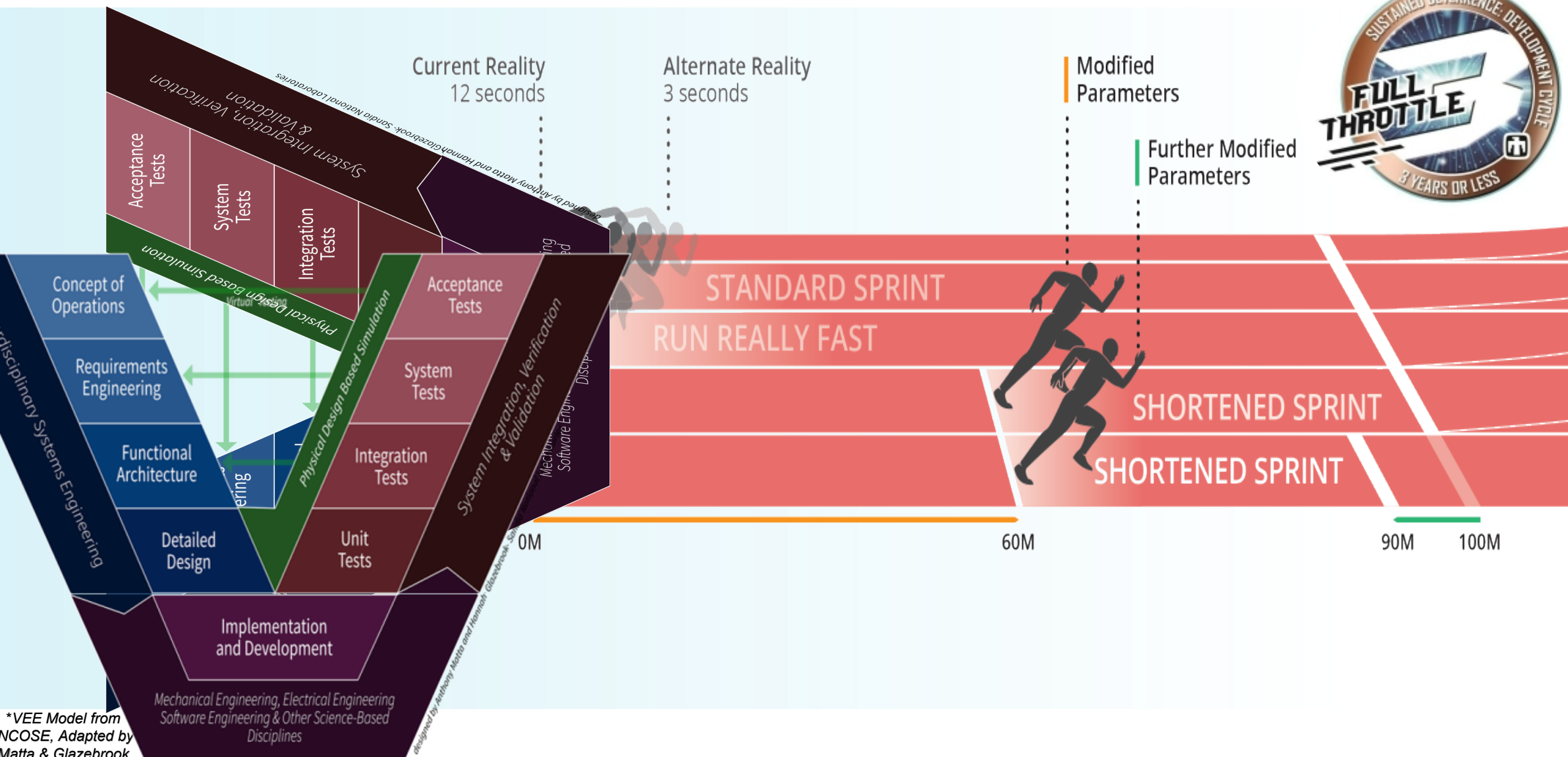


Move the starting line by building infrastructure

- Model-based approaches with reference architectures
- Common testers
- Design libraries
- Component reuse
- Modular architectures

May shorten the required distance by possibly performing some qualification after FPU

Strategy



*VEE Model from NCOSE, Adapted by Matta & Glazebrook

NW DESIGN
LIFECYCLE
FOCUS AREAS

Current Cycle
Time
~12 Years

AND



Casey Noll

- Verification & Validation MBSE
- Complex testing and environment reference architectures



Erik Olson

- Reduced order modeling
- Interrelating high fidelity physics codes for early design engineering



Ryan Coleman

- Digital Twin data strategy for integrated models
- Ontologically based integrated data sets

AND

Objective Cycle
Time
<3 Years

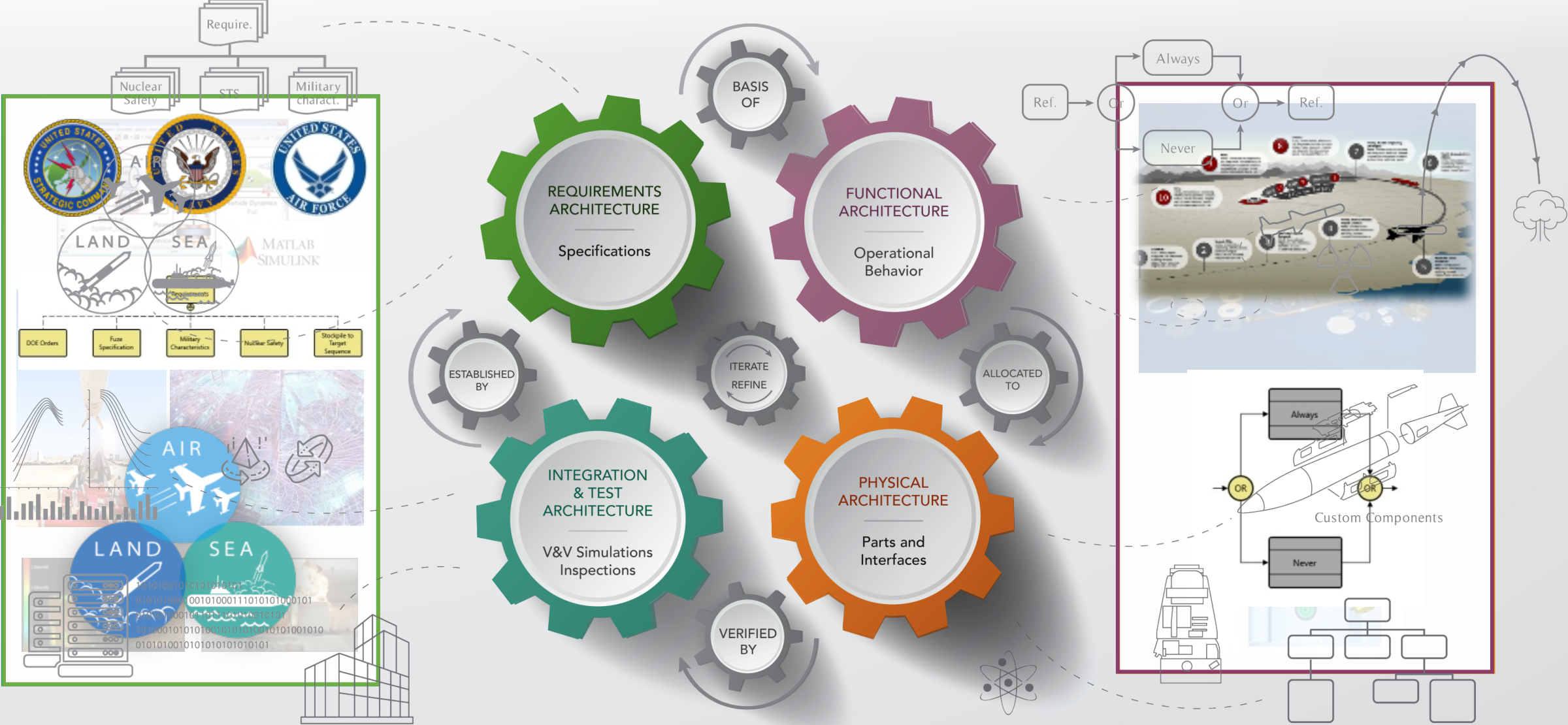


Casey Noll
R&D Systems Engineering

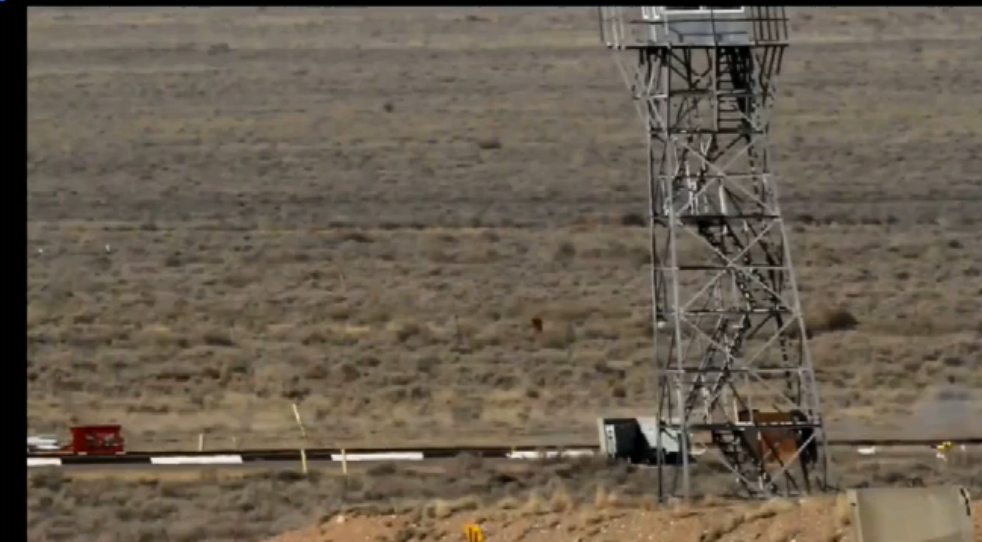
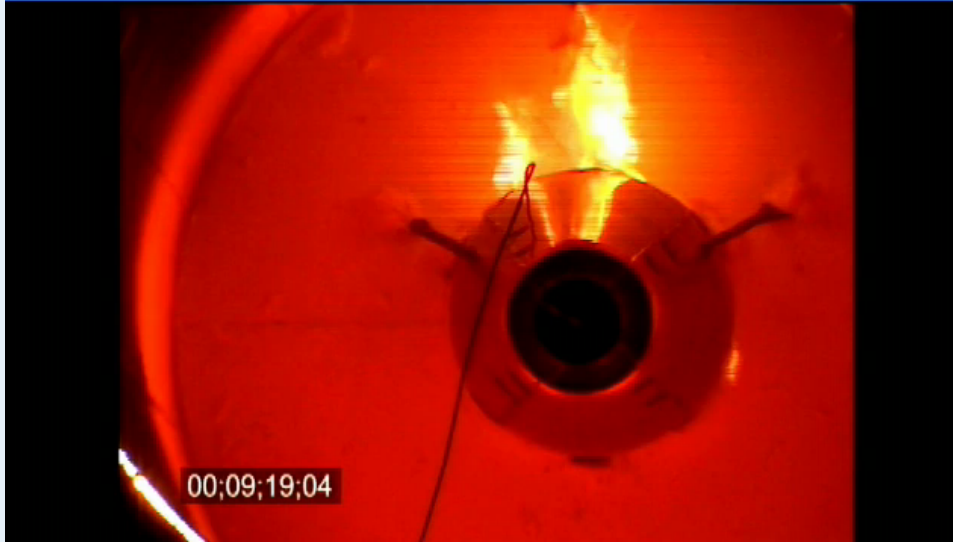
How Modeling Verification and Validation Activities Reduce the NW Development Time

Served as a Nuclear Weapon (NW) component Product Realization Team (PRT) Lead responsible for the development and transition to production of custom high reliability components supporting multiple programs impacting the NW stockpile. Casey has his BS/MS in Engineering Management, from Missouri University of Science and Technology and is currently pursuing his Master in Systems Engineering from Stevens Institute of Technology.

MBSE for Nuclear Deterrence

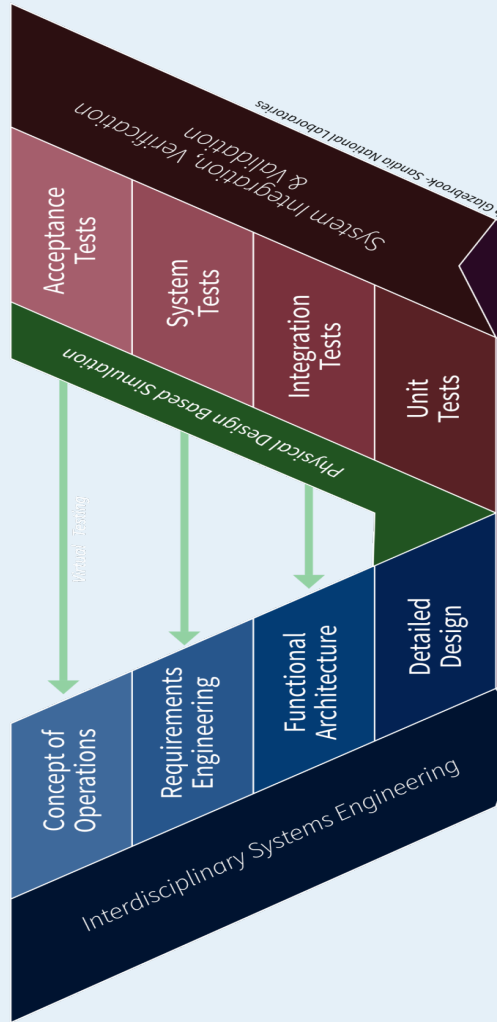


Verification & Validation



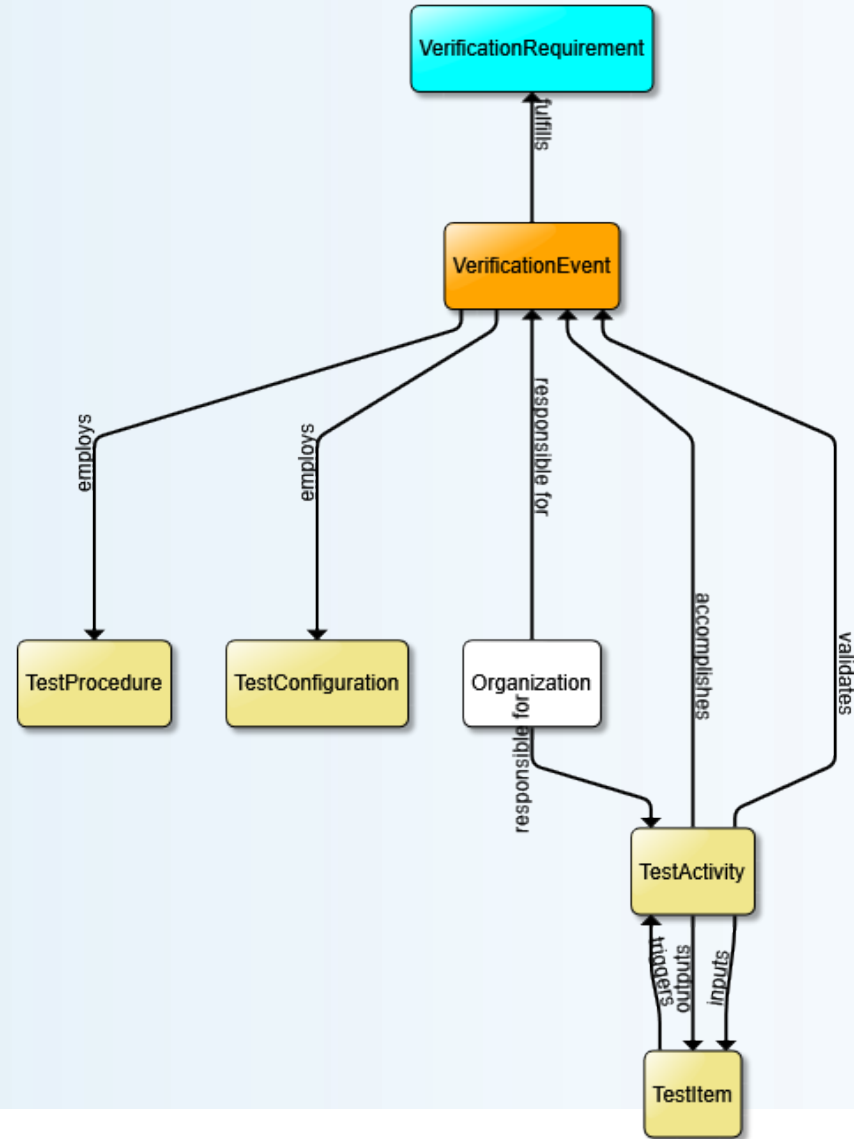
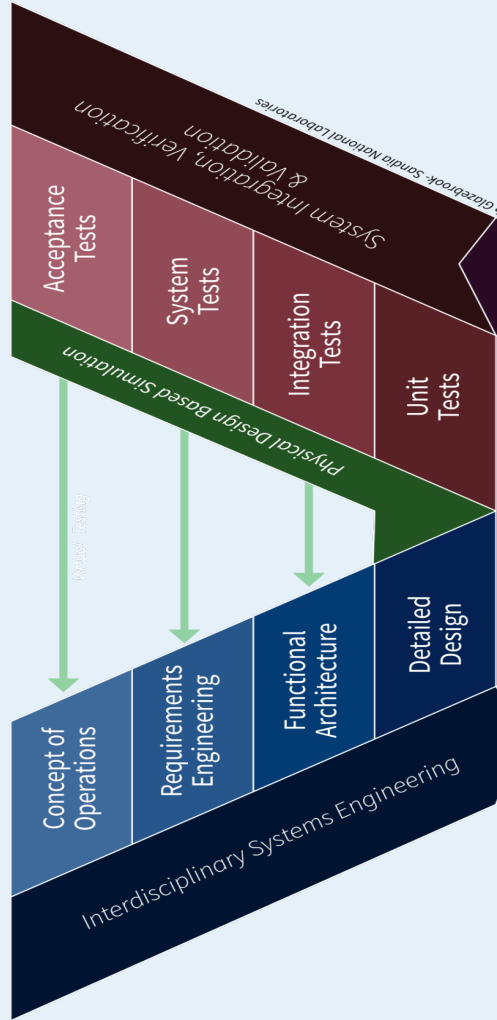
How can V&V modeling contribute to reducing the lifecycle for NW?

Verification & Validation

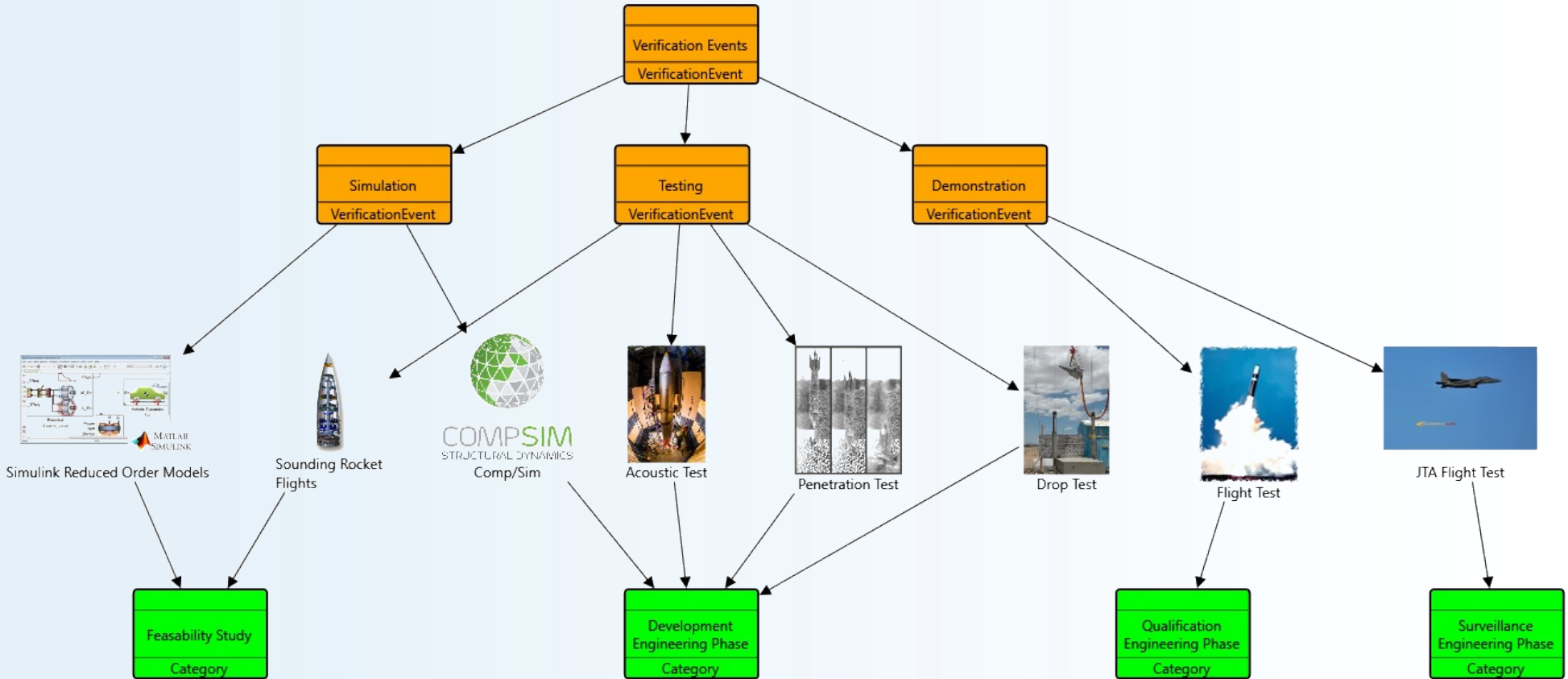
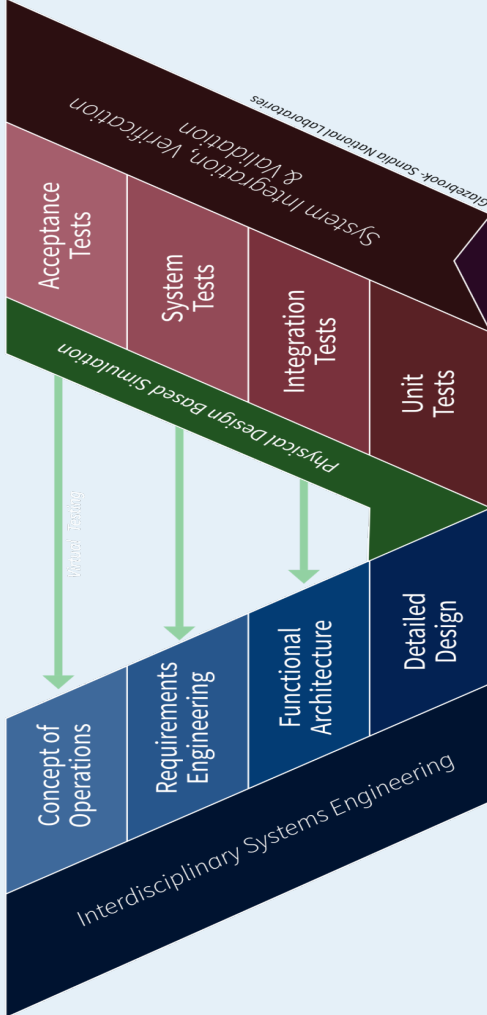


Requirement No.	Document	Paragraph	Shall Statement	Verification Success Criteria	Verification Method	Facility or Lab	Phase*	Acceptance Requirement?	Preflight Acceptance?	Performing Organization	Results
	<i>Unique identifier or each requirement</i>	<i>Paragraph number of the requirement</i>	<i>Text (within reason) of the requirement, i.e., the "shall"</i>	<i>Success criteria for the requirement</i>	<i>Verification method for the requirement (analysis, inspection, demonstration, test)</i>	<i>Facility or laboratory used to perform the verification and validation.</i>	<i>Phase in which the verification and validation will be performed.</i>	<i>Indicate whether this requirement is also verified during initial acceptance testing of each unit.</i>	<i>Indicate whether this requirement is also verified during any pre-flight or recurring acceptance testing of each unit</i>	<i>Organization responsible for performing the verification</i>	<i>Indicate documents that contain the objective evidence that requirement was satisfied</i>
P-1	xxx	3.2.1.1 Capability: Support Uplinked Data (LDR)	System X shall provide a max. ground-to-station uplink of...	1. System X locks to forward link at the min and max data rate tolerances 2. System X locks to the forward link at the min and max operating frequency tolerances	Test	xxx	5	Yes	No	xxx	TPS xxxx
P-i	xxx	Other paragraphs	Other "shalls" in PTRS	Other criteria	xxx	xxx	xxx	Yes/No	Yes/No	xxx	Memo xxx
S-i or other unique designator	xxxxx (other specs, ICDs, etc.)	Other paragraphs	Other "shalls" in specs, ICDs, etc.	Other criteria	xxx	xxx	xxx	Yes/No	Yes/No	xxx	Report xxx

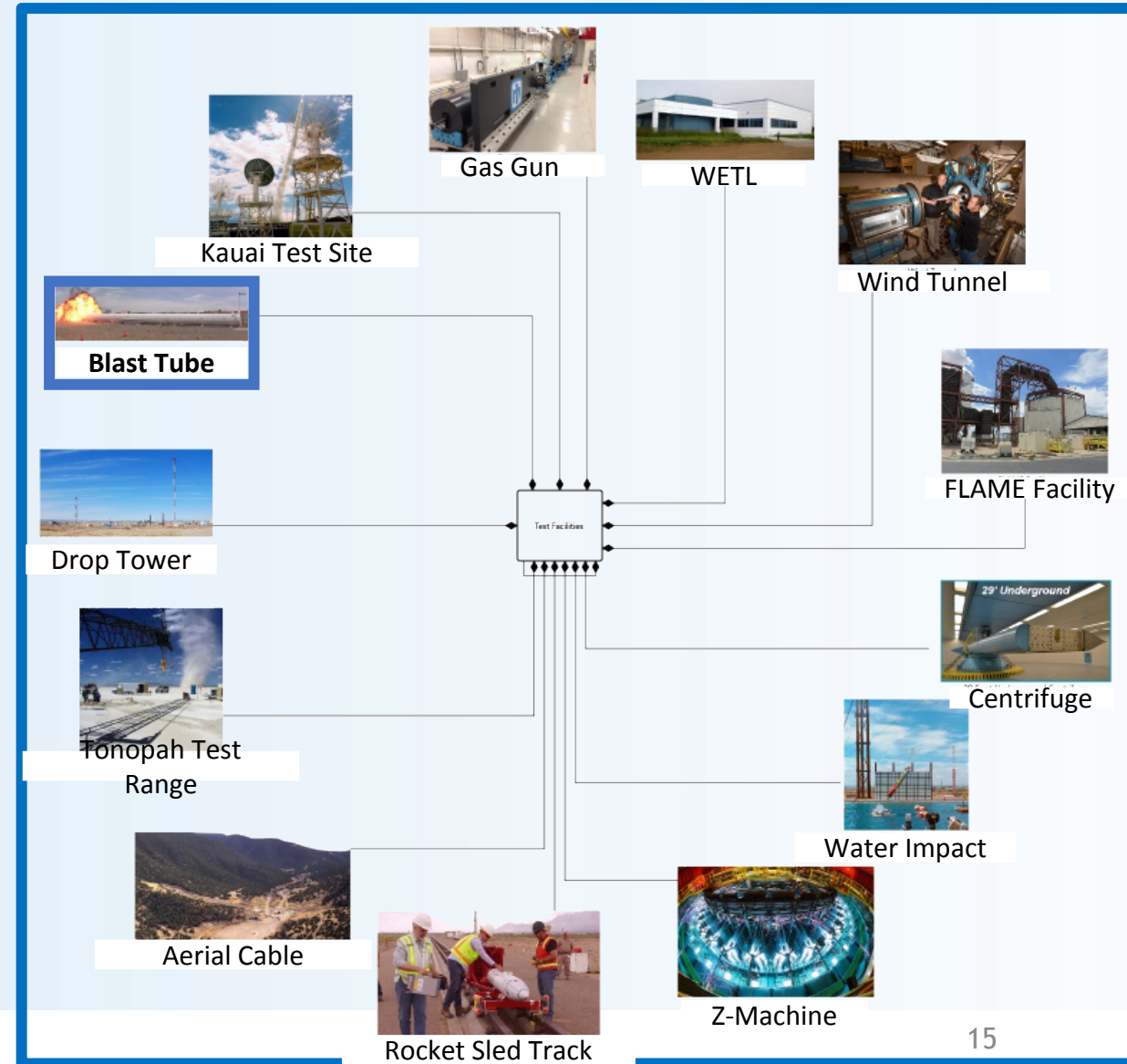
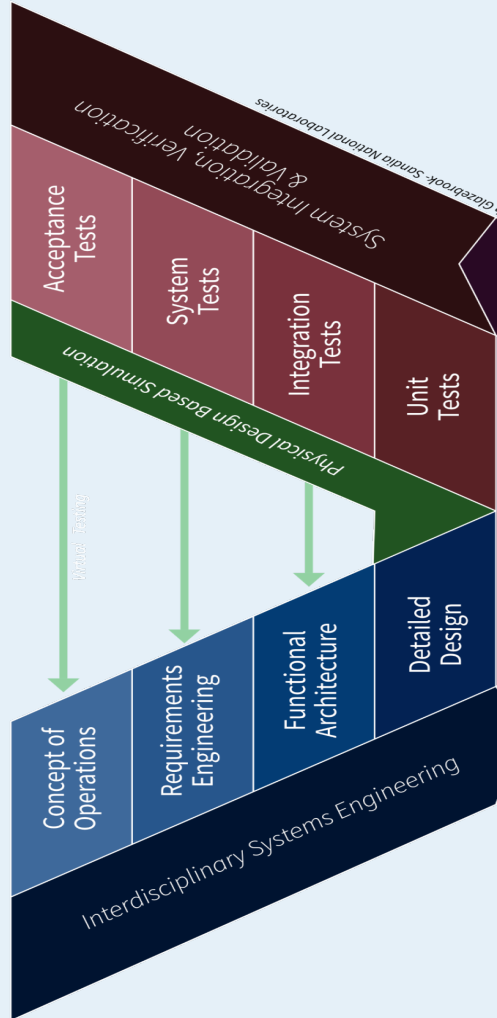
Verification & Validation



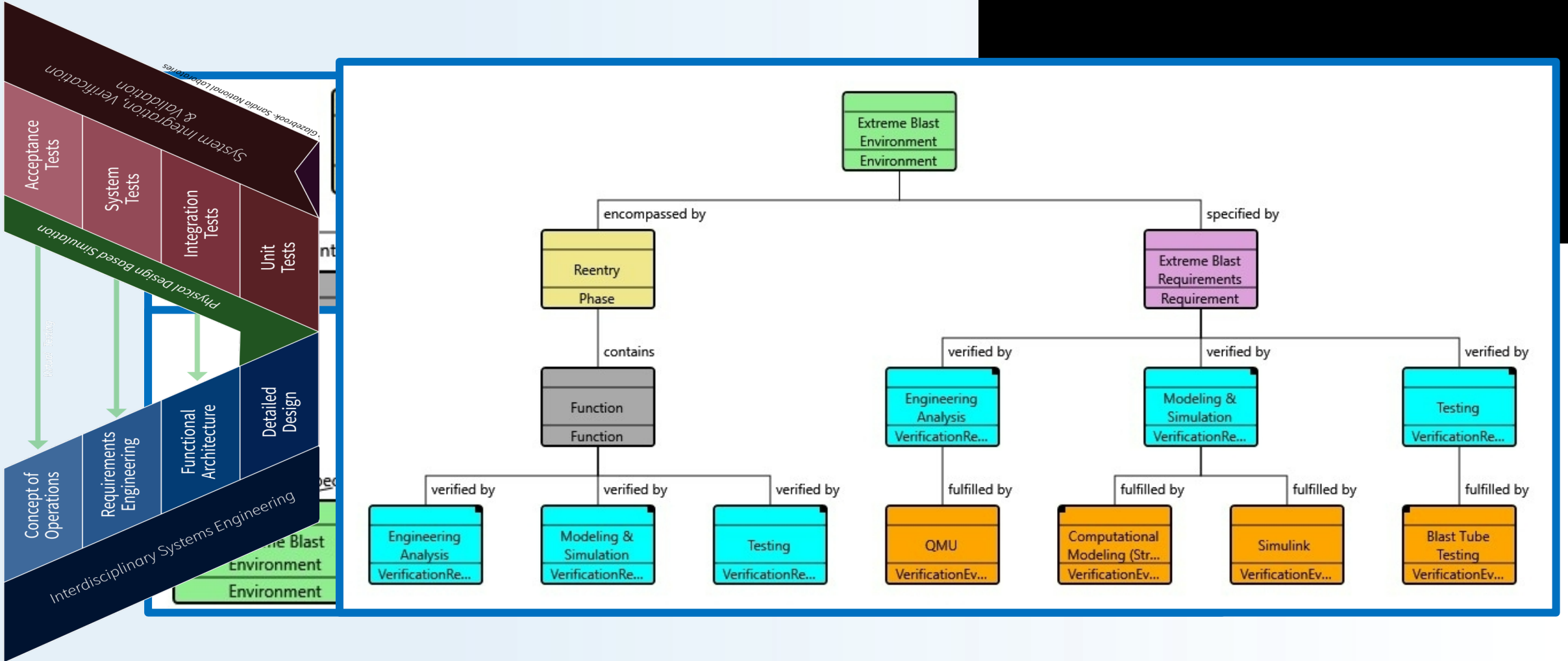
Verification & Validation



Verification & Validation



Verification & Validation



V&V modeling moves the “starting line” to shorten the lifecycle of NW



Erik Olson
R&D Electrical Engineering

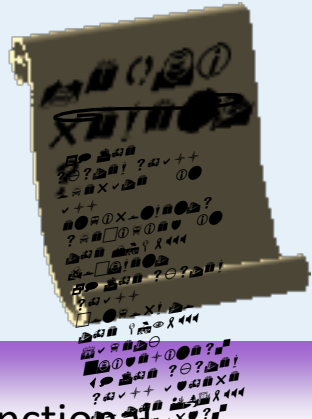
How Bridging MBSE with Reduced Order Modeling Reduces Development Time

Erik Olson has a background in both Electrical and Mechanical Engineering. He has his PhD in Electrical Engineering from University of Wisconsin. He spent the last ten years working in Sandia's satellite programs, and spent two years as an R&D engineer at Tyco thermal Controls in Menlo Park, California.

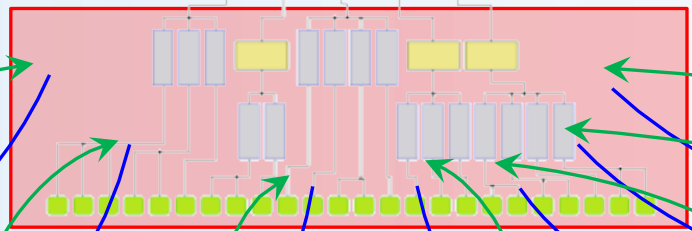
The Role of MBSE and Reduced Order Modeling



System Architecture



Functional Models



Derived Requirements

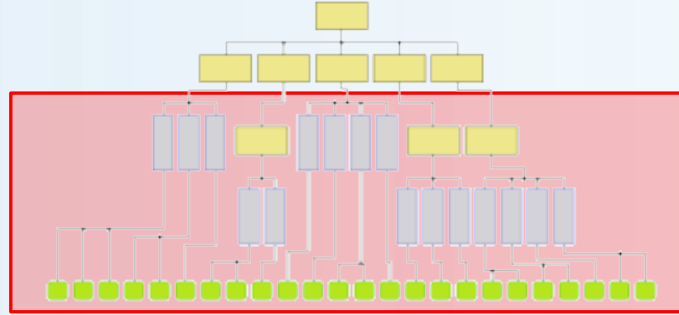


Validation

The Role of MBSE and Reduced Order Modeling



System Architecture



Derived Requirements



Validation

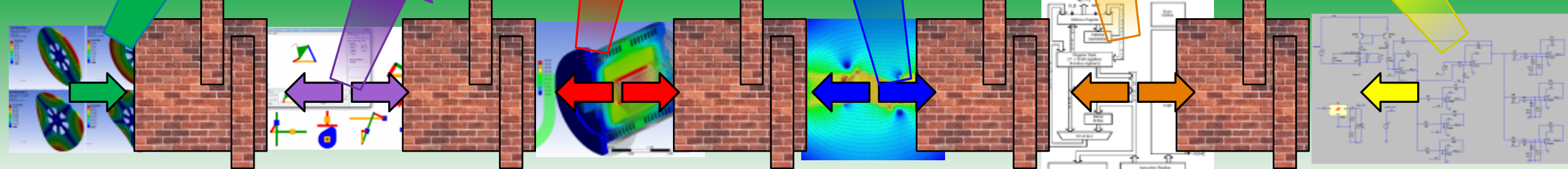
Functional Models



Reduced Order Models



Component Designs



Mechanical Modeling - Vibration



Mechanical Modeling - Kinematics



Thermal Modeling - Conduction



Electro-magnetics RAMSES

Circuit Modeling - Digital

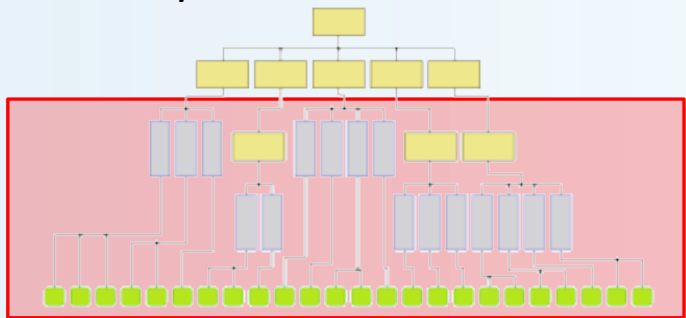
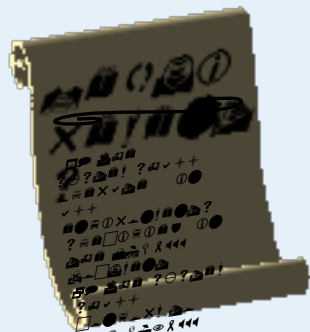


Circuit Modeling - Analog / Power

The Role of MBSE and Reduced Order Modeling



System Architecture



Derived Requirements



Validation

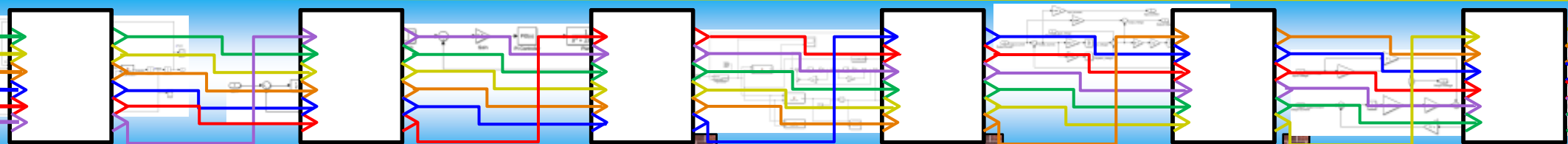


Verification

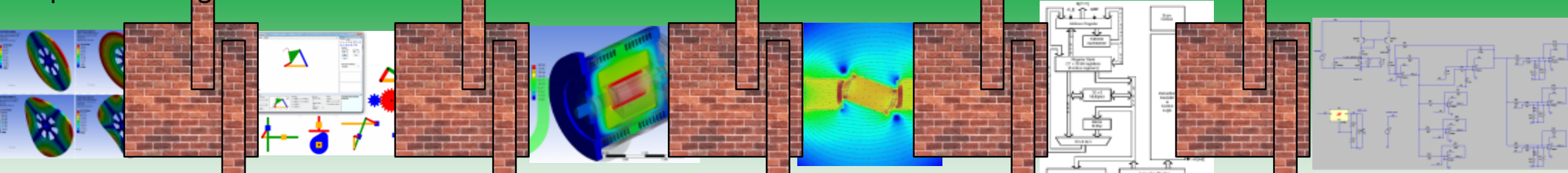
Function Models



Reduced Order Models



Component Designs



Mechanical Modeling - Vibration



Mechanical Modeling - Kinematics



Thermal Modeling - Conduction



Electro-magnetics RAMSES

Circuit Modeling - Digital



Circuit Modeling - Analog / Power



Equivalent Simulink Models



Passive Coupled Networks

LTSpice

SIMULINK

Mechanical Vibration / Electrical

Mechanical Vibe

Stiffness Tensors

$$\begin{bmatrix} k_{xx23} & k_{xy23} & k_{xz23} \\ k_{yx23} & k_{yy23} & k_{yz23} \\ k_{zx23} & k_{zy23} & k_{zz23} \end{bmatrix}$$

Electrical Contact Chatter

Thermal – Mechanical Electrical Contact Model

Thermal Model

Spring Force

Rotation Matrix

Electrical Signal

Thermal Input

Acceleration Input

Acceleration

Switching Power Converter Models

LTSpice

SIMULINK

Thermal Conduction Models

Thermal Radiation Models

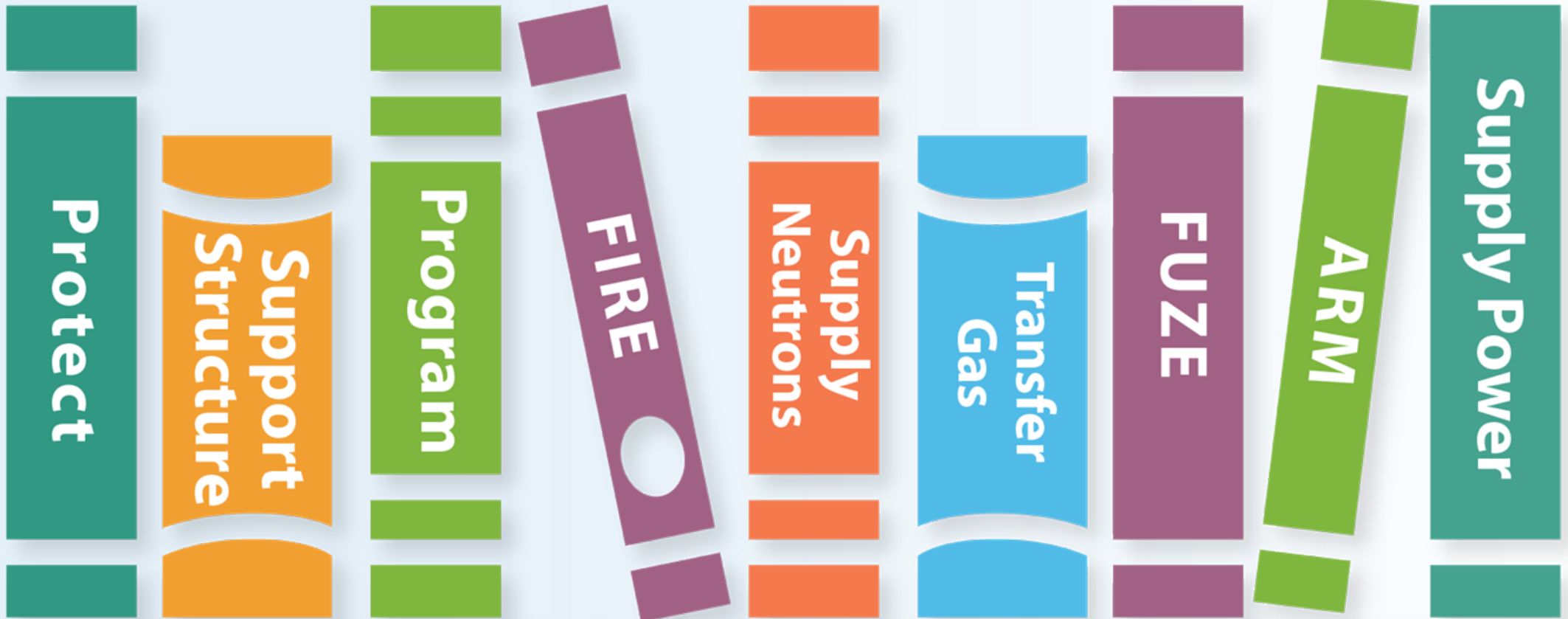
Reduced Order Modeling allows for virtual cycle verification with combined environments



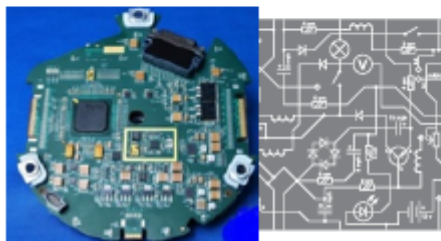
Ryan Coleman
R&D Computer Scientist

How Data Strategy For The Digital Twin Reduces NW Development Time

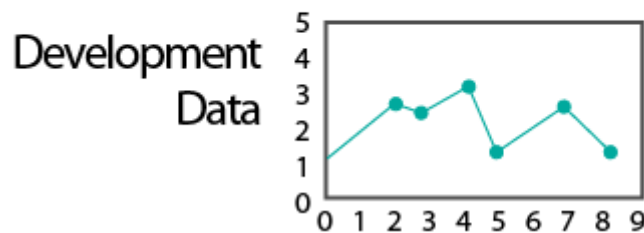
Ryan has experience in abnormal environments and detonator modeling, and many of the advanced simulation and computing analyses for nuclear weapons qualification. Immediately prior to joining Sandia, Ryan was an academic postdoc in Pharmaceutical Chemistry at University of California San Francisco, where he built and used software systems for drug discovery. Ryan has degrees in Computer Science, Philosophy, and his PhD in Computational Biology.



Library of Functions; Books of Components

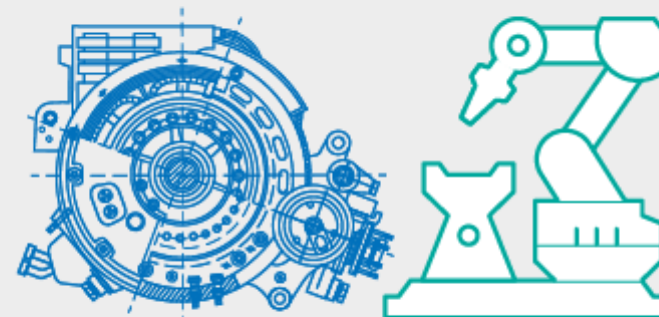
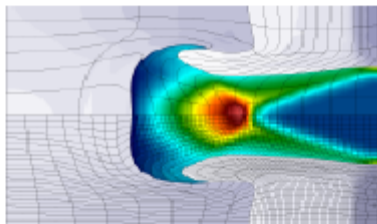


Mk2017 Design



Environment & Margins

Simulation Models



Manufacturing Plan

Unit Test Plan



Integration Test Plan



A Digital Twin for Components allows them to be reused to shorten development time

Library of Functions; Books of Components



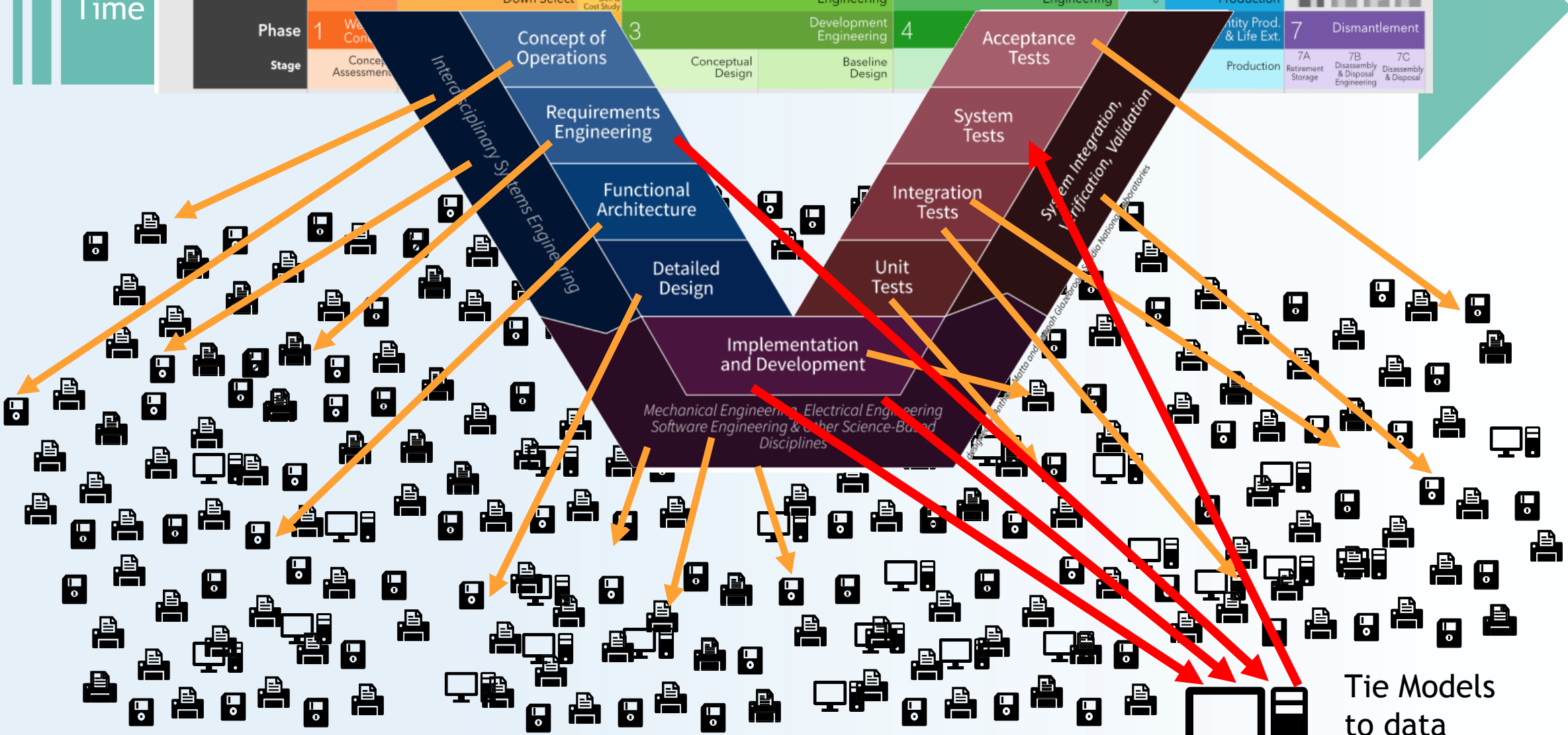
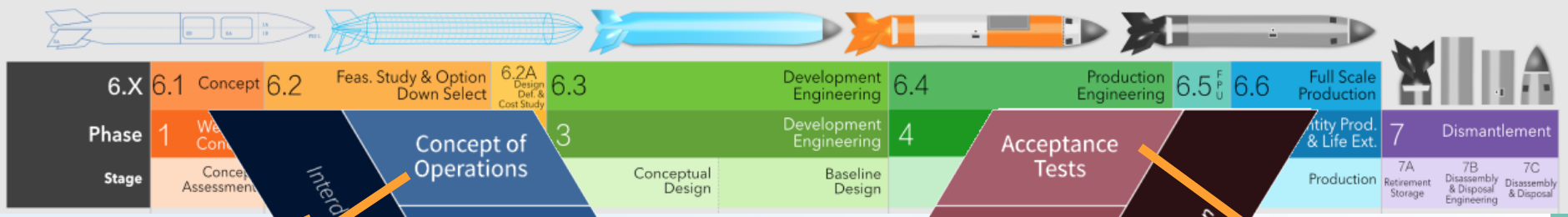
The image displays a library of functional components. On the left, a shelf holds nine books with spines labeled: **Protect**, **Support Structure**, **Program**, **FIRE**, **Supply Neutrons**, **Transfer Gas**, **FUZE**, **ARM**, and **Supply Power**. In the foreground, several open book cards are shown, each representing a component's documentation. The most prominent card features:

- Mk2017 Design**: A photograph of a cylindrical metal component.
- Development Data**: A line graph with the following data points:

X-axis	Y-axis
1	2.5
2	3.0
3	2.5
4	3.5
5	1.5
6	2.5
7	3.0
8	1.5
9	2.0
- Environment & Margins**: Represented by icons of a snowflake and a sun.
- Simulation Models**: A small image of a 3D simulation model.
- Manufacturing Plan**: A photograph of a component being machined.
- Unit Test Plan**: An icon of a hammer striking a yellow block.
- Integration Test Plan**: A hierarchical tree diagram.

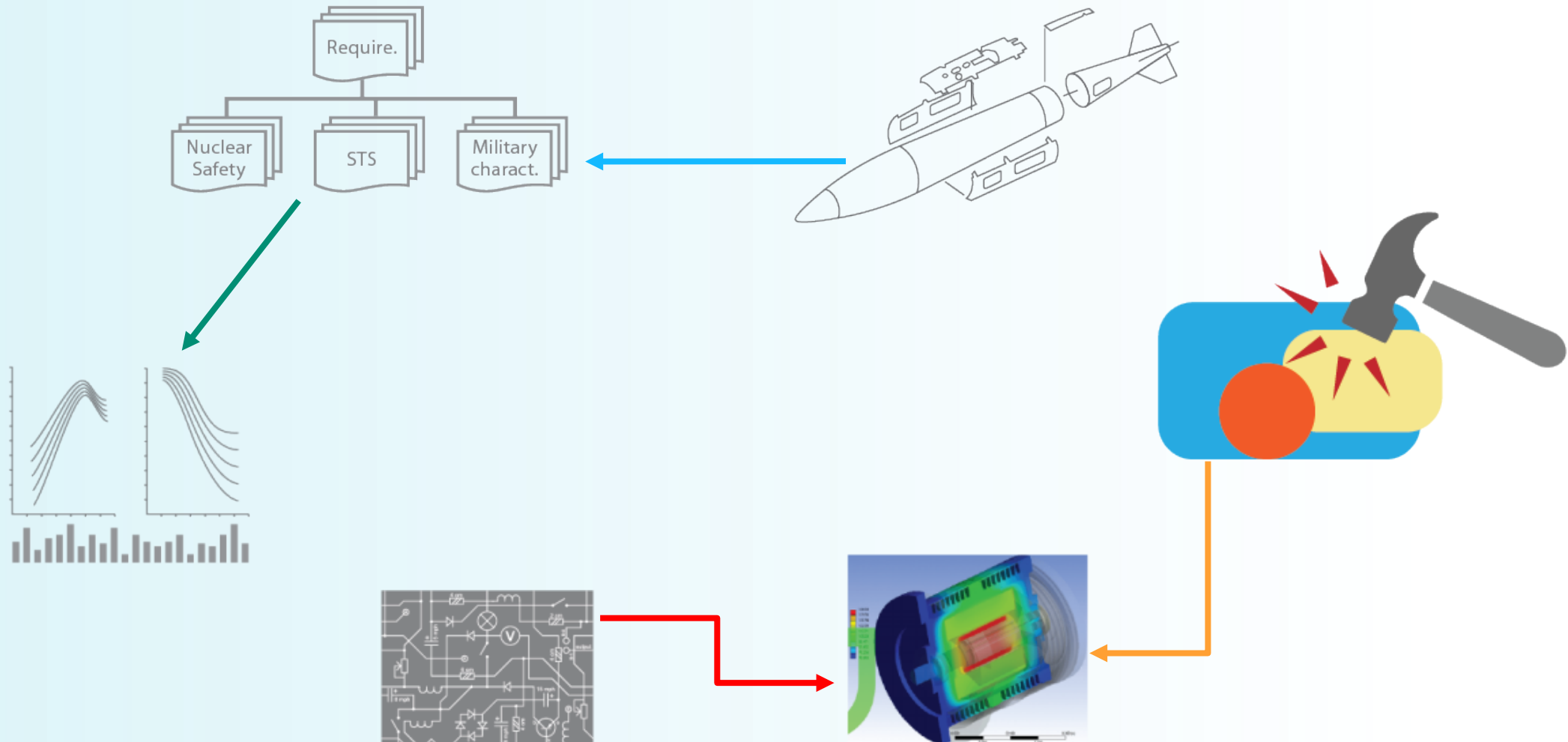
Infrastructure to reuse components will reduce development time

Time



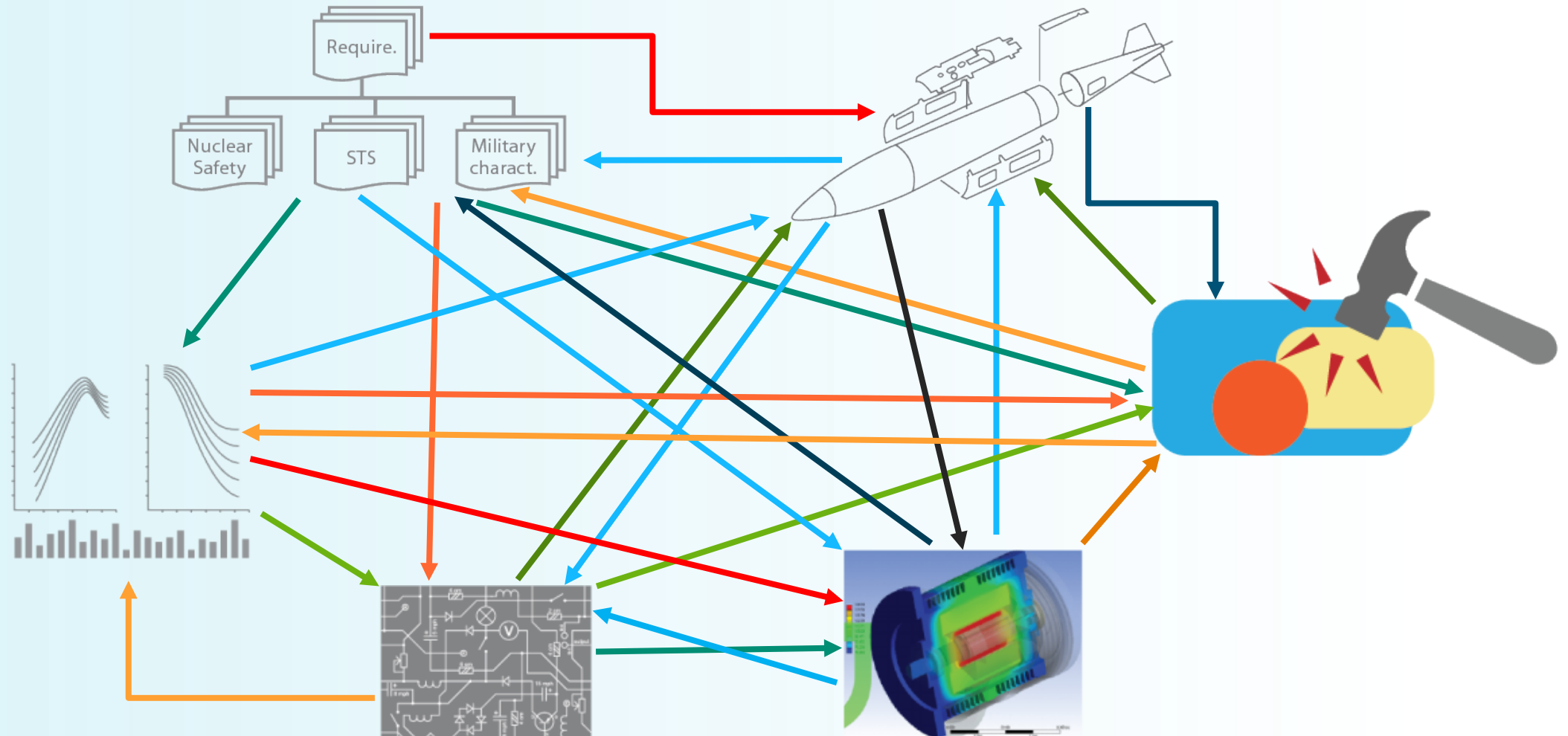
Digital Twin of Each Weapon System will reduce development time

Architecting the Connections Between Diverse and Disparate Sources



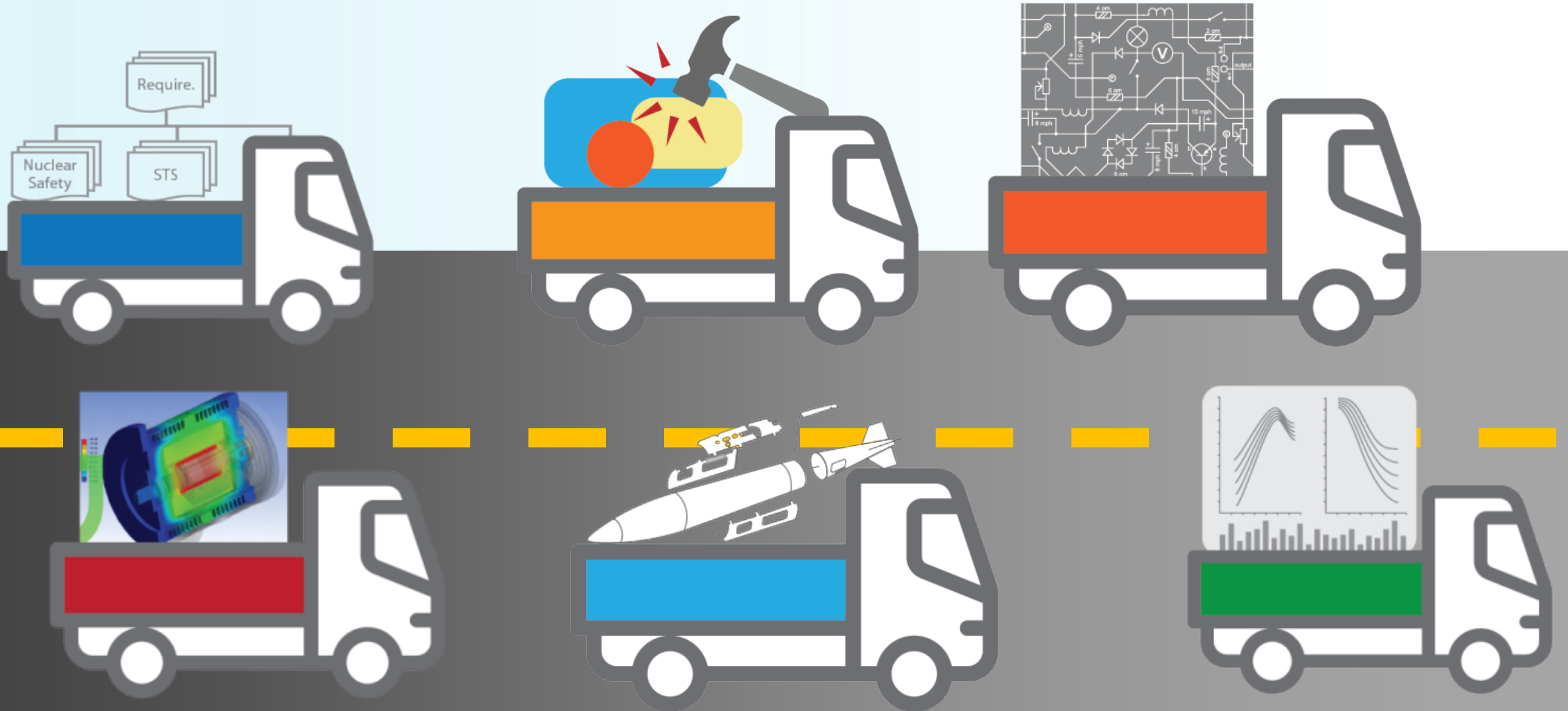
Connecting Data Sources will be Necessary For Success

Architecting the Connections Between Diverse and Disparate Sources



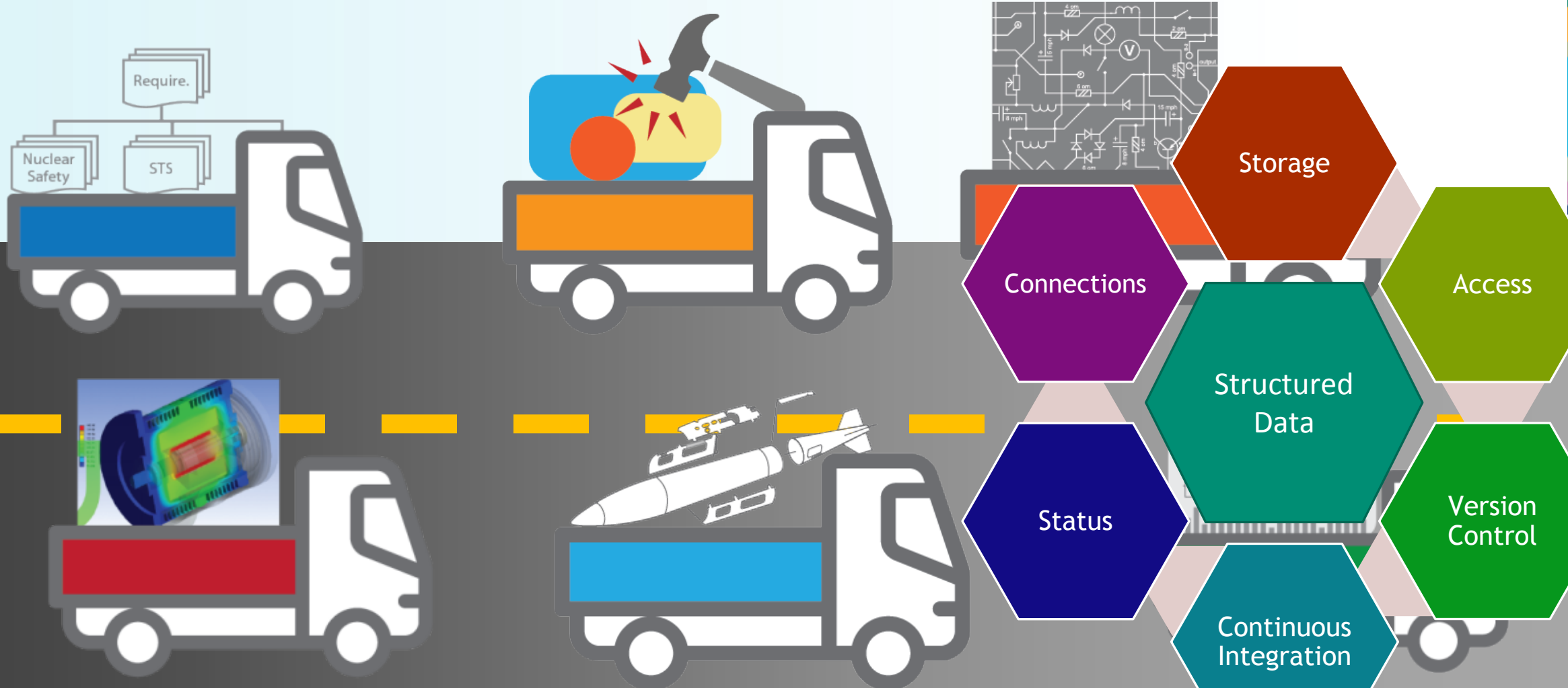
But A Quadratic Number of Data Translations Will Be Unmanageable

Merging Complex Data Sources

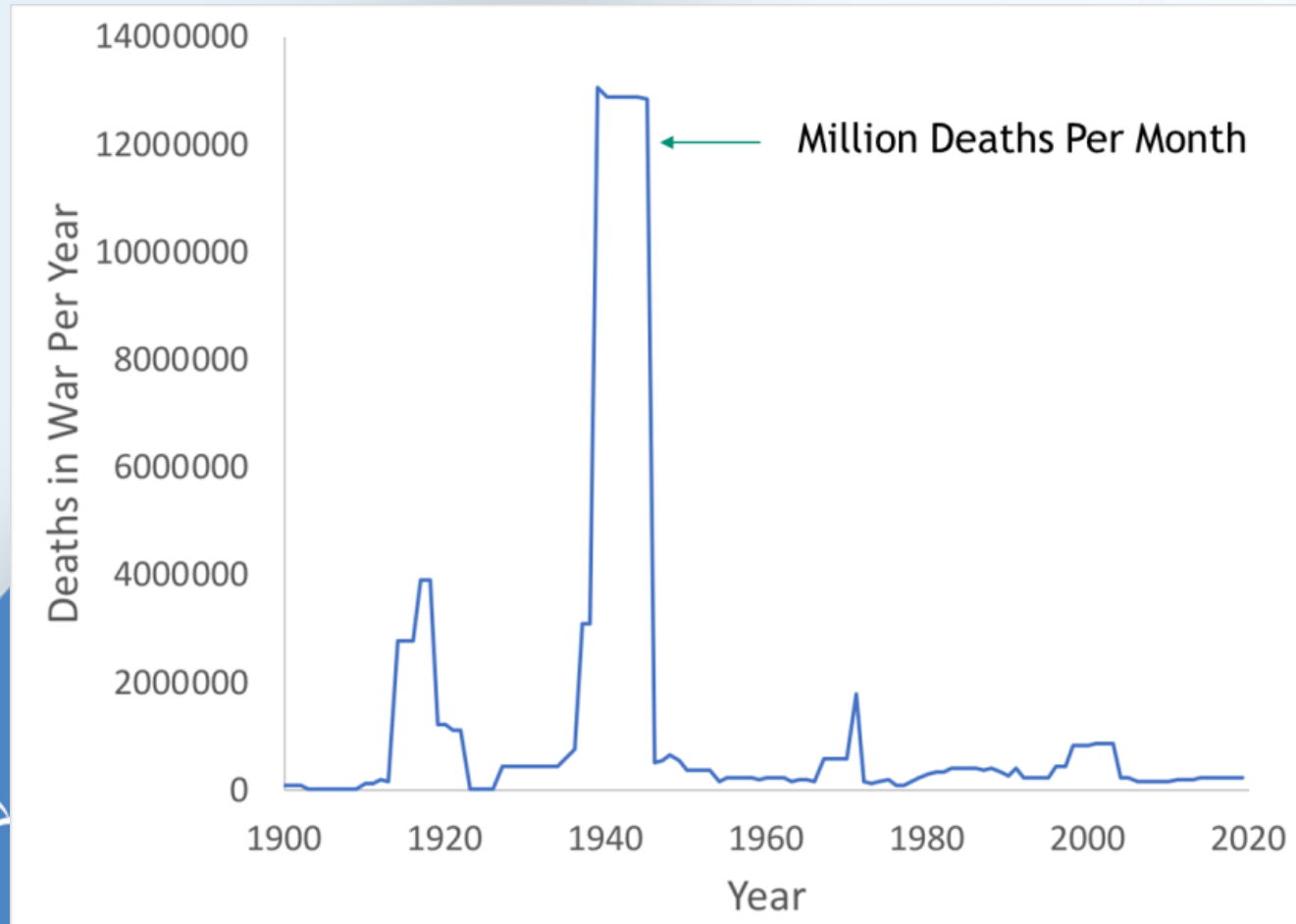


Build a Single Data Layer (Road) to Move Data, along with one Adapter (Truck) per Data Source

Merging Complex Data Sources



Allows Data Storage, Warehousing, Version Control, Access Control to be built in a Single Place



Nuclear Deterrence Works

Respond to Threats, Sustained
Deterrence



Tip-to-Tail System Modeling Using Reduced Order Modeling



PRESENTED BY

Erik Olson, 2496

December 10, 2018

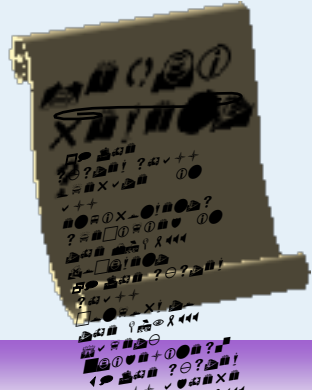


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of Energy's National Nuclear Security
Administration under contract DE-
NA0003525.

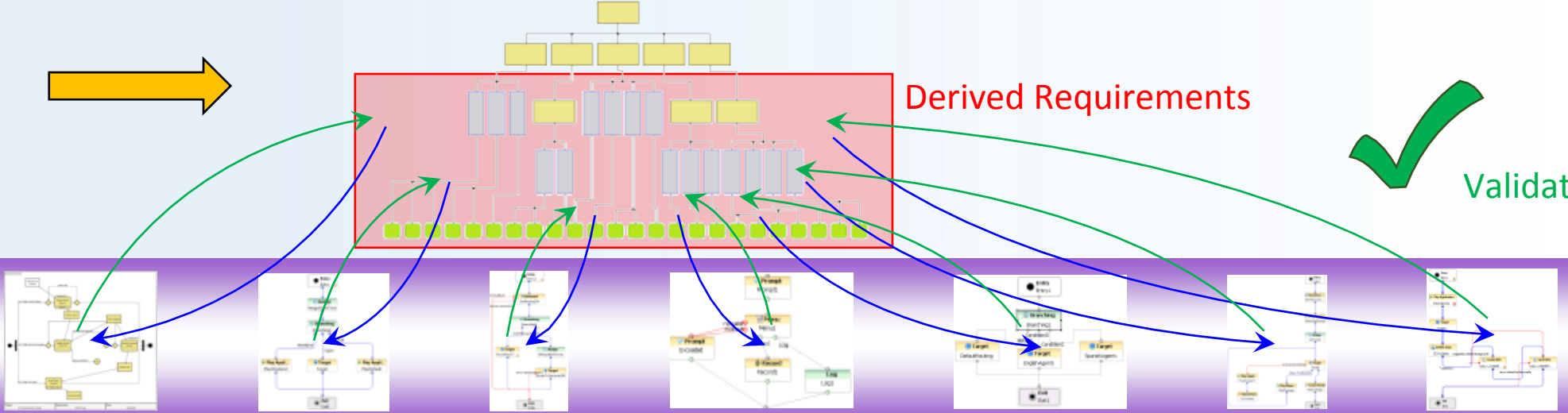
The Role of MBSE and Reduced Order Modeling



System Architecture



Function Models



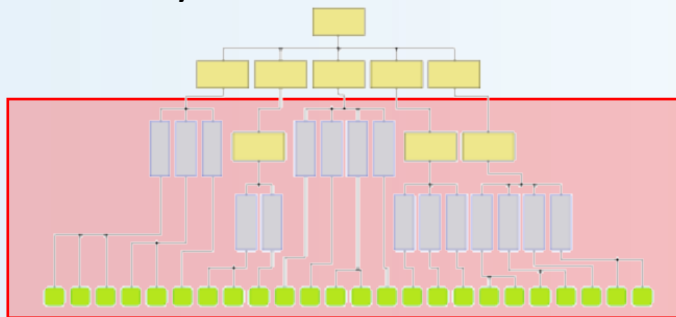
Derived Requirements



The Role of MBSE and Reduced Order Modeling



System Architecture



Derived Requirements



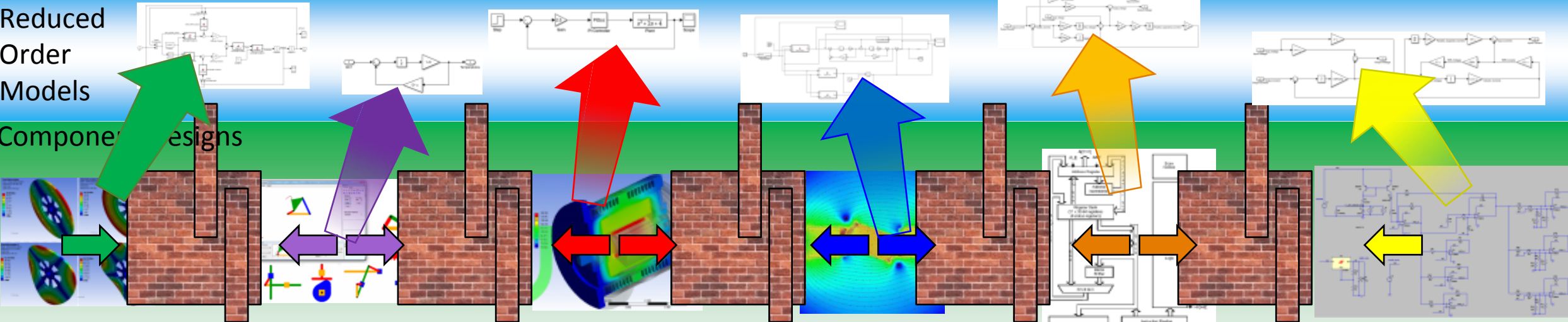
Validation

Function Models



Reduced Order Models

Component Designs



Mechanical Modeling - Vibration

Mechanical Modeling - Kinematics

Thermal Modeling - Conduction

Electro-magnetics

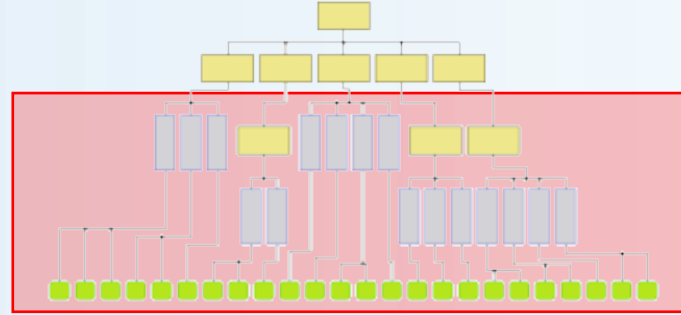
Circuit Modeling - Digital

Circuit Modeling - Analog / Power

The Role of MBSE and Reduced Order Modeling



System Architecture

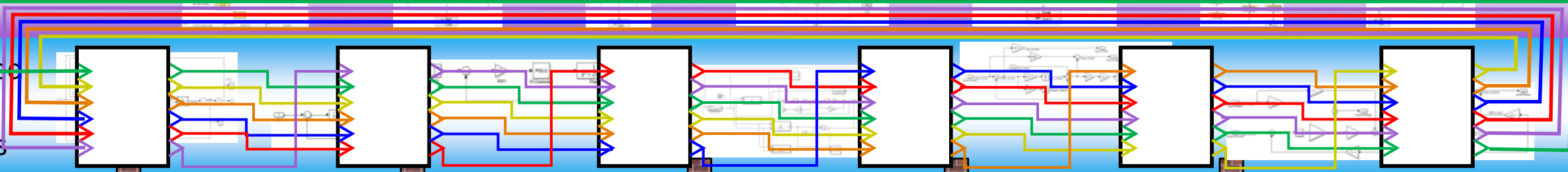


Derived Requirements

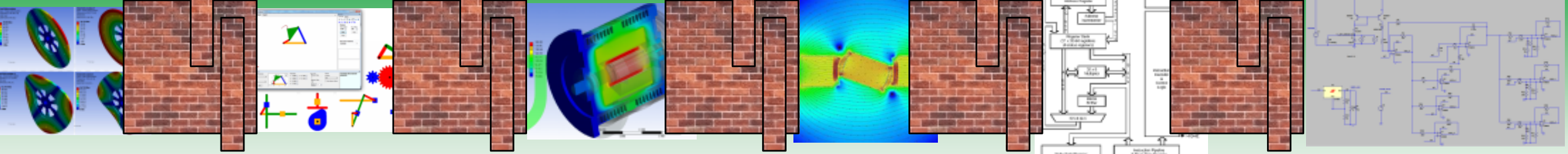
Function Models



Reduced Order Models



Component Designs



Mechanical Modeling - Vibration

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Circuit Modeling - Digital

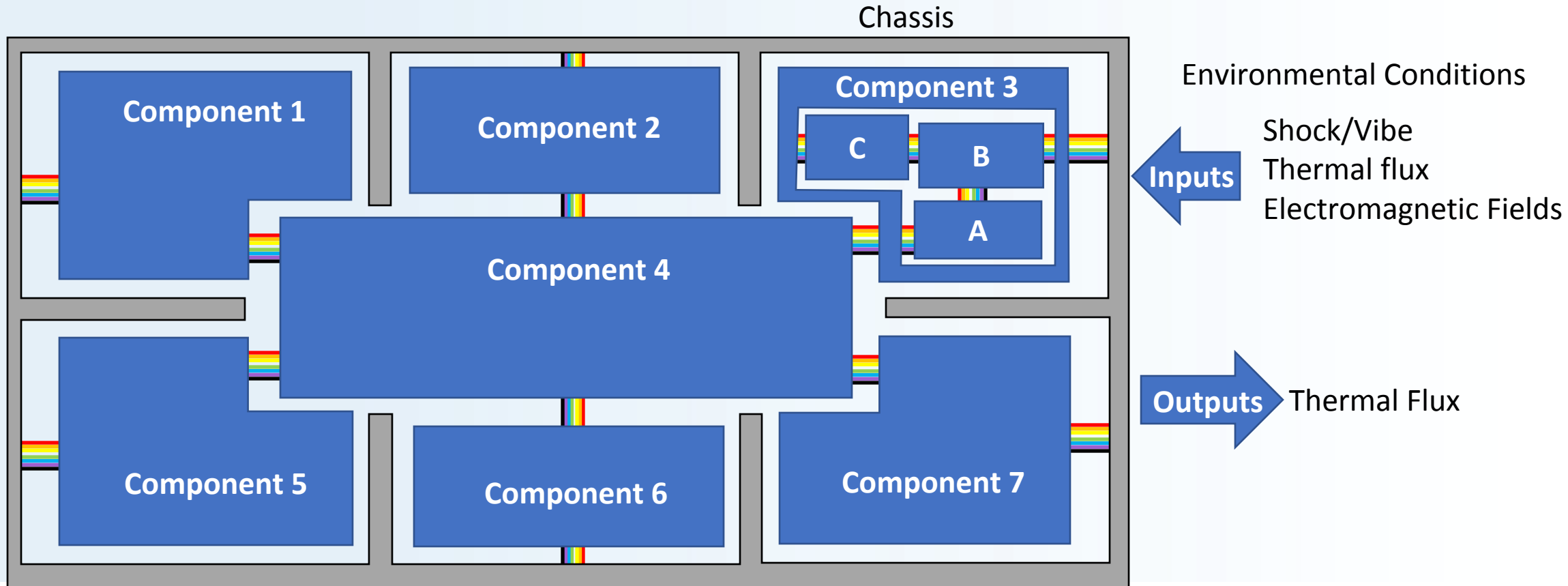
Circuit Modeling - Analog / Power

Tip to Tail System Level Model

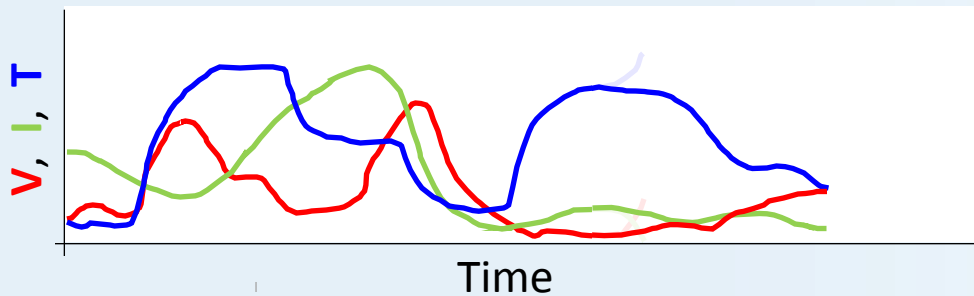


- Interfaces:
- Thermal
 - Mechanical - Shock / Vibe
 - Mechanical - Kinematic
 - Electrical – Digital
 - Electrical – Power
 - Electrical – Analog
 - Fluids

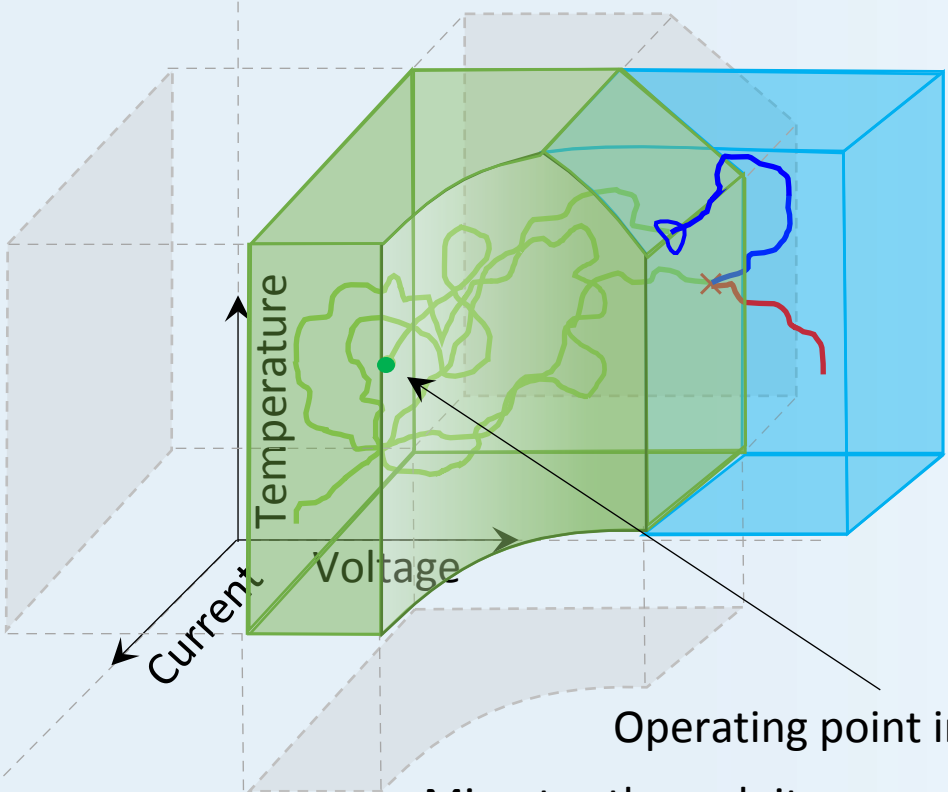
Modeling of Components and Interfaces



Physics Variable Trajectories

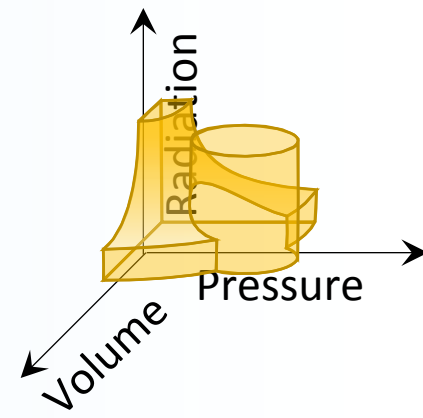
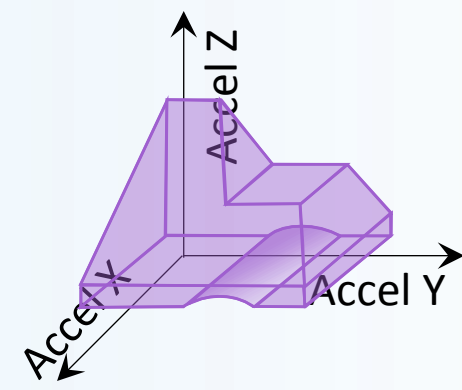
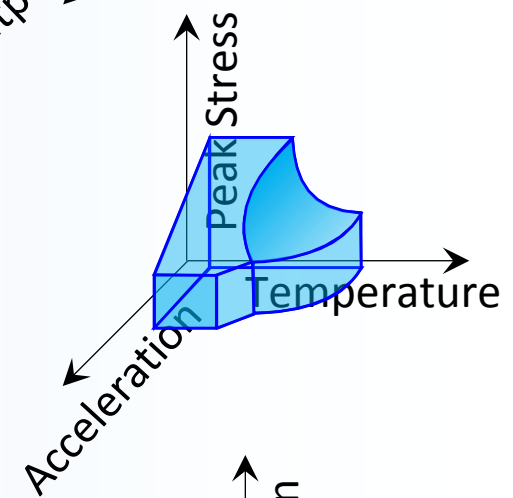
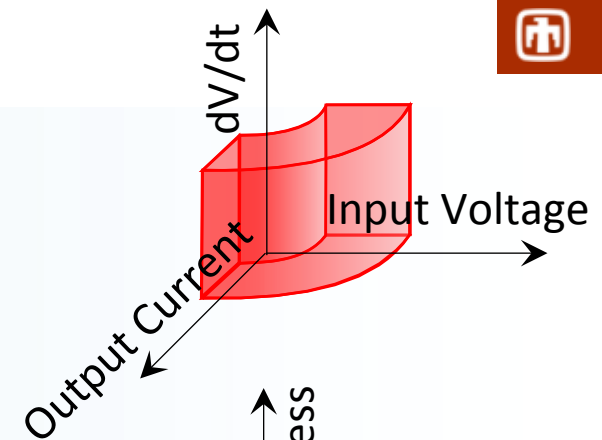


Region of high accuracy, high confidence Behavioral
Possibly Linear
"Ideal" performance
Verified against physics design model (Finite Element, PSPICE)

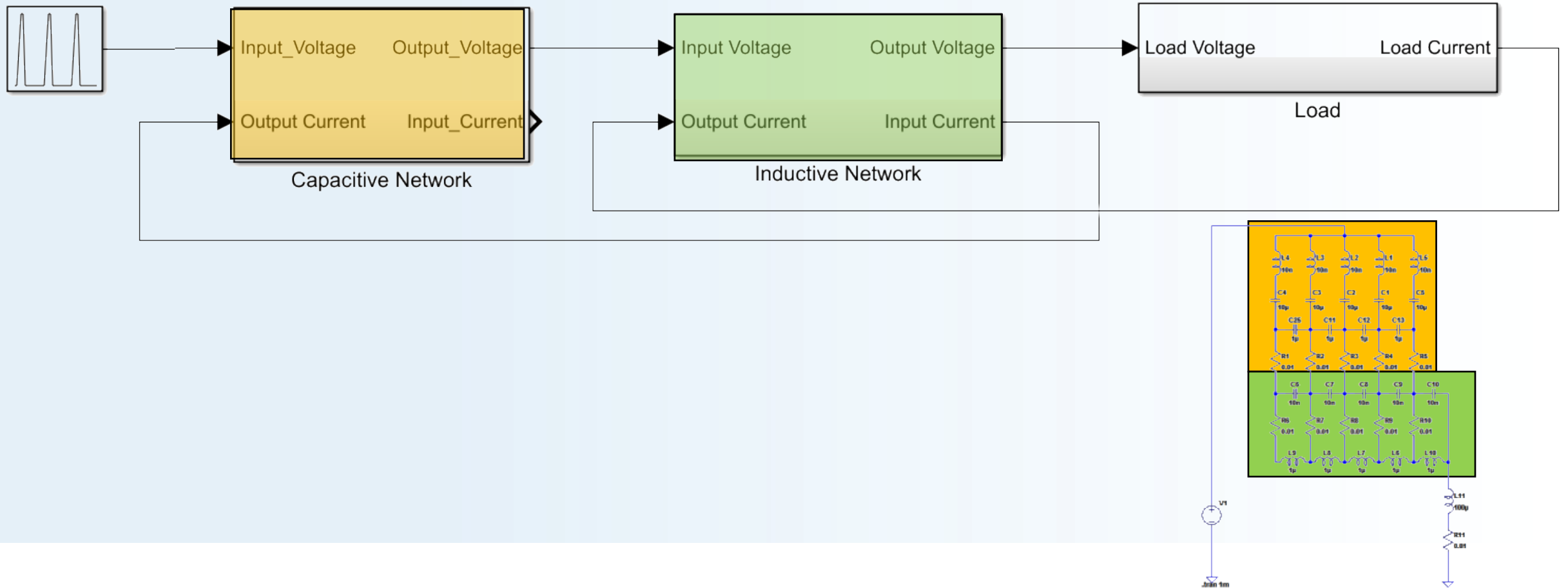


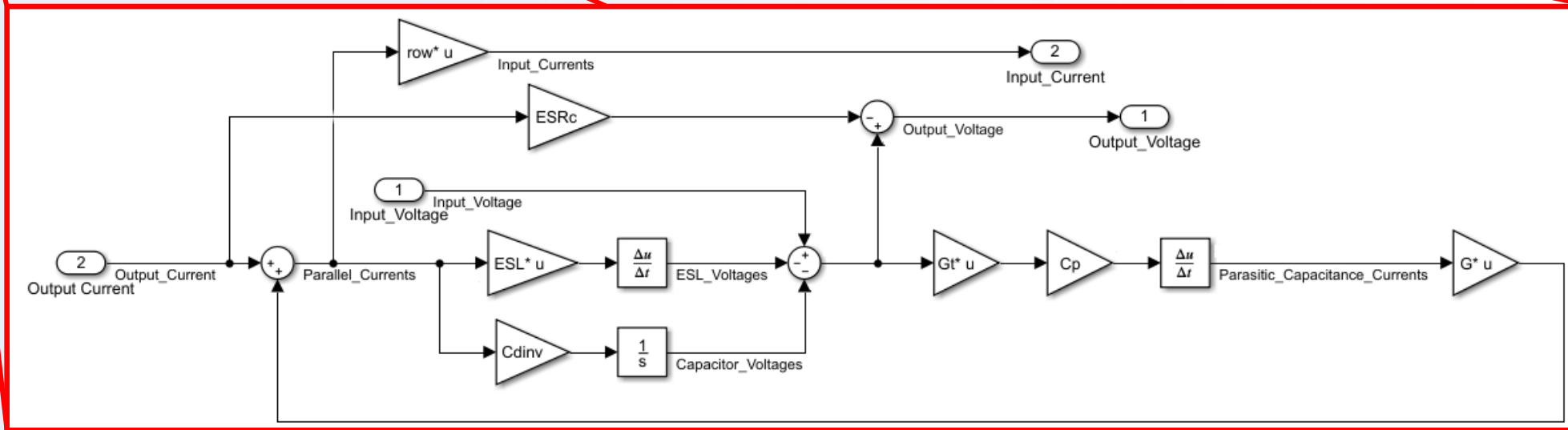
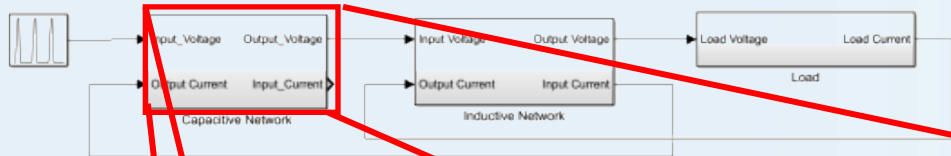
Operating point in simulation space
Migrates through its space during a simulation

If external conditions force the modeled component beyond its limits of accuracy, A piece-wise extended model can be made to extend the accuracy of the component's model, if necessary.

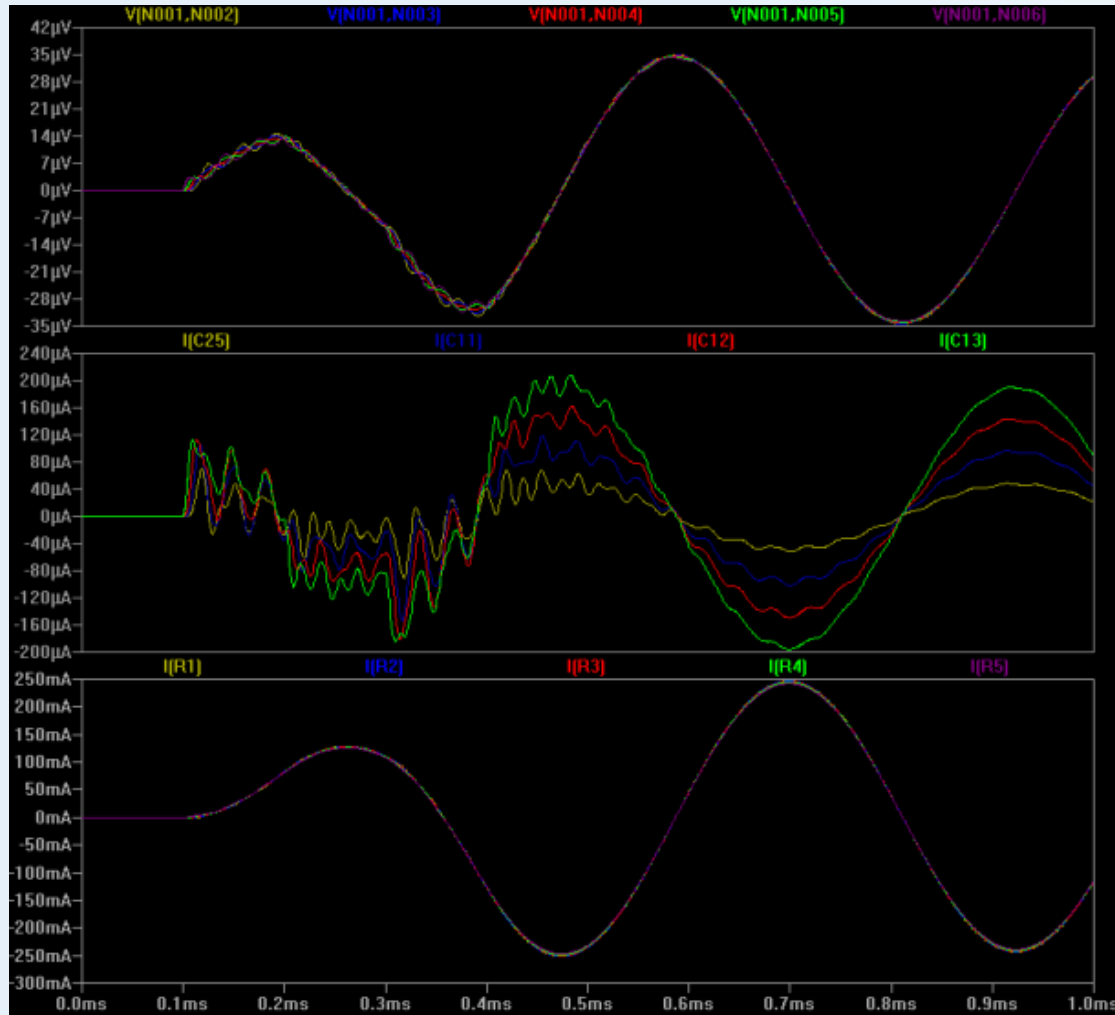


Connecting Passive Electrical Components

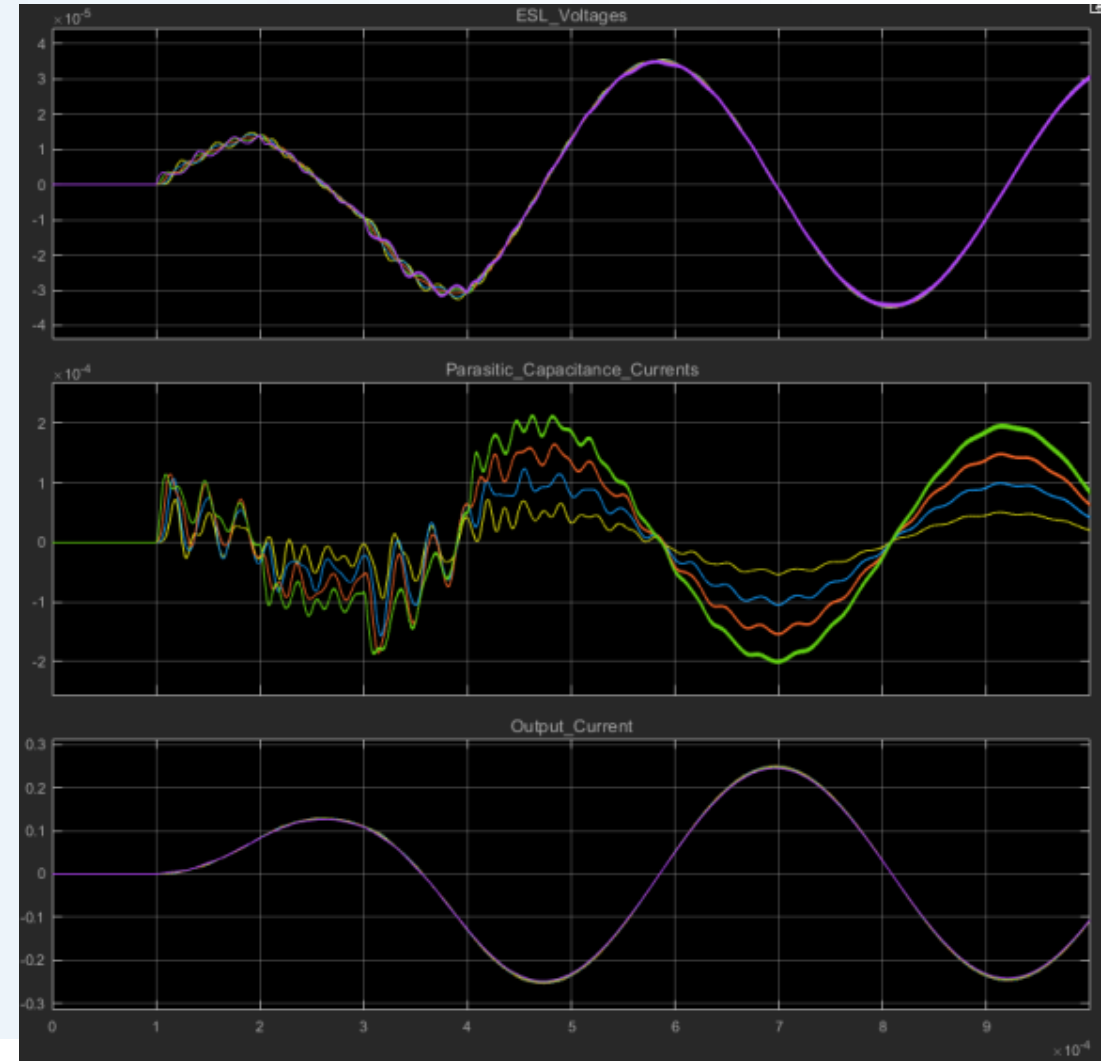


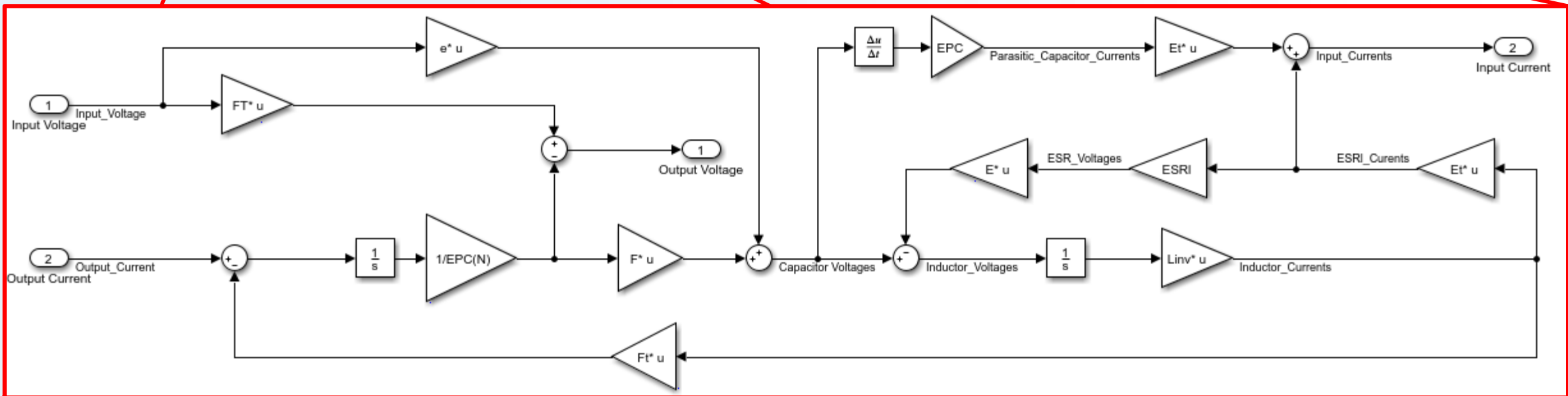
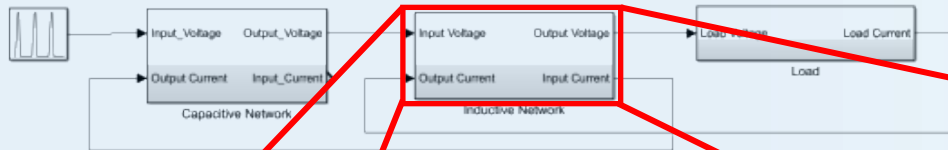


LTSpice

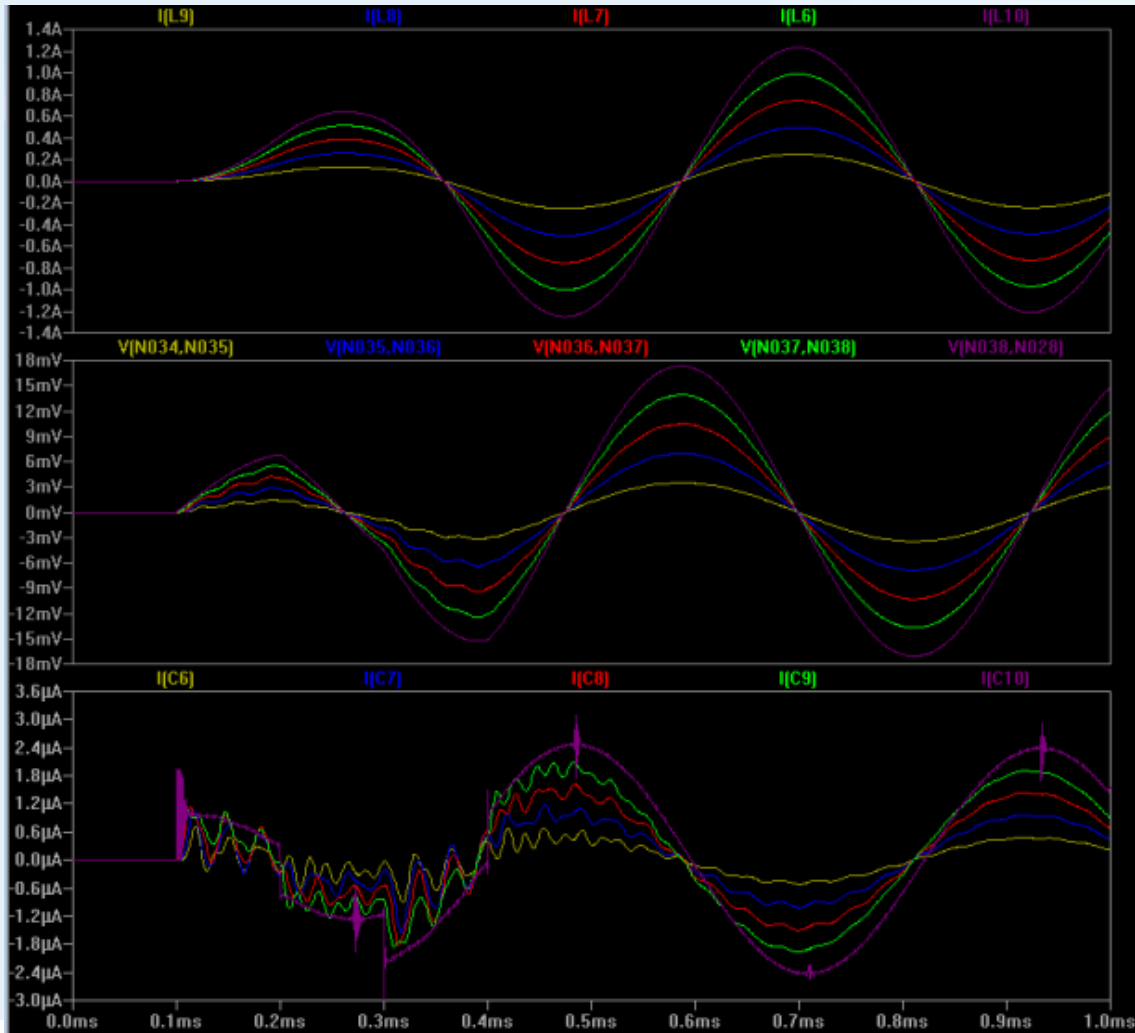


SIMULINK

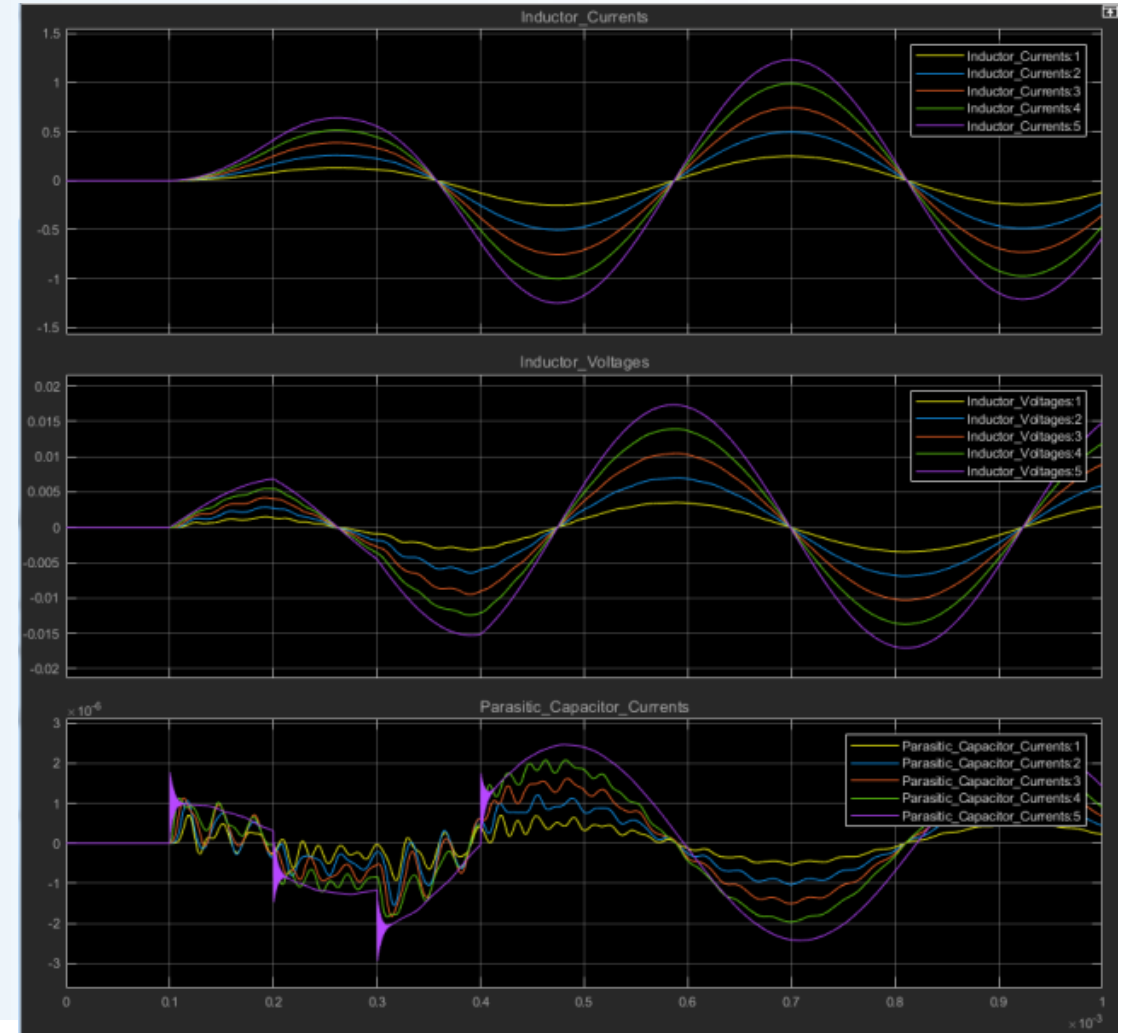


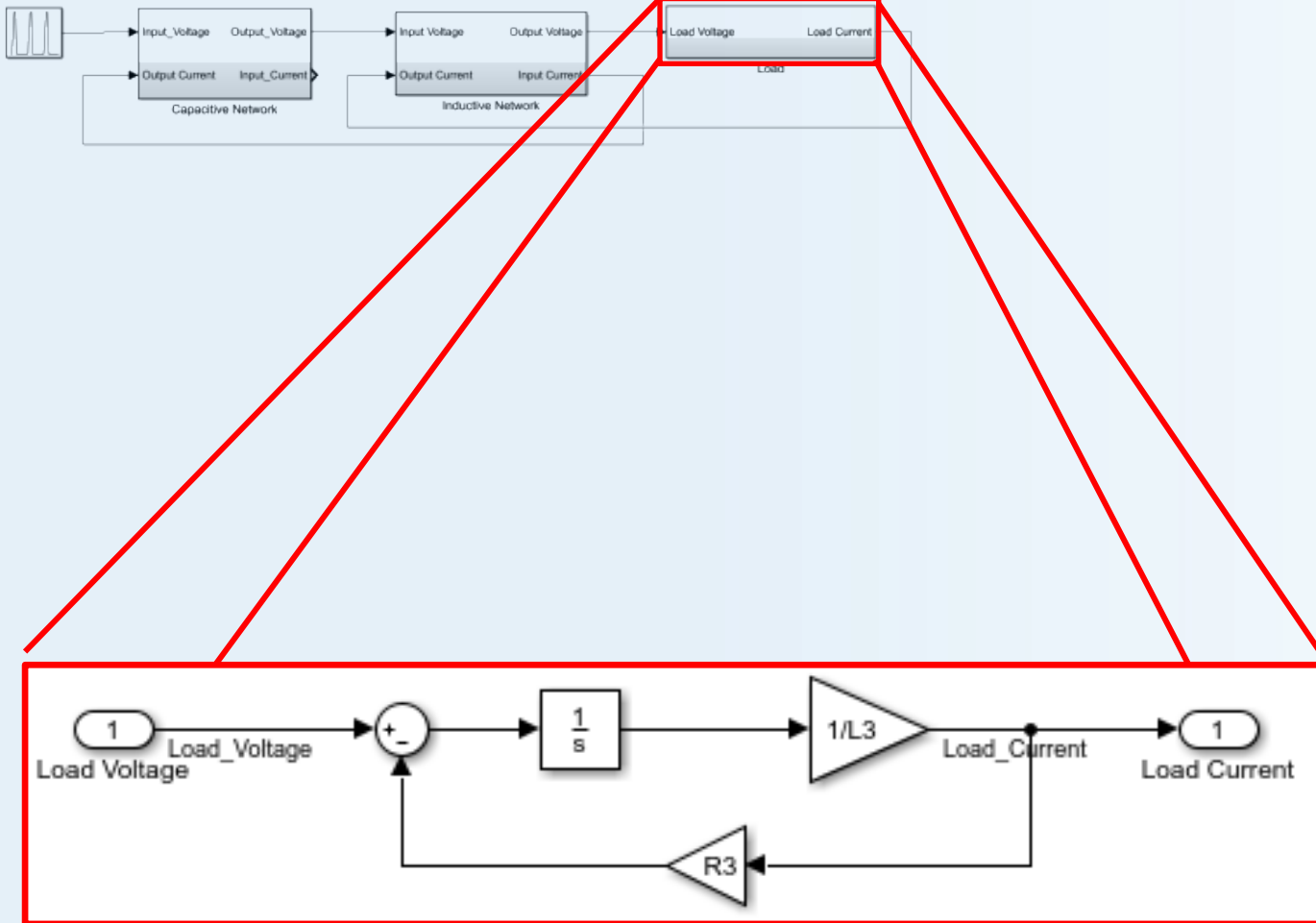


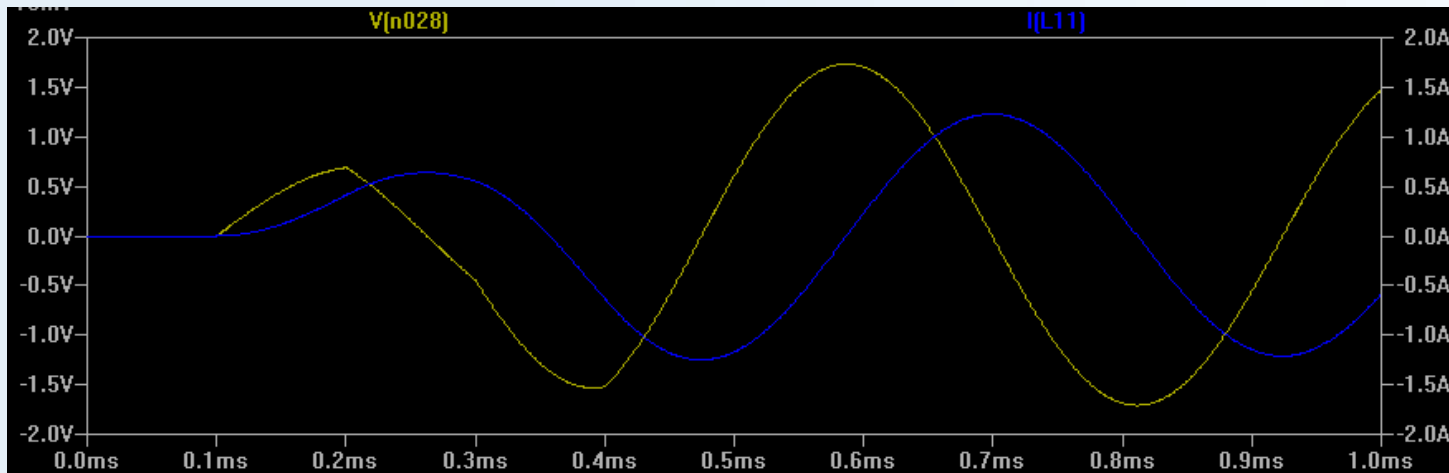
LTSpice



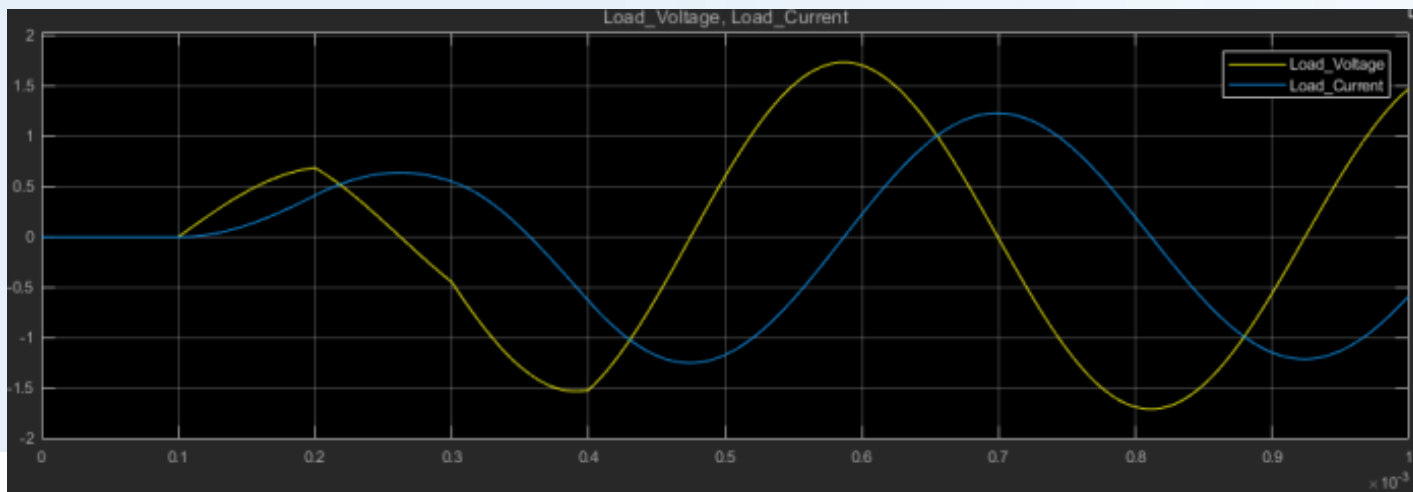
SIMULINK





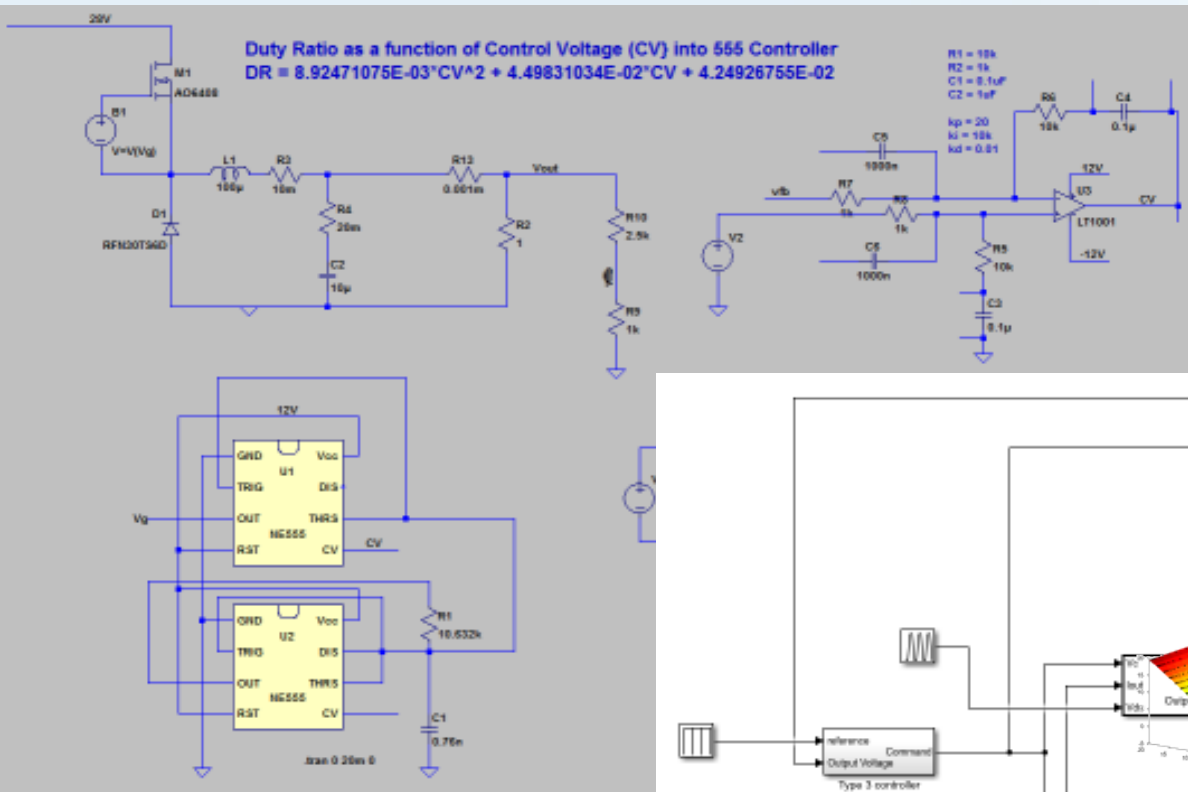


LTSpice



SIMULINK

LTspice

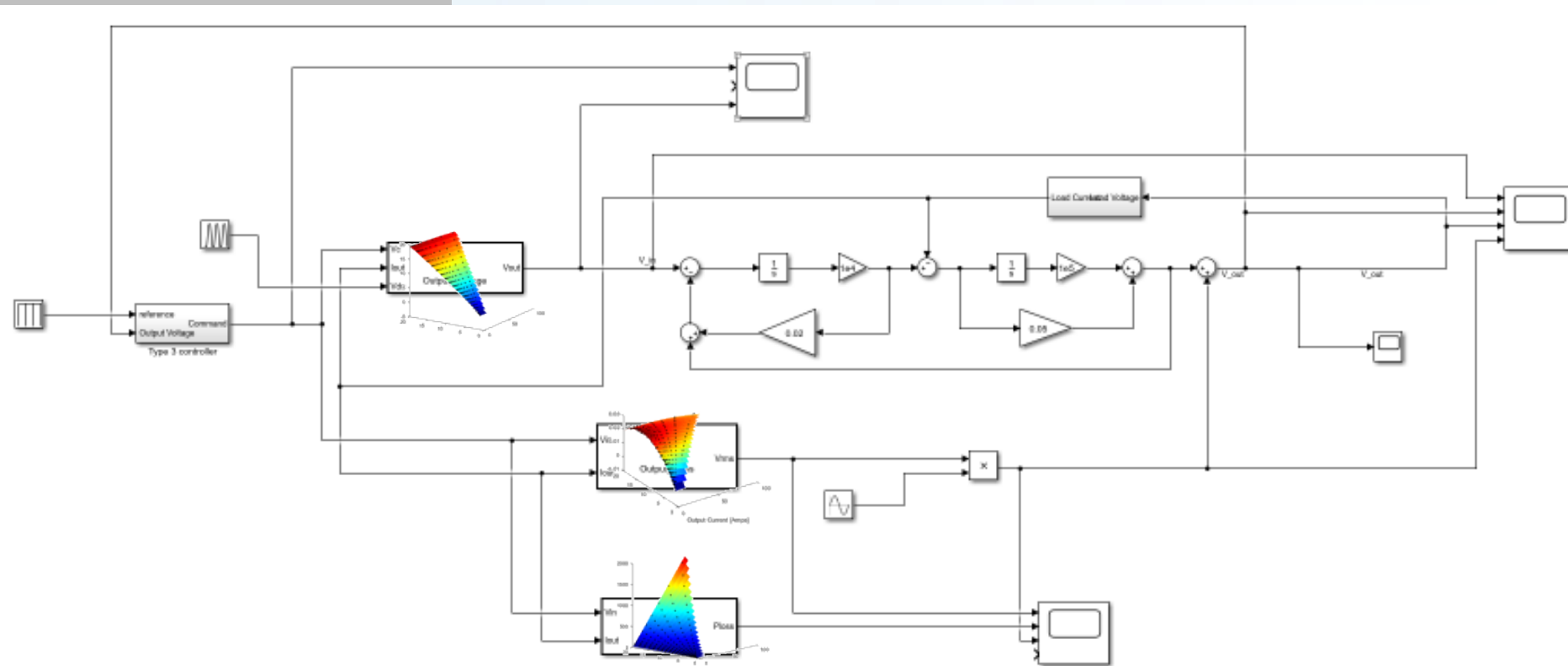


Output Voltage = (Duty Ratio, Output Current)

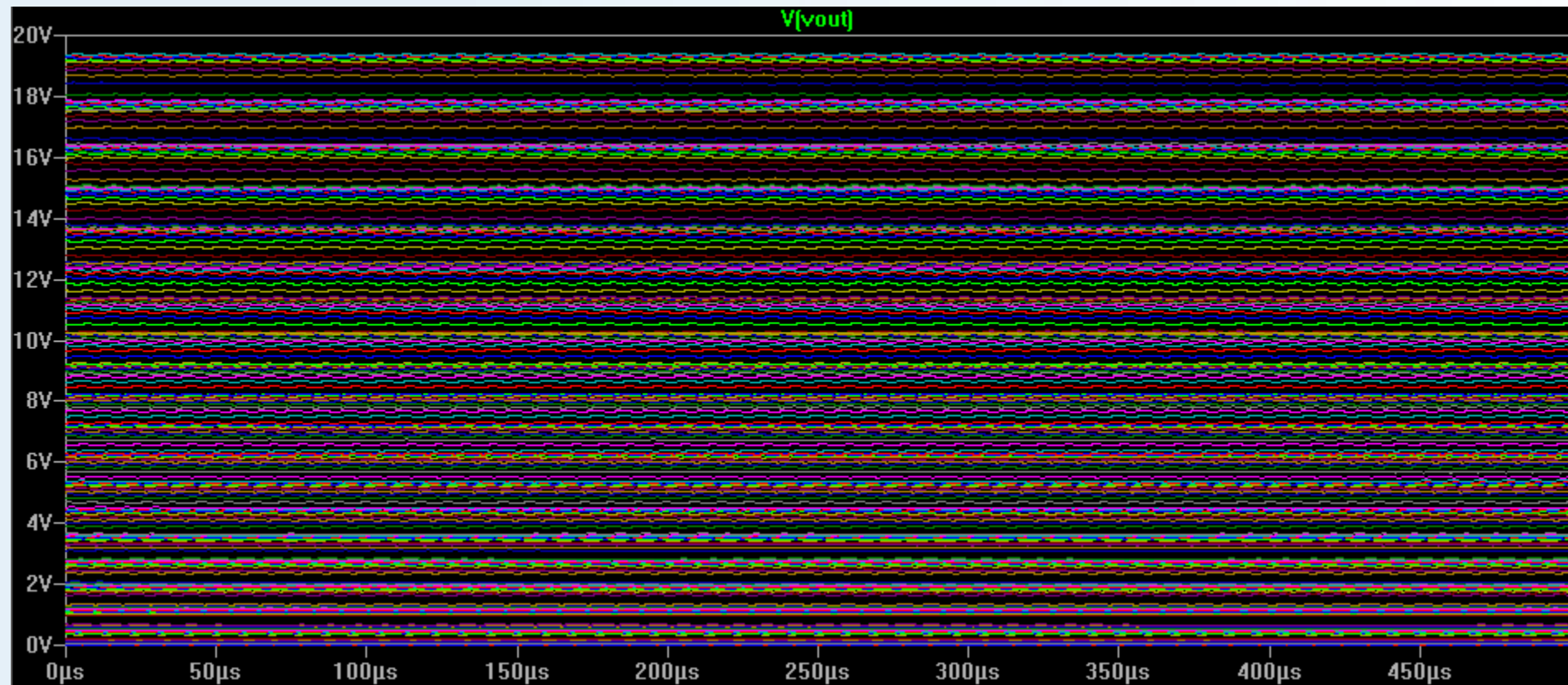
Output Voltage Ripple = (Duty Ratio, Output Voltage)

Power Loss = (Duty Ratio, Output Voltage)

SIMULINK



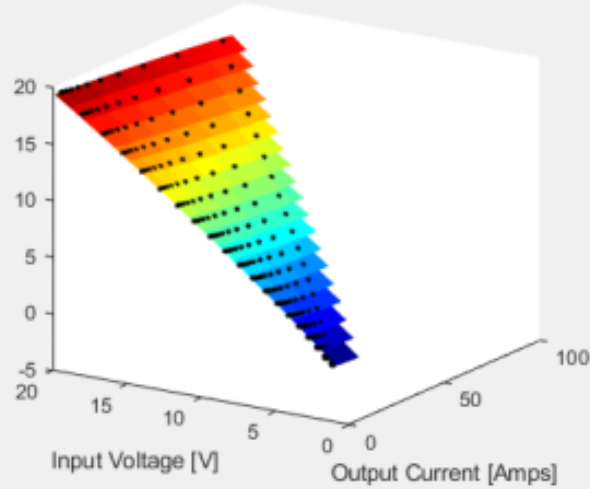
Sweeping Variables to extract Behavioral Parameters



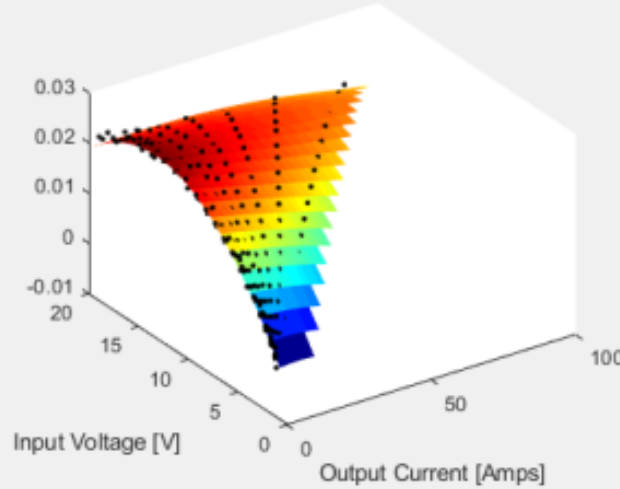
Modeling Parameters as Multi-Dimensional Polynomials



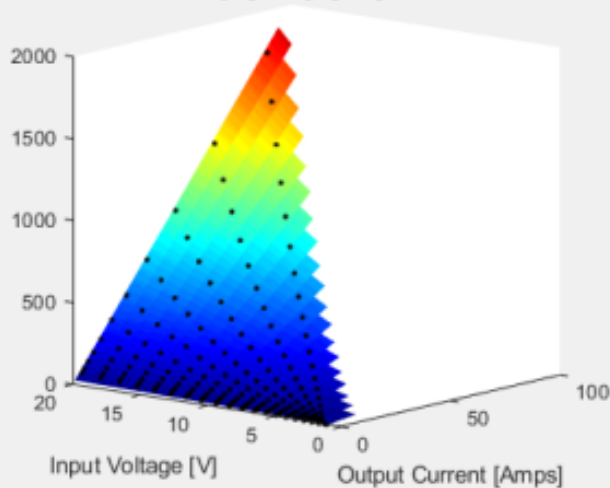
Output Voltage [V], Poly: [2x2], err = 1.9336



RMS Output Voltage [V], Poly: [2x2], err = 0.00016214



Power Loss [W], Poly: [1x1], err = 333.0655



$$\begin{bmatrix} 1.127e-06 & 2.411e-04 & -6.790e-03 \\ -7.693e-05 & -4.359e-03 & 1.162e+00 \\ 1.015e-03 & -2.069e-02 & -1.222e+00 \end{bmatrix}$$

$$\begin{bmatrix} -3.219e-08 & 2.222e-06 & -1.667e-04 \\ 8.7346e-07 & -4.856e-05 & 4.504e-03 \\ -5.533e-06 & 1.205e-04 & -4.507e-03 \end{bmatrix}$$

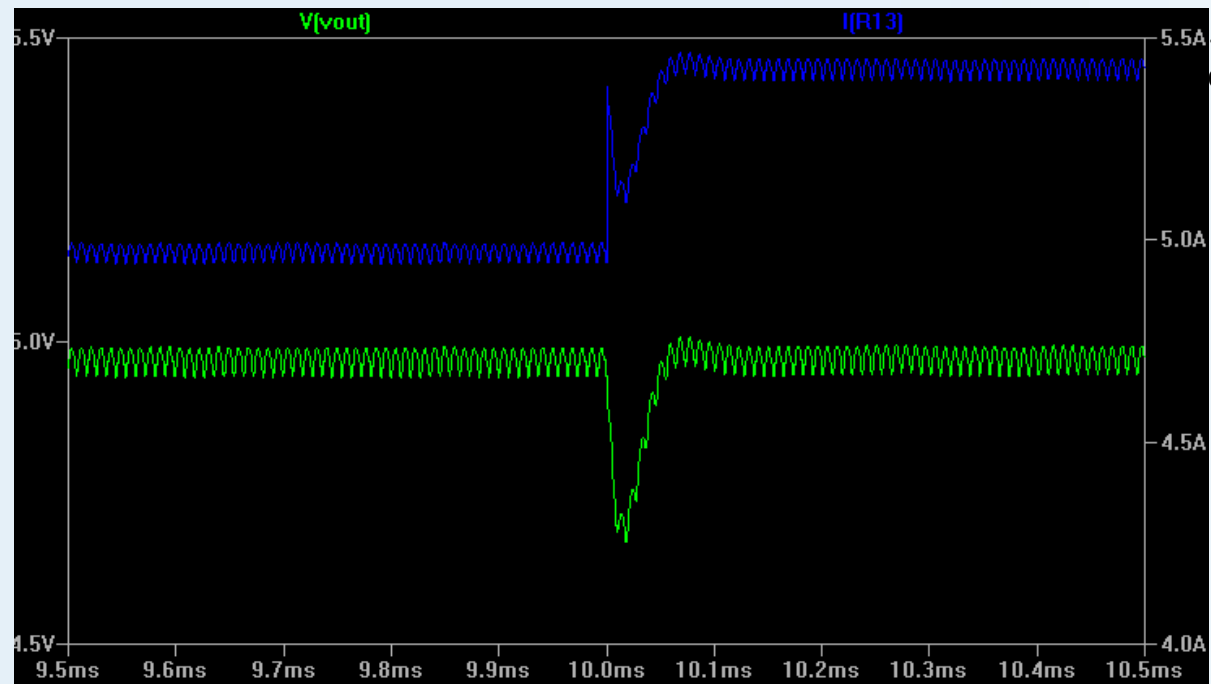
$$\begin{bmatrix} 9.642e-01 & 4.549e-02 \\ 7.222e-01 & -9.500e-02 \end{bmatrix}$$

$$\begin{bmatrix} V_{in}^2 & V_{in} & 1 \end{bmatrix} \begin{bmatrix} A_{11} & A_{12} & A_{13} \\ A_{21} & A_{22} & A_{23} \\ A_{31} & A_{32} & A_{33} \end{bmatrix} \begin{bmatrix} I_{out}^2 \\ I_{out} \\ 1 \end{bmatrix}$$

$$= A_{11} V_{in}^2 I_{out}^2 + A_{12} V_{in}^2 I_{out} + A_{13} V_{in}^2 + A_{21} V_{in} I_{out}^2 + A_{22} V_{in} I_{out} + A_{23} V_{in} + A_{31} I_{out}^2 + A_{32} I_{out} + A_{33}$$

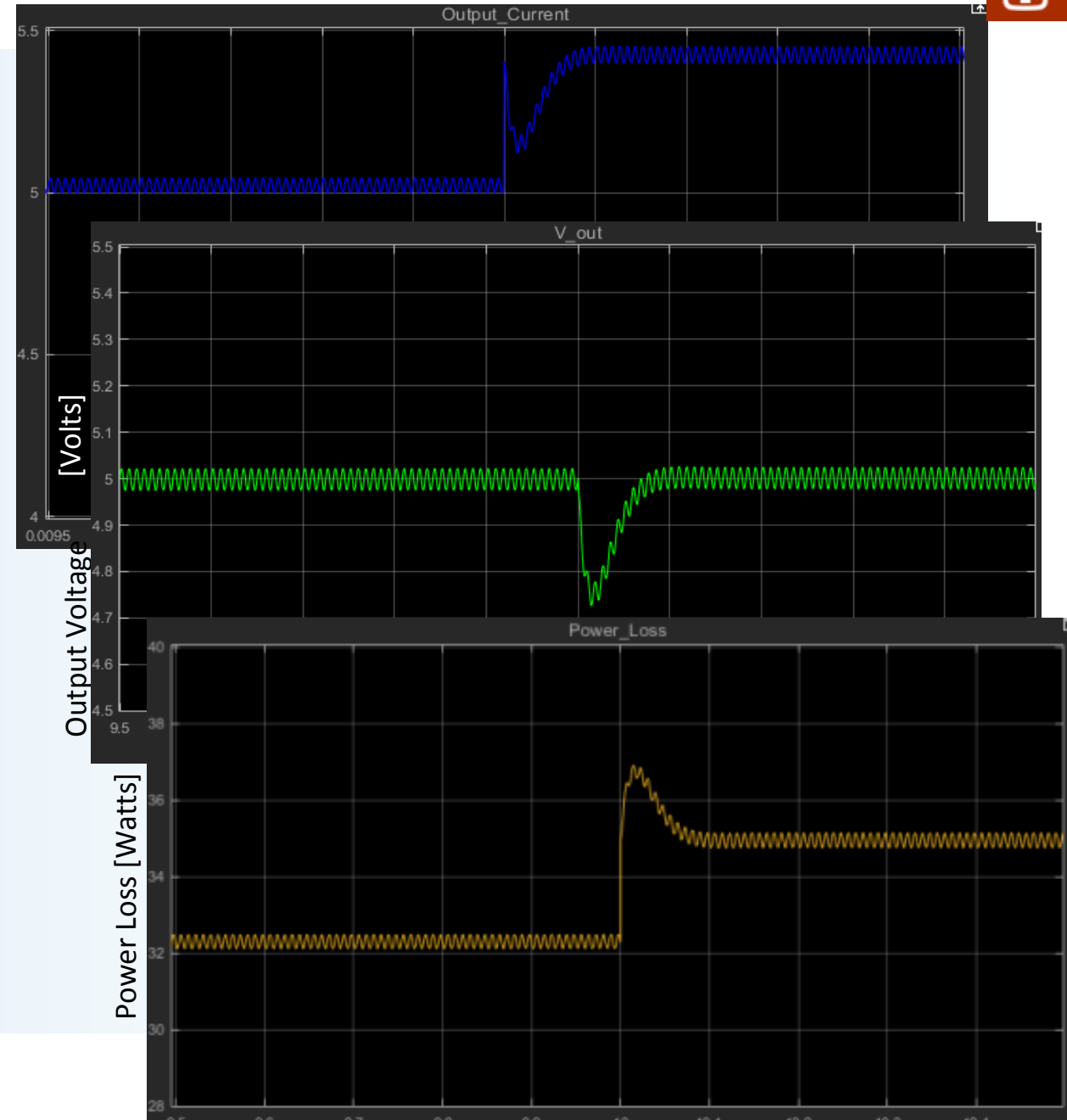
Power Converter Modeling Results

LTspice



Output Current [Amps]

SIMULINK

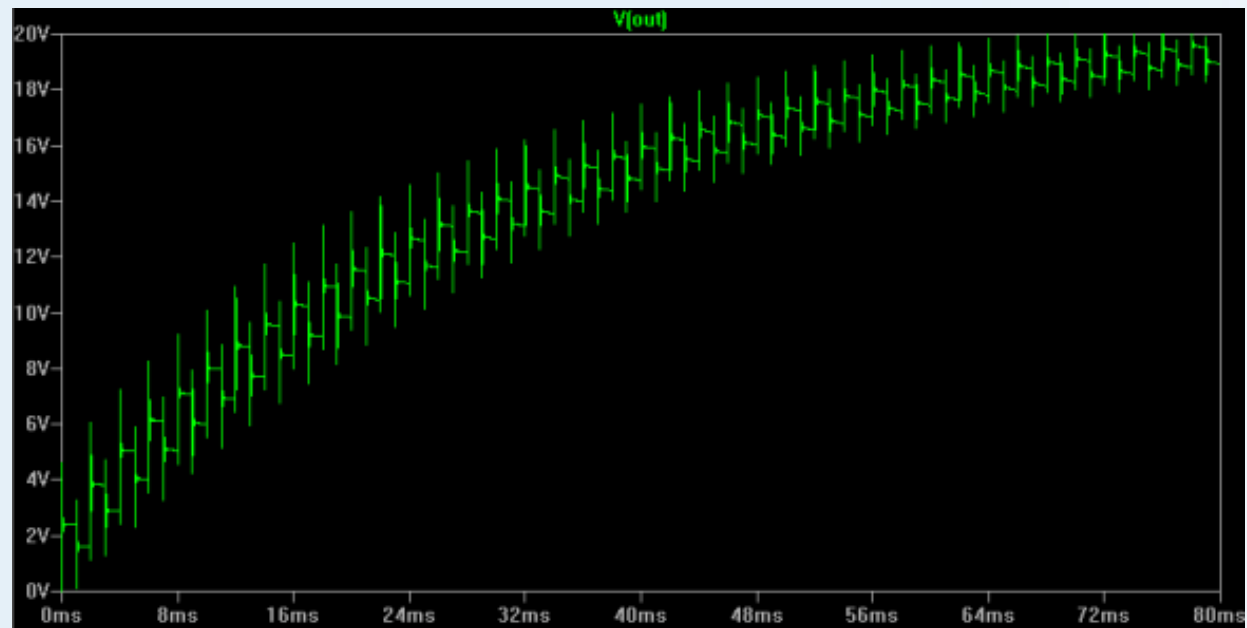


Output Voltage [Volts]

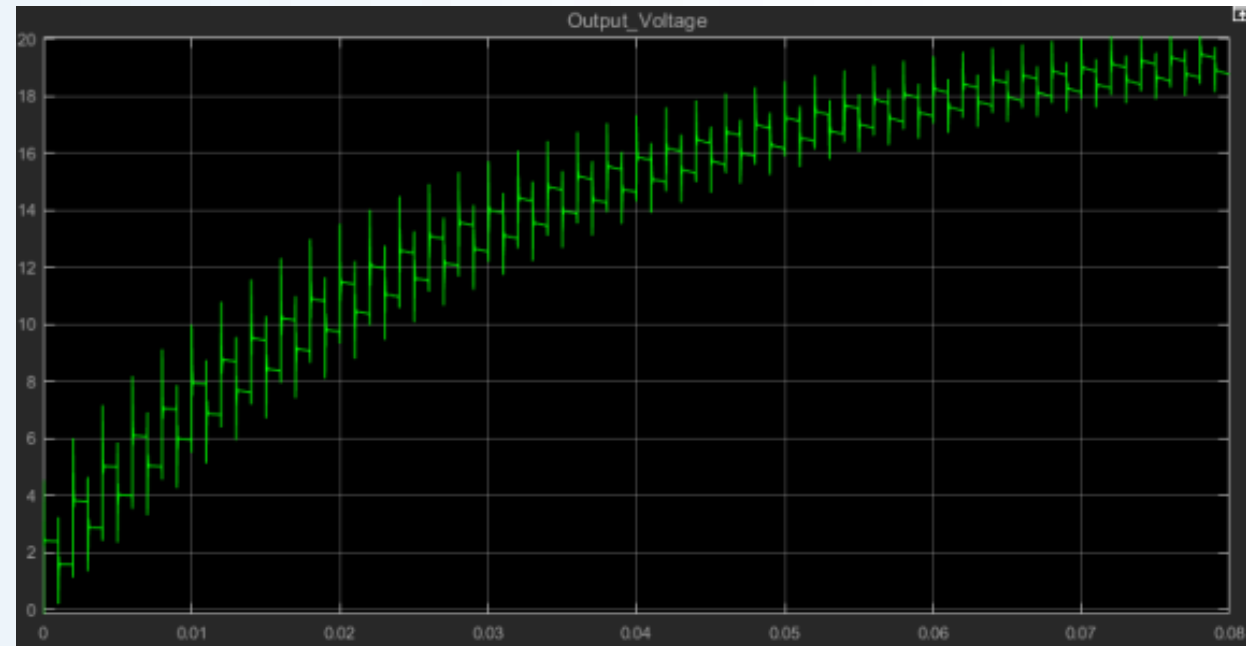
Power Loss [Watts]

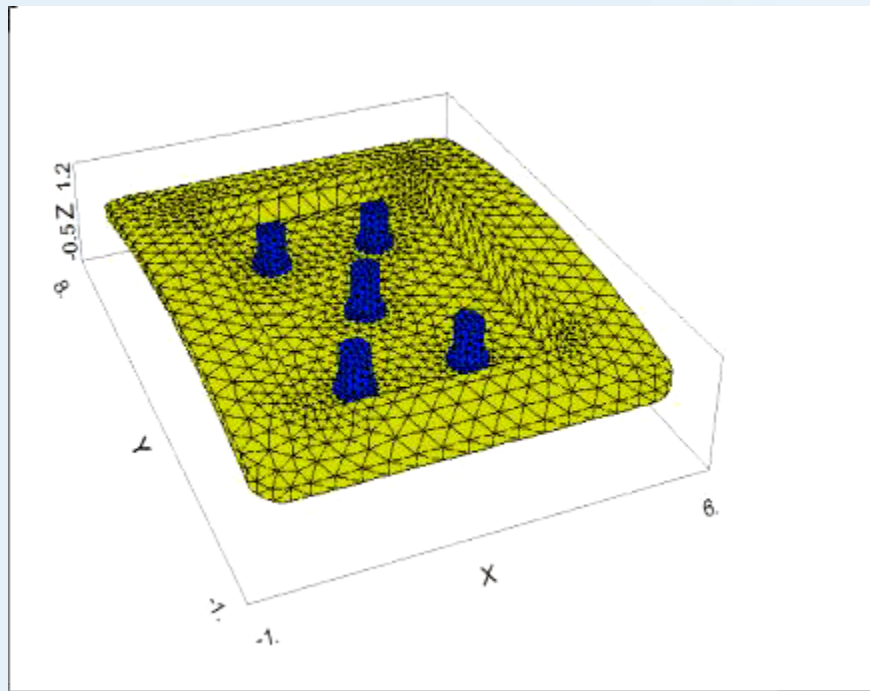
Output Voltage

LTspice

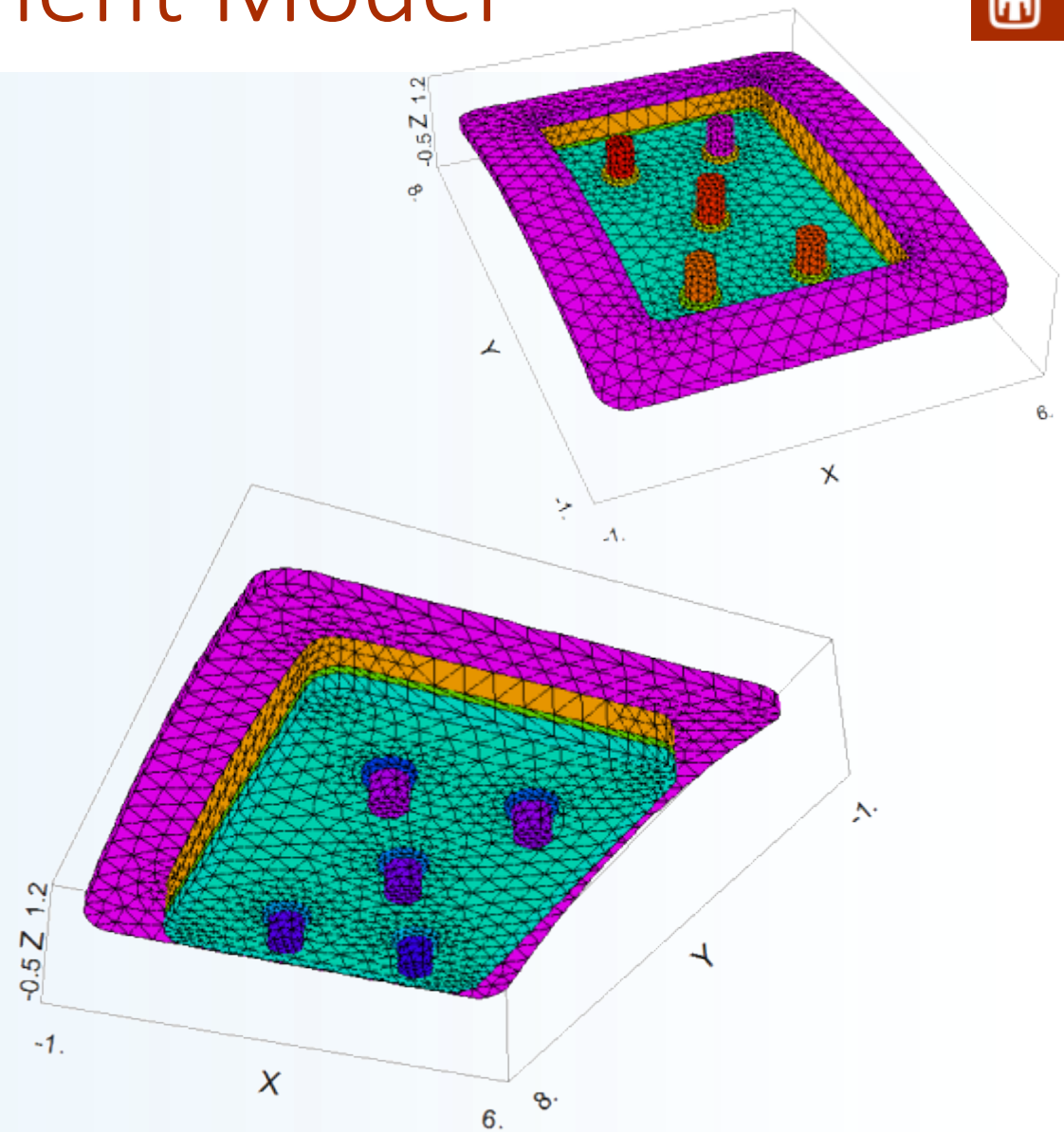


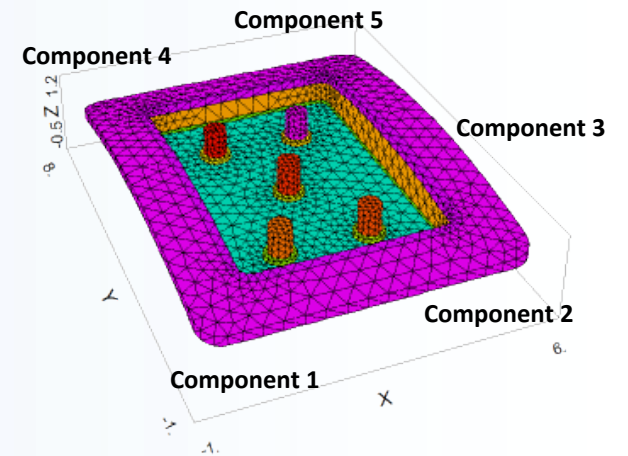
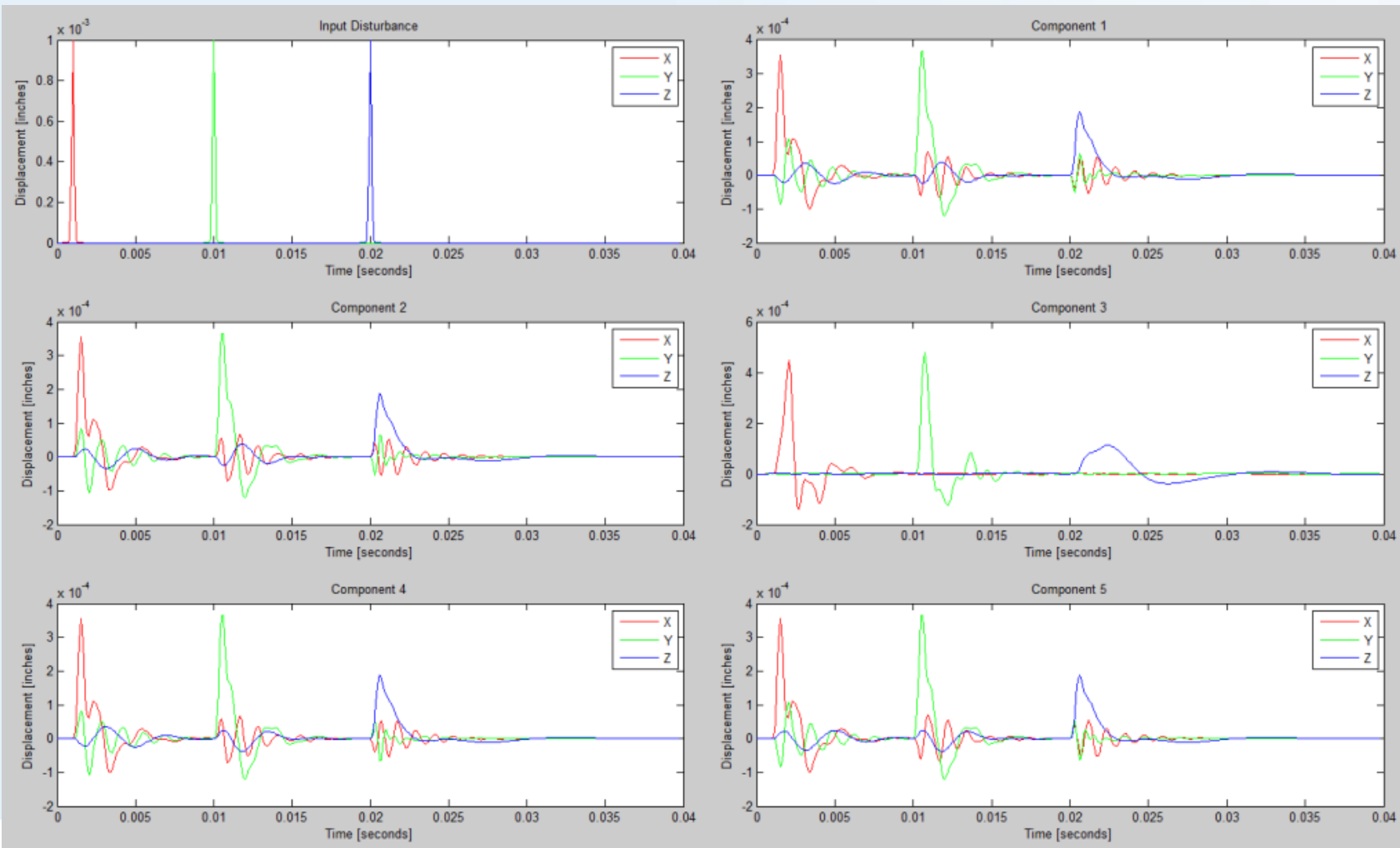
SIMULINK



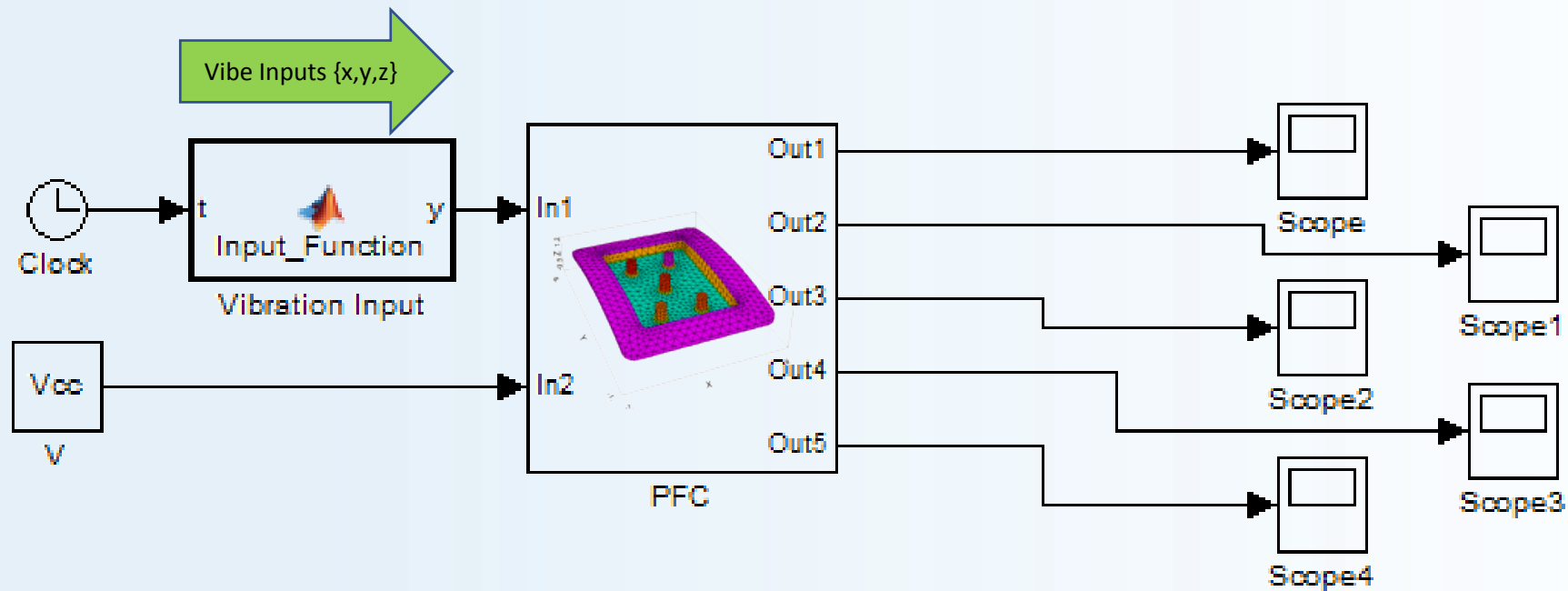


[Click on Video]

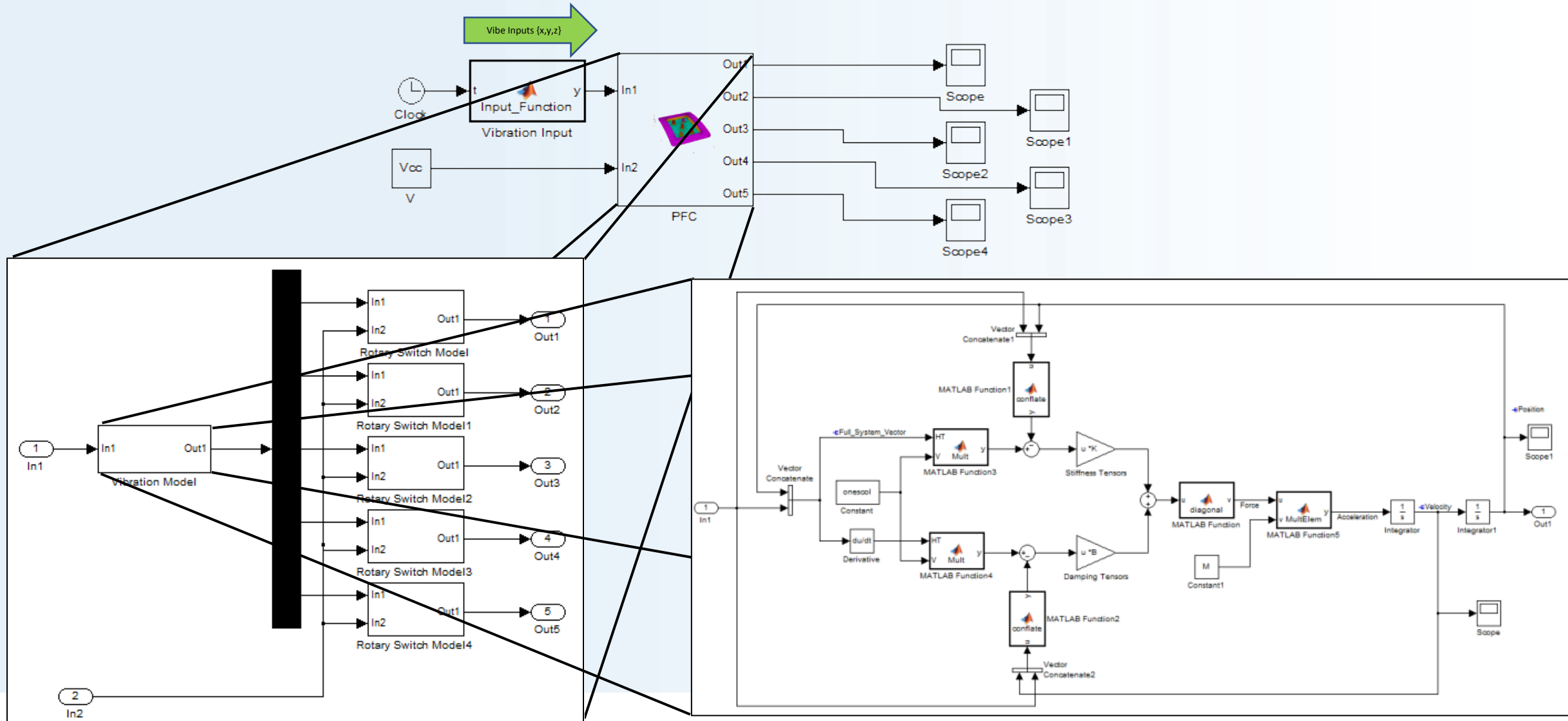




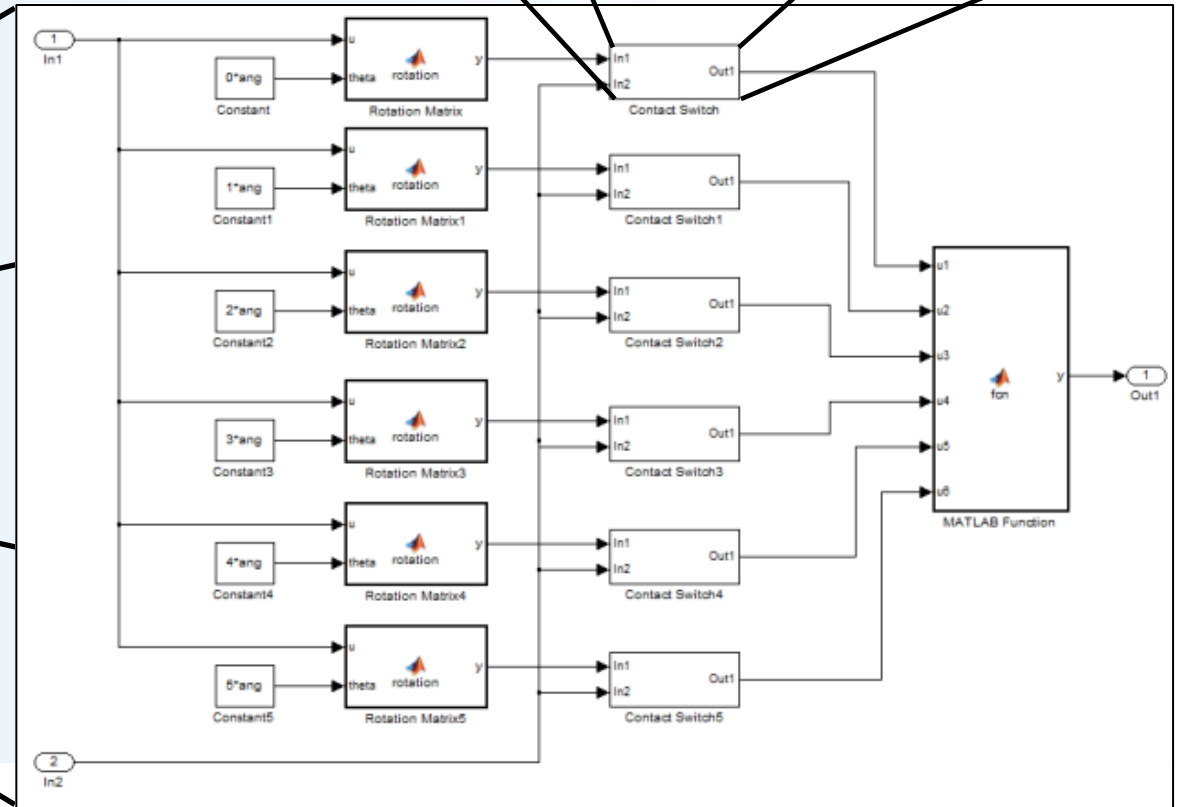
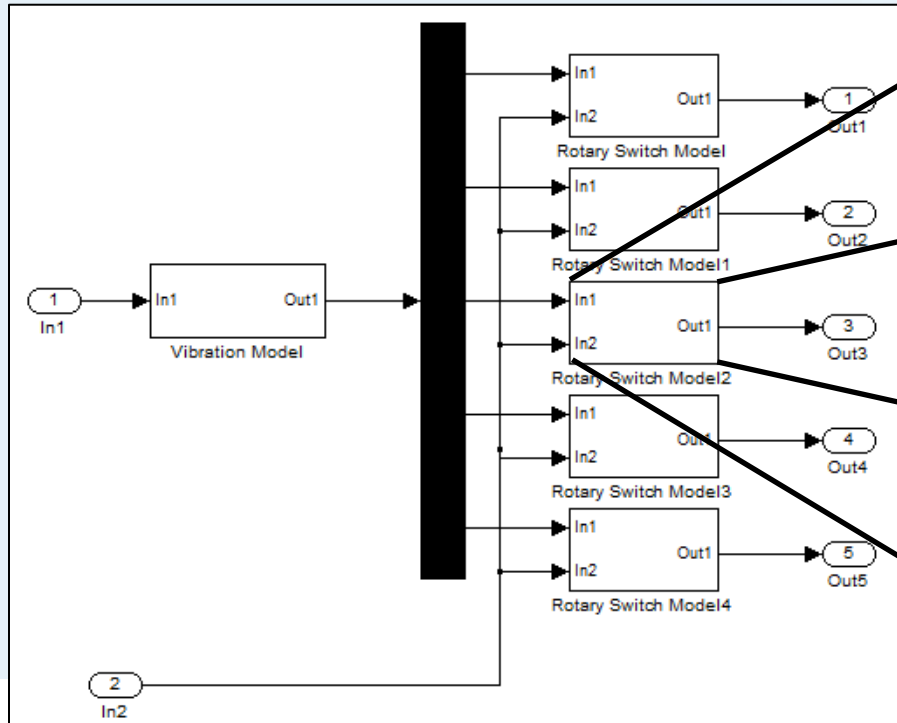
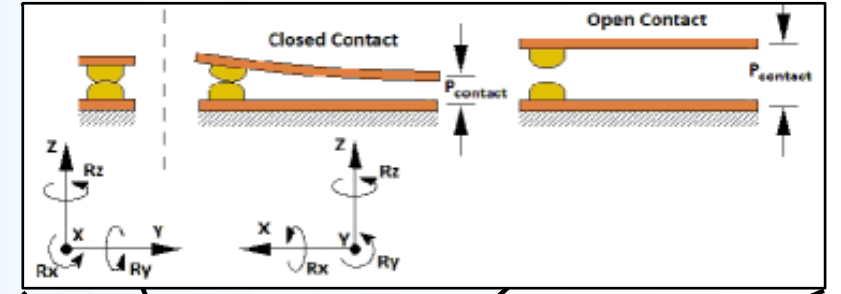
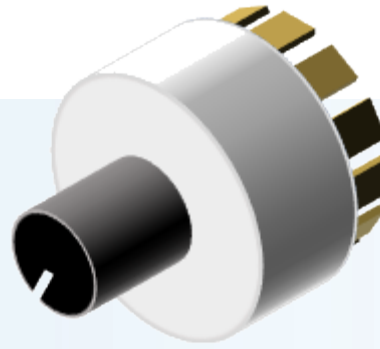
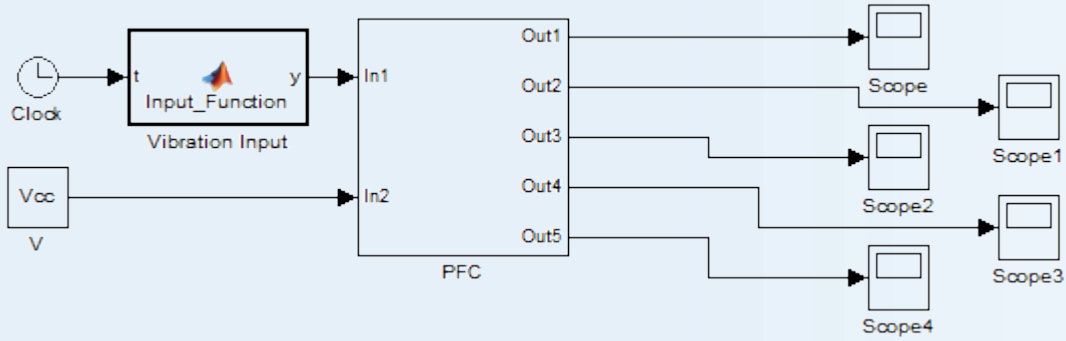
Top Level Simulink Model for Reduced Order Shock/Vibration



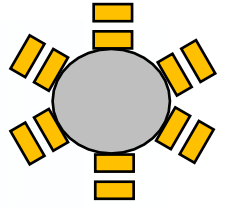
Simulink Model Reduced Order Shock/Vibration



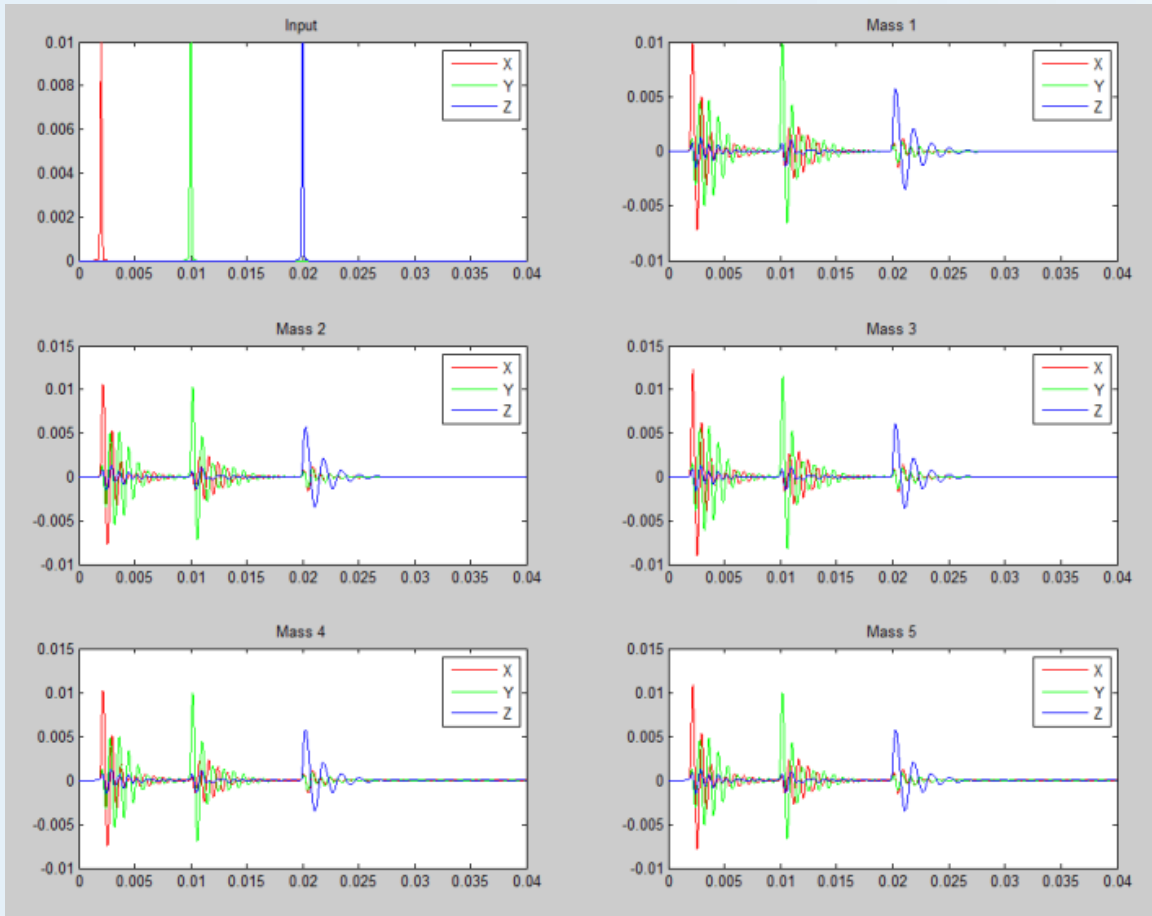
PFC - Simulink Model



Simplified Five-Mass Model



Dynamics of each mass



Acceleration at each connector on component 1
Each component has six contacts at 60° orientation



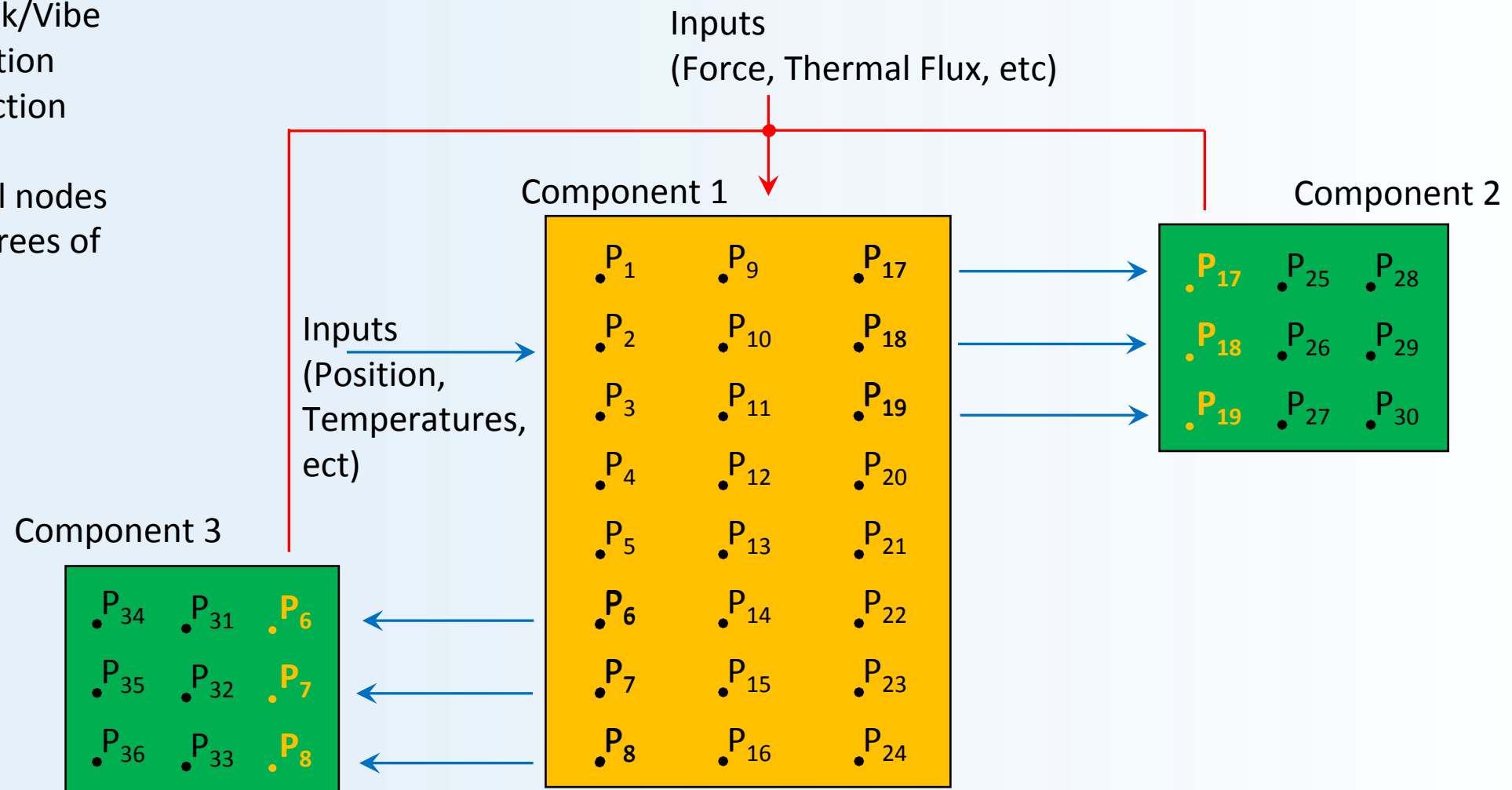
Connecting Linear Continuous Time Models



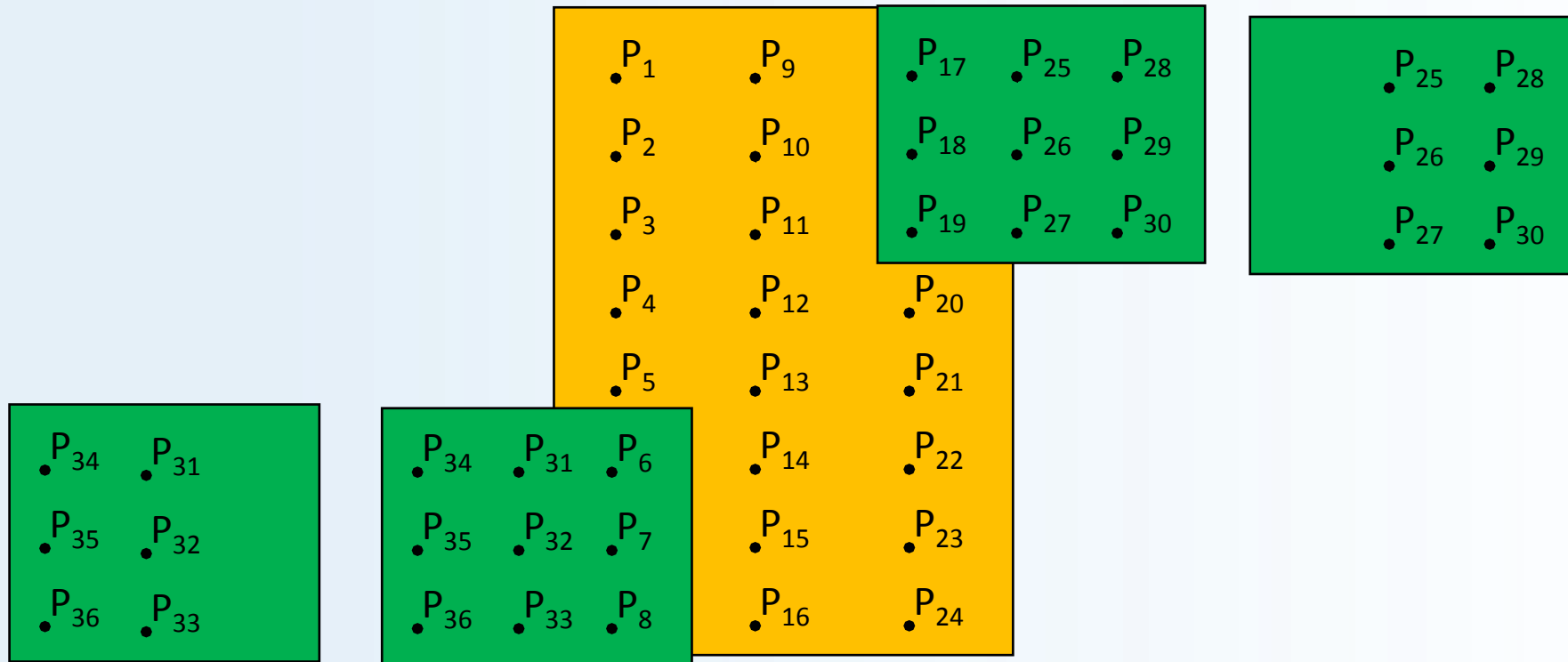
Mechanical Shock/Vibe
Thermal Conduction
Electrical Conduction

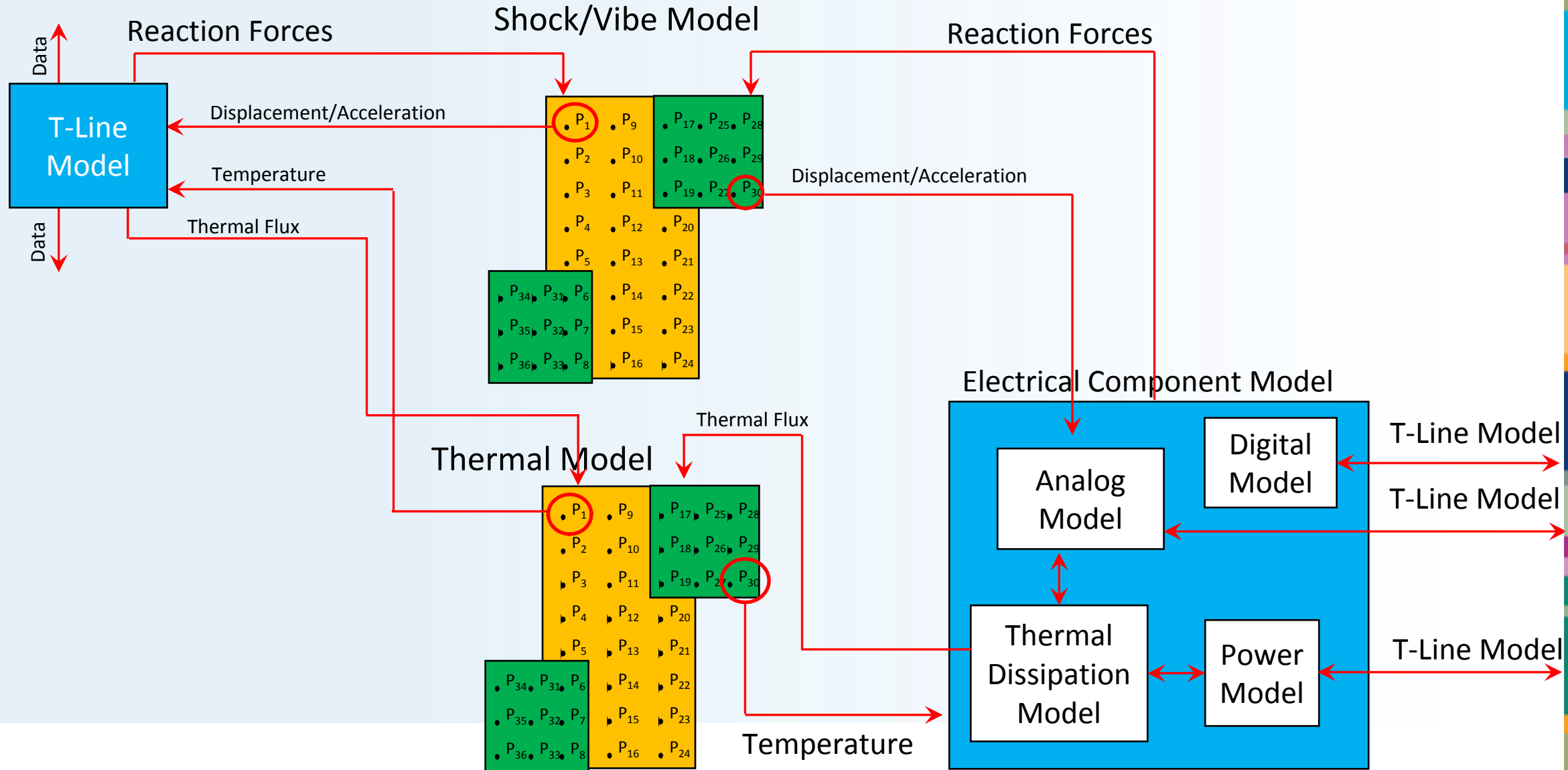
Points are spatial nodes
with physics degrees of
freedom:

- Temperature
- Displacement
- Voltage



Connecting Linear Continuous Time Models

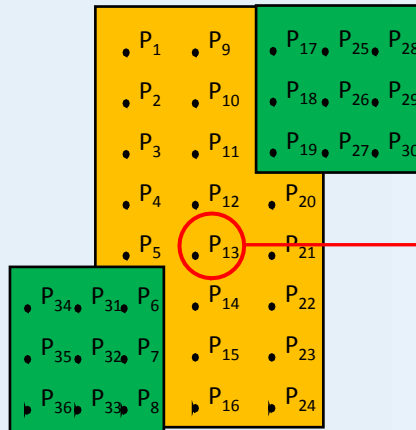




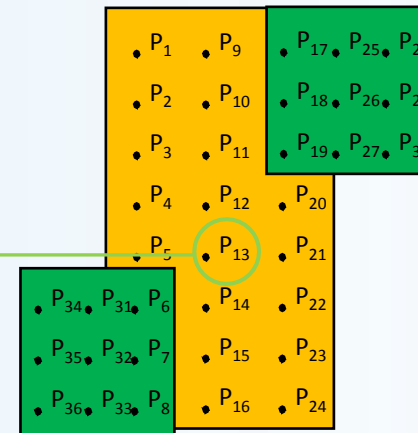
Modeling Interconnects in System Model



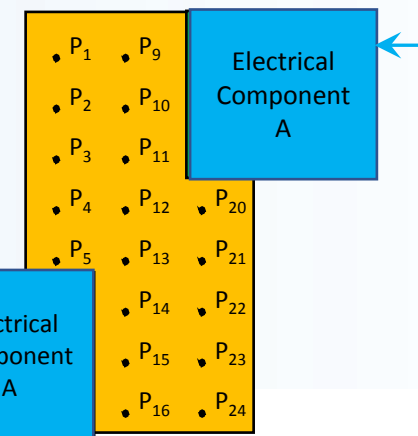
Thermal Model



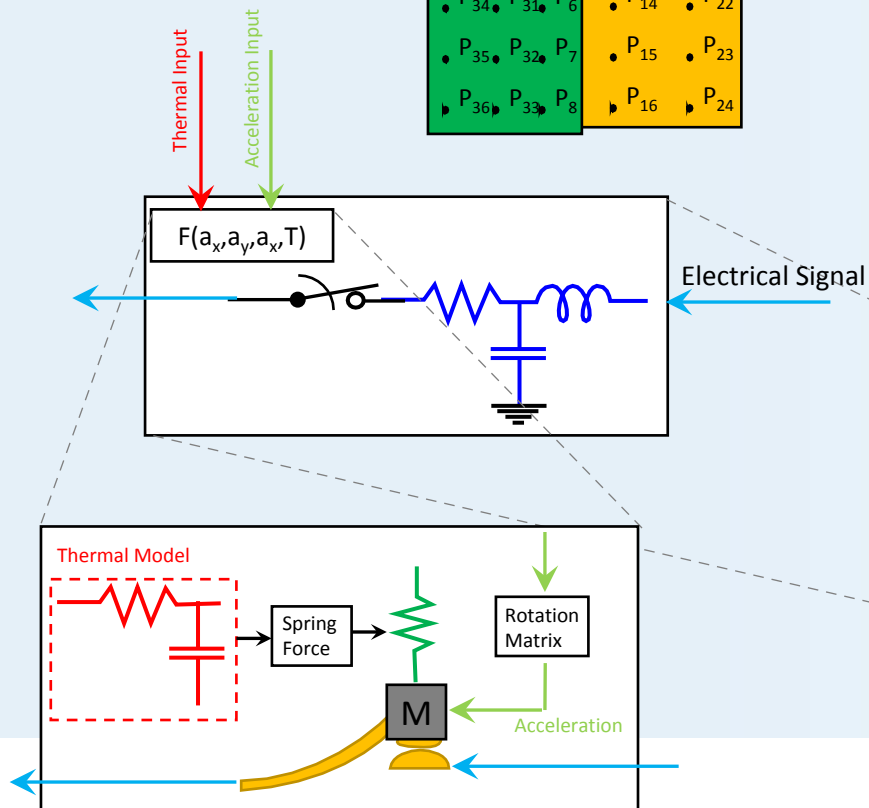
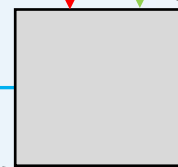
Shock/Vibe Model



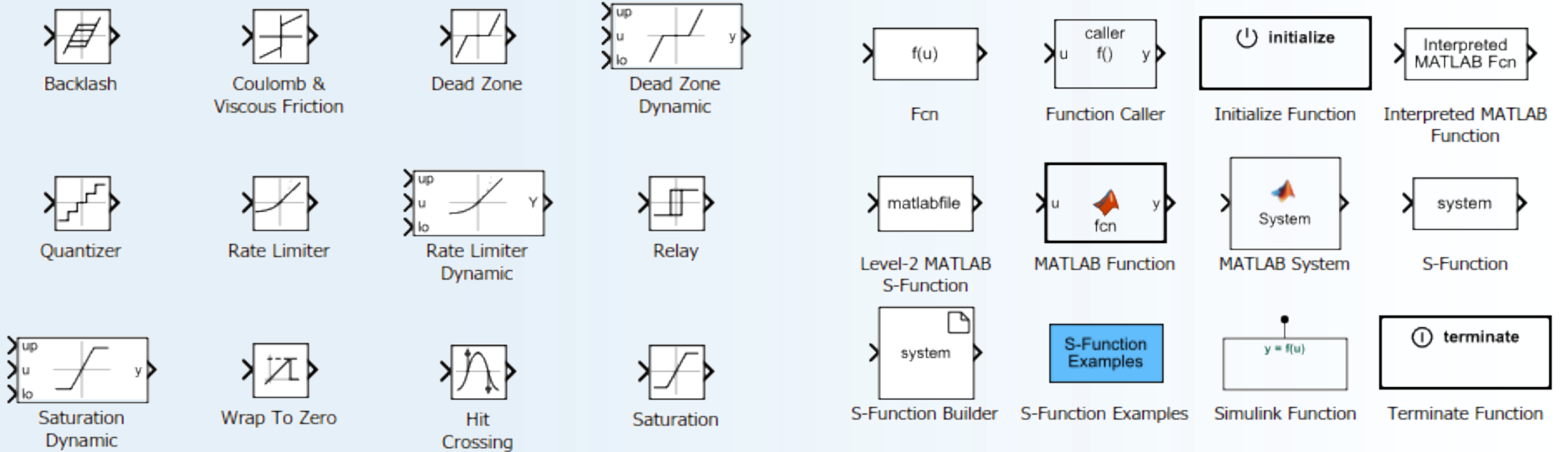
Electrical Model



Interconnect Model



Modeling Nonlinearities

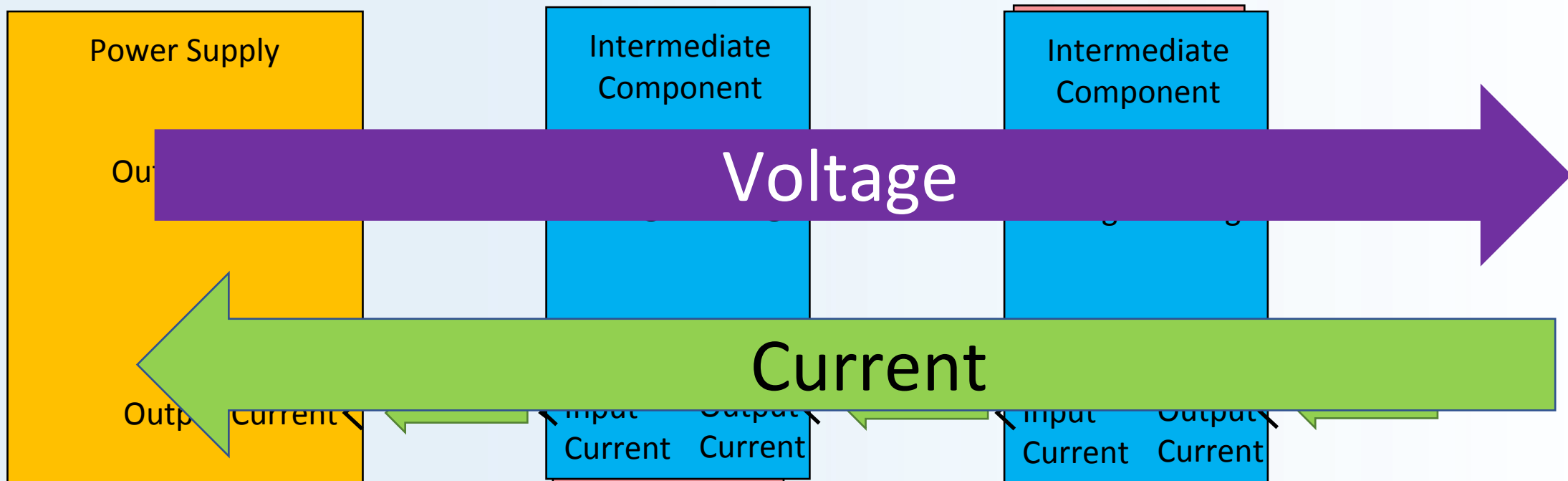


Can be added to existing linear models

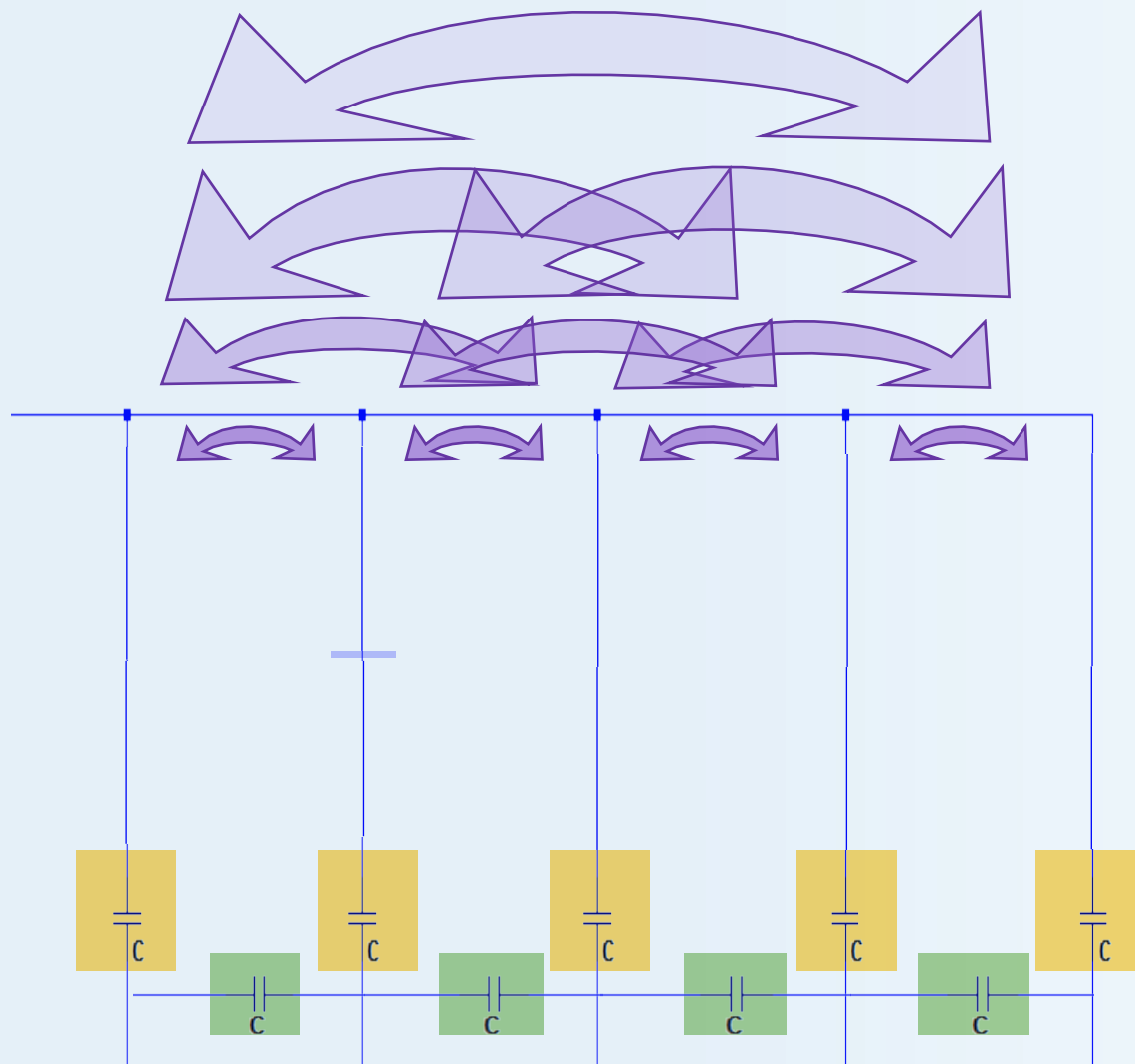
User-Defined, Custom models can be made



- Analog
- Digital
- Power
 - Electrical - Thermal



Capacitive Networks



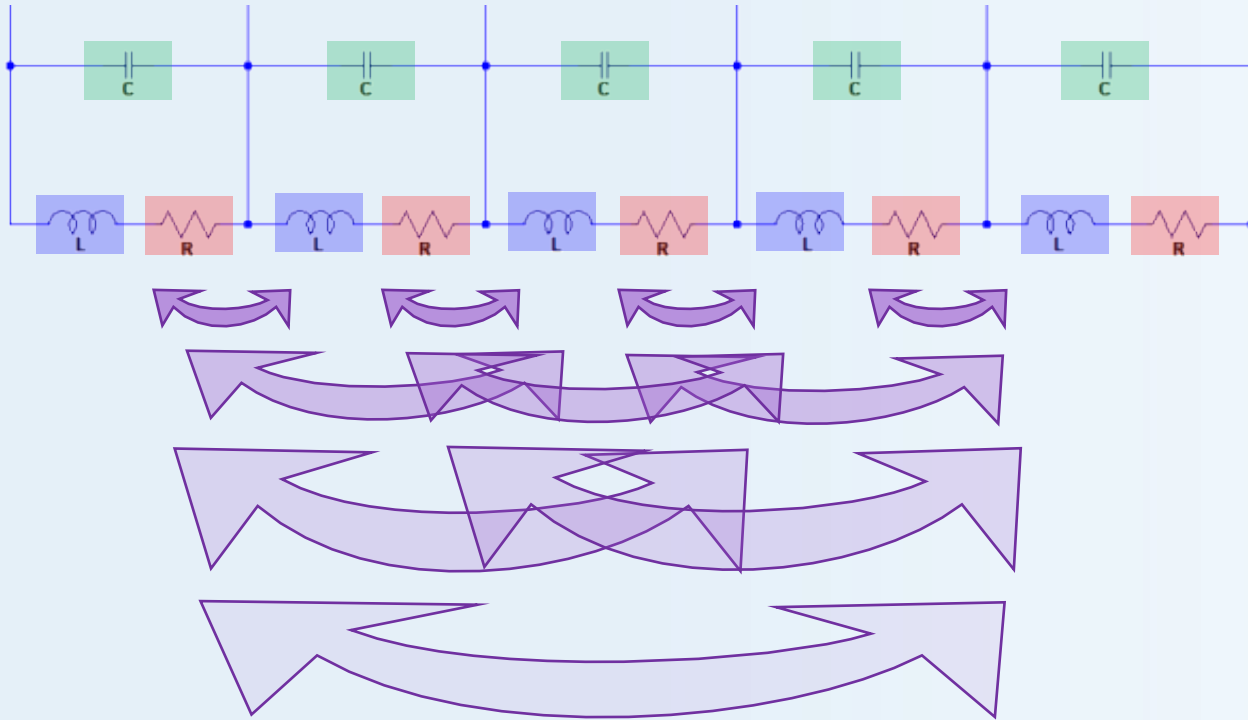
$$\begin{bmatrix} C_{11} & C_{12} & 0 & 0 & 0 \\ C_{12} & C_{22} & C_{23} & 0 & 0 \\ 0 & C_{23} & C_{33} & C_{34} & 0 \\ 0 & 0 & C_{34} & C_{44} & C_{45} \\ 0 & 0 & 0 & C_{45} & C_{55} \end{bmatrix}$$

$$\begin{bmatrix} C_{11}+C_{12} & -C_{12} & 0 & 0 & 0 \\ -C_{12} & C_{12}+C_{22}+C_{23} & -C_{23} & 0 & 0 \\ 0 & -C_{23} & C_{23}+C_{33}+C_{34} & -C_{34} & 0 \\ 0 & 0 & -C_{34} & C_{34}+C_{44}+C_{45} & -C_{45} \\ 0 & 0 & 0 & -C_{45} & C_{45}+C_{55} \end{bmatrix}$$

$$\begin{bmatrix} R_1 \\ R_2 \\ R_3 \\ R_4 \\ R_5 \end{bmatrix}$$

$$\begin{bmatrix} L_{11} & L_{12} & L_{13} & L_{14} & L_{15} \\ L_{21} & L_{22} & L_{23} & L_{24} & L_{25} \\ L_{31} & L_{32} & L_{33} & L_{34} & L_{35} \\ L_{41} & L_{42} & L_{43} & L_{44} & L_{45} \\ L_{51} & L_{52} & L_{53} & L_{54} & L_{55} \end{bmatrix}$$

Inductive Networks



$$\begin{bmatrix} R_1 \\ R_2 \\ R_3 \\ R_4 \\ R_5 \end{bmatrix}$$

$$\begin{bmatrix} C_1 \\ C_2 \\ C_3 \\ C_4 \\ C_5 \end{bmatrix}$$

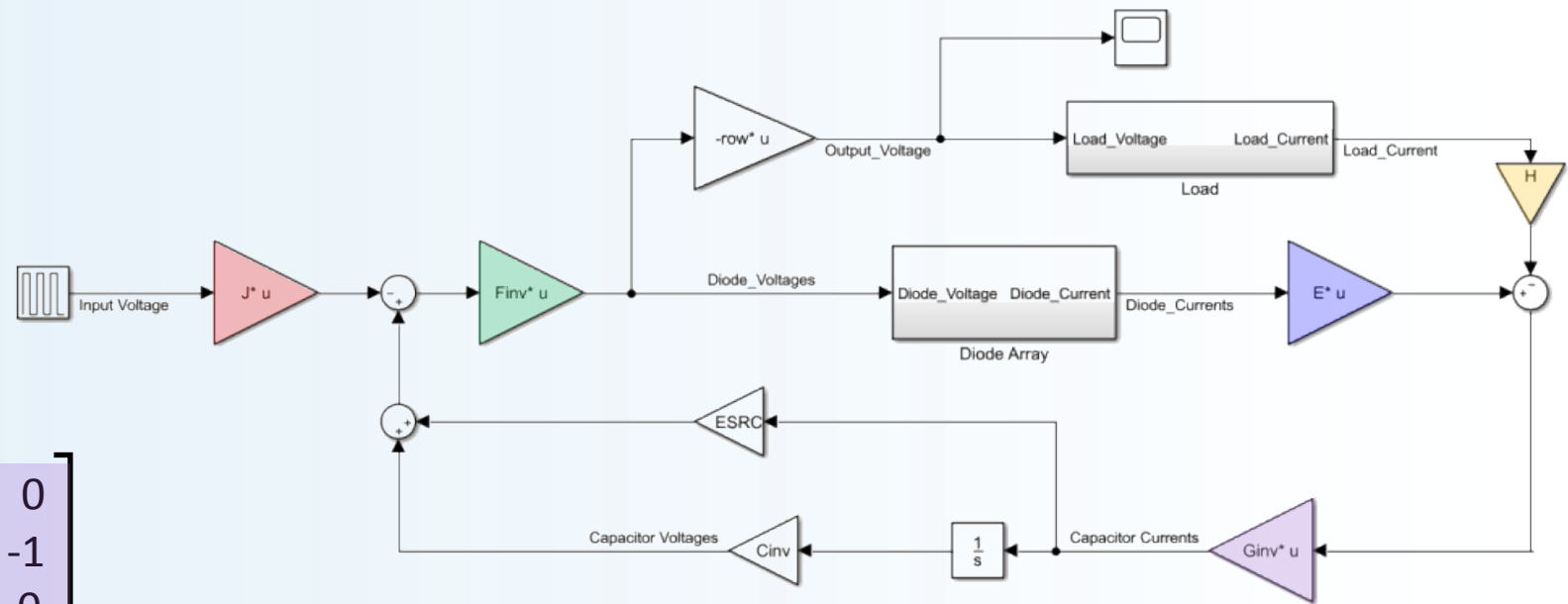
$$\begin{bmatrix} -C_1 & 0 & 0 & 0 & 0 \\ C_1 & -C_2 & 0 & 0 & 0 \\ 0 & C_2 & -C_3 & 0 & 0 \\ 0 & 0 & C_3 & -C_4 & 0 \\ 0 & 0 & 0 & C_4 & -C_5 \end{bmatrix}$$

$$\begin{bmatrix} L_{11} & L_{12} & L_{13} & L_{14} & L_{15} \\ L_{21} & L_{22} & L_{23} & L_{24} & L_{25} \\ L_{31} & L_{32} & L_{33} & L_{34} & L_{35} \\ L_{41} & L_{42} & L_{43} & L_{44} & L_{45} \\ L_{51} & L_{52} & L_{53} & L_{54} & L_{55} \end{bmatrix}$$

Topologically Derived Charge Pump Constants



$$\begin{aligned}
 E &= \begin{bmatrix} 1 & -1 & 0 & 0 & 0 & 0 \\ 0 & 1 & -1 & 0 & 0 & 0 \\ 0 & 0 & 1 & -1 & 0 & 0 \\ 0 & 0 & 0 & 1 & -1 & 0 \\ 0 & 0 & 0 & 0 & 1 & -1 \\ 0 & 0 & 0 & 0 & 0 & 1 \end{bmatrix} & J &= \begin{bmatrix} 1 \\ 0 \\ 0 \\ 0 \\ 0 \\ 0 \end{bmatrix} & H &= \begin{bmatrix} 0 \\ -1 \\ 0 \\ -1 \\ 0 \\ -1 \end{bmatrix} \\
 F &= \begin{bmatrix} -1 & 0 & 0 & 0 & 0 & 0 \\ 1 & 1 & 0 & 0 & 0 & 0 \\ 0 & 1 & 1 & 0 & 0 & 0 \\ 0 & 0 & 1 & 1 & 0 & 0 \\ 0 & 0 & 0 & 1 & 1 & 0 \\ 0 & 0 & 0 & 0 & 1 & 1 \end{bmatrix} & F^{-1} &= \begin{bmatrix} -1 & 0 & 0 & 0 & 0 & 0 \\ 1 & 1 & 0 & 0 & 0 & 0 \\ -1 & -1 & 1 & 0 & 0 & 0 \\ 1 & 1 & -1 & 1 & 0 & 0 \\ -1 & -1 & 1 & -1 & 1 & 0 \\ 1 & 1 & -1 & 1 & -1 & 1 \end{bmatrix} \\
 G &= \begin{bmatrix} -1 & 0 & 1 & 0 & 0 & 0 \\ 0 & -1 & 0 & 1 & 0 & 0 \\ 0 & 0 & -1 & 0 & 1 & 0 \\ 0 & 0 & 0 & -1 & 0 & 1 \\ 0 & 0 & 0 & 0 & -1 & 0 \\ 0 & 0 & 0 & 0 & 0 & -1 \end{bmatrix} & G^{-1} &= \begin{bmatrix} -1 & 0 & -1 & 0 & -1 & 0 \\ 0 & -1 & 0 & -1 & 0 & -1 \\ 0 & 0 & -1 & 0 & -1 & 0 \\ 0 & 0 & 0 & -1 & 0 & -1 \\ 0 & 0 & 0 & 0 & -1 & 0 \\ 0 & 0 & 0 & 0 & 0 & -1 \end{bmatrix}
 \end{aligned}$$



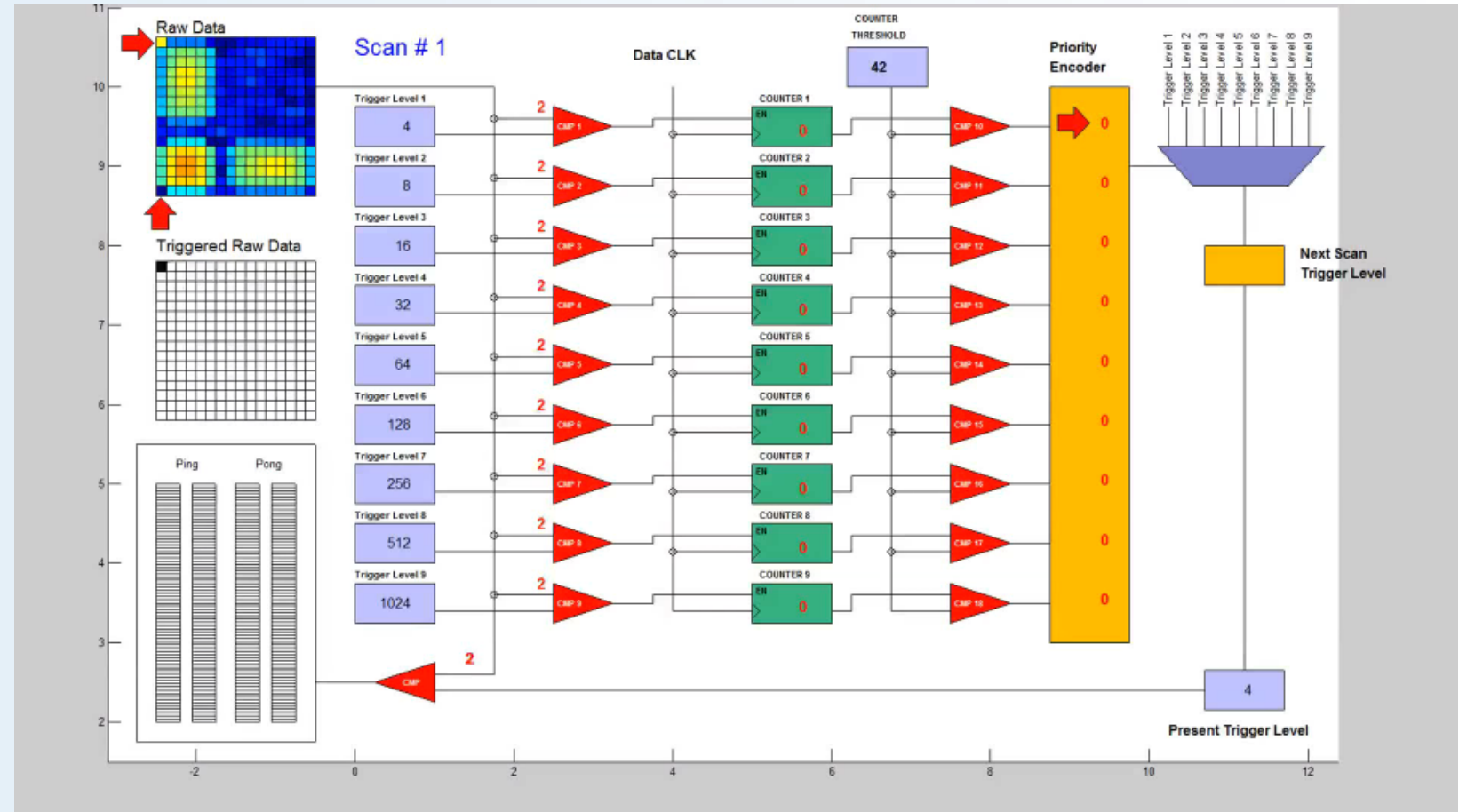
Modeled components:

- Configuration Registers
- Digital Signal Processors
- Ping-Pong SRAM Memories
- Counters
- Comparators
- Latches
- Other state machines

Functions:

- High-pass/low-pass image filtering
- Auto trigger threshold shifting
- Commandable windows
 - Force trigger
 - Mask
 - Return to normal
- Persistence latching
- Data Prioritization modes
- Noise threshold pointers

A Matlab model was made of a Sandia-designed High Speed Focal Plane Array (FPA)

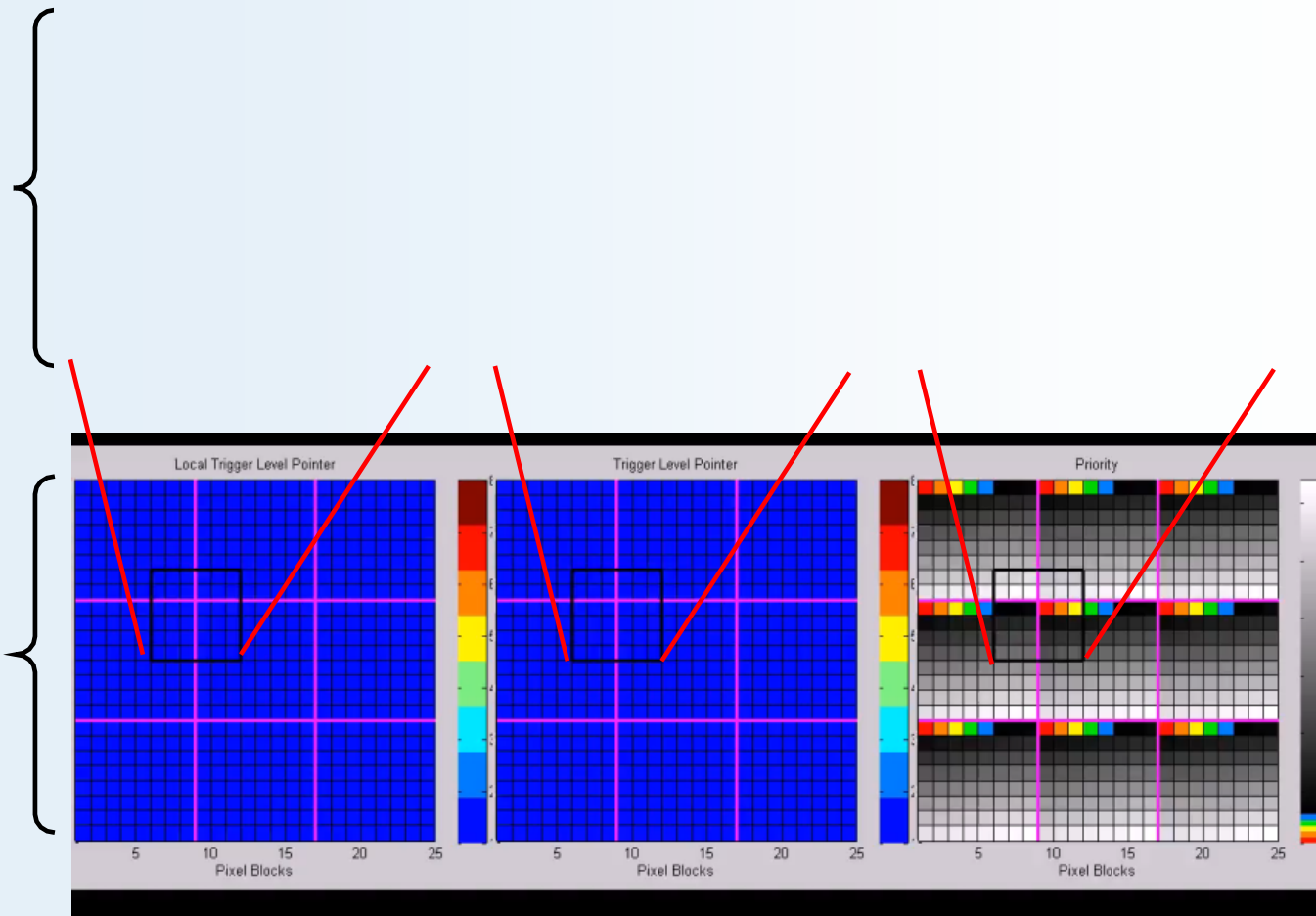


[Click on Video]

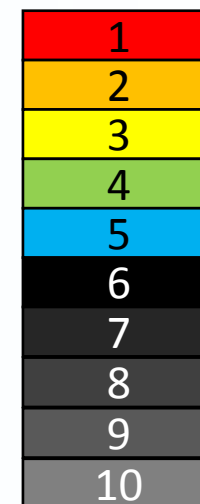


384 x 384 Pixels,
2304 Digital Signal Processors

Entire Focal Plane array
1536 x 1536 Pixels



Top 5 Prioritized DSPs

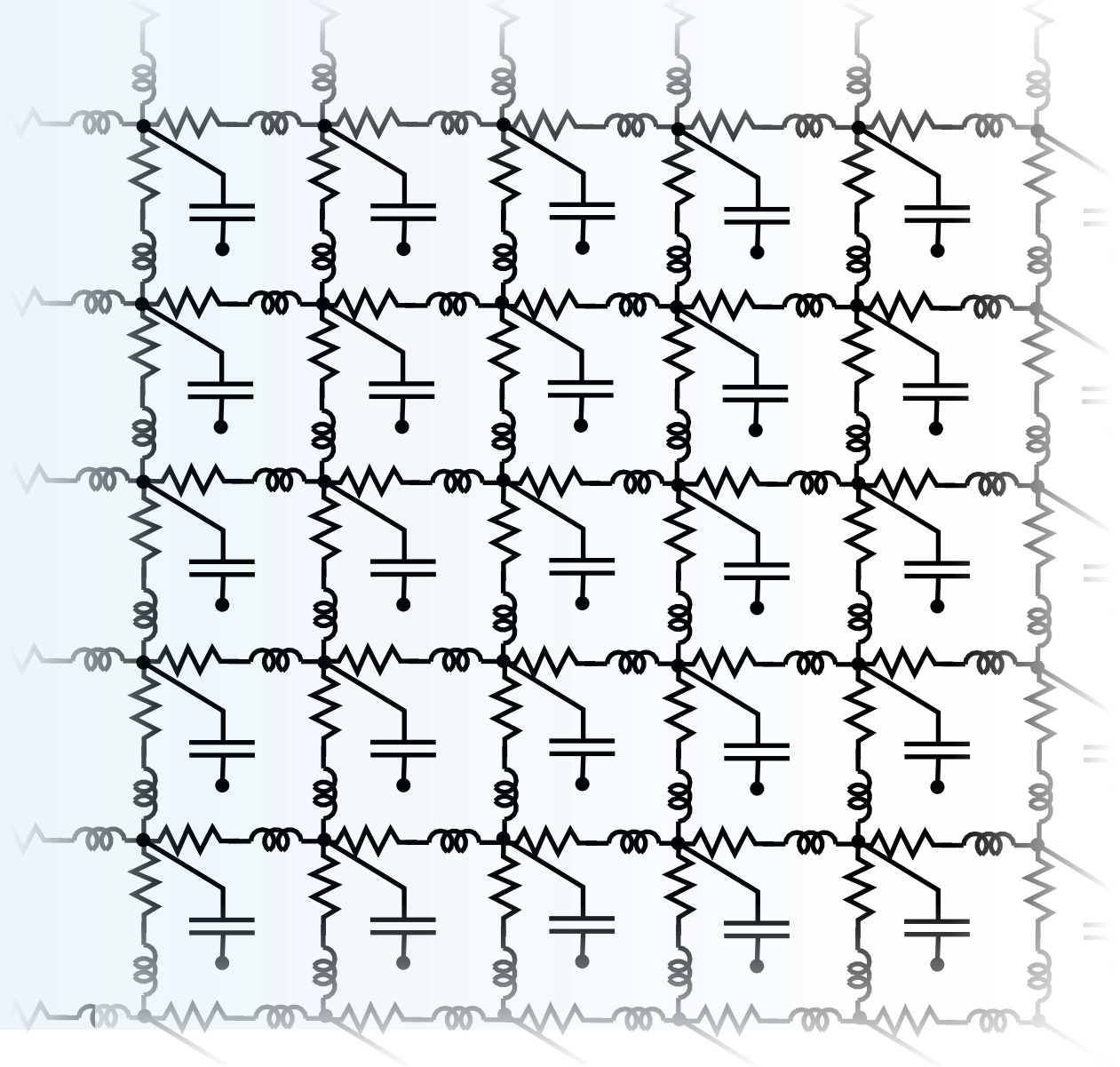


⋮

64

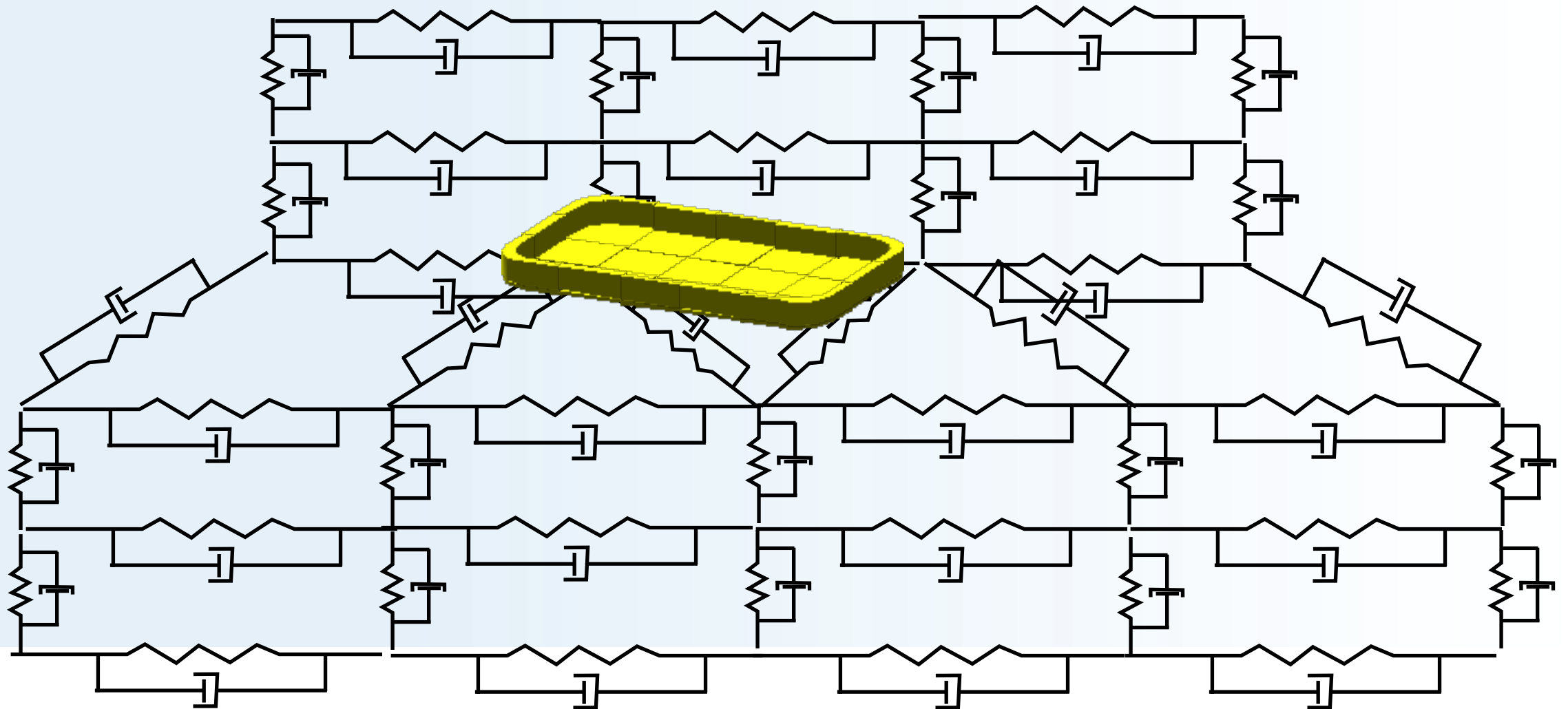
[Click on Video]

- Chassis Currents
 - Faults
 - Common mode currents
 - Lightning
- 2D / 3D transmission line





- Vibration / Shock
- Peak Stress
- Fatigue
- Kinematic Behavior
- Deformation



Coupling Elements as Tensors vs Constants



Stiffness Tensor

$$\begin{bmatrix} k_{xx23} & k_{xy23} & k_{xz23} \\ k_{yx23} & k_{yy23} & k_{yz23} \\ k_{zx23} & k_{zy23} & k_{zz23} \end{bmatrix}$$

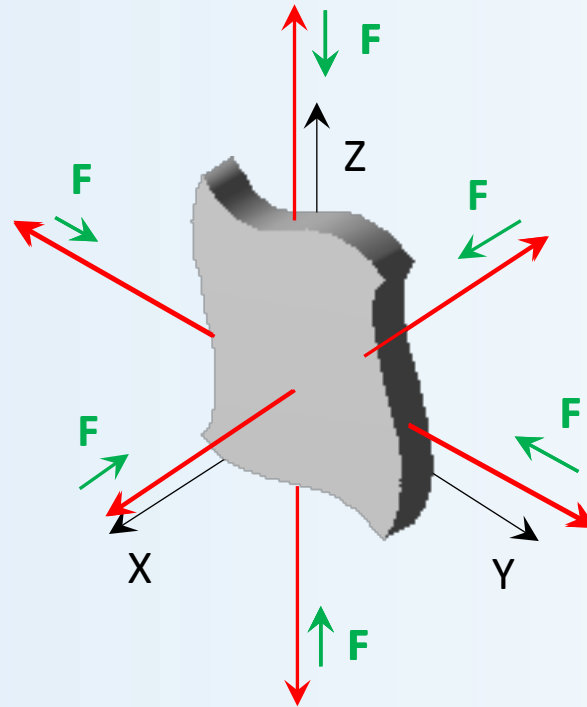
Symmetry

Damping Tensor

$$\begin{bmatrix} b_{xx23} & b_{xy23} & b_{xz23} \\ b_{yx23} & b_{yy23} & b_{yz23} \\ b_{zx23} & b_{zy23} & b_{zz23} \end{bmatrix}$$

Symmetry

Displacement / "Stretching"
Force

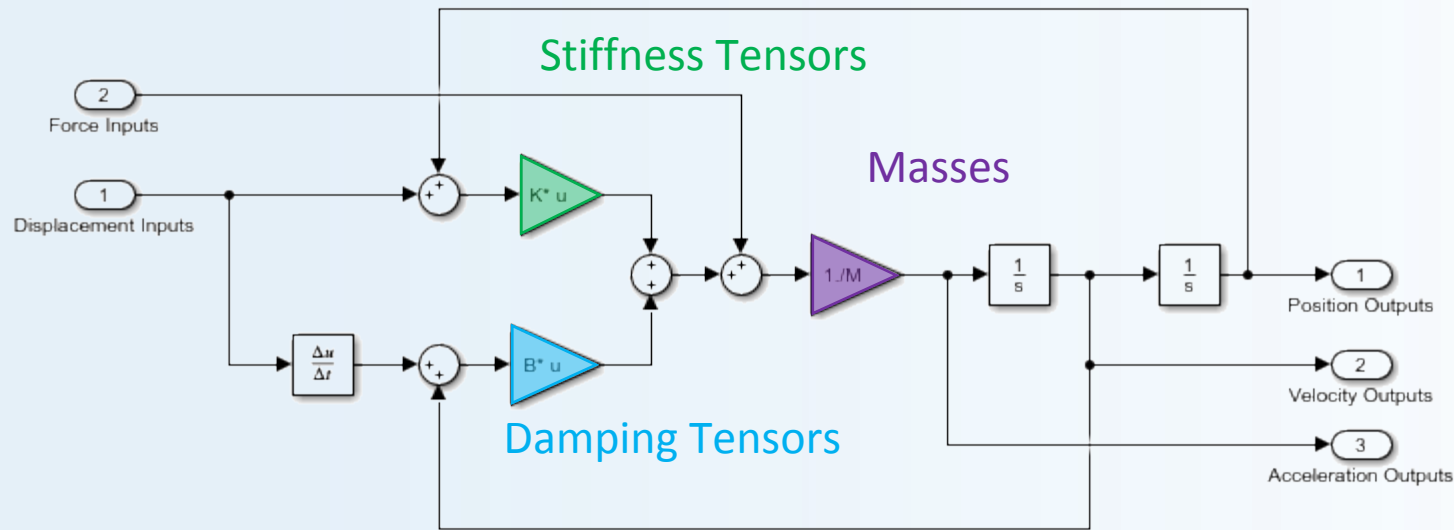


Stiffness Tensors in System Matrix

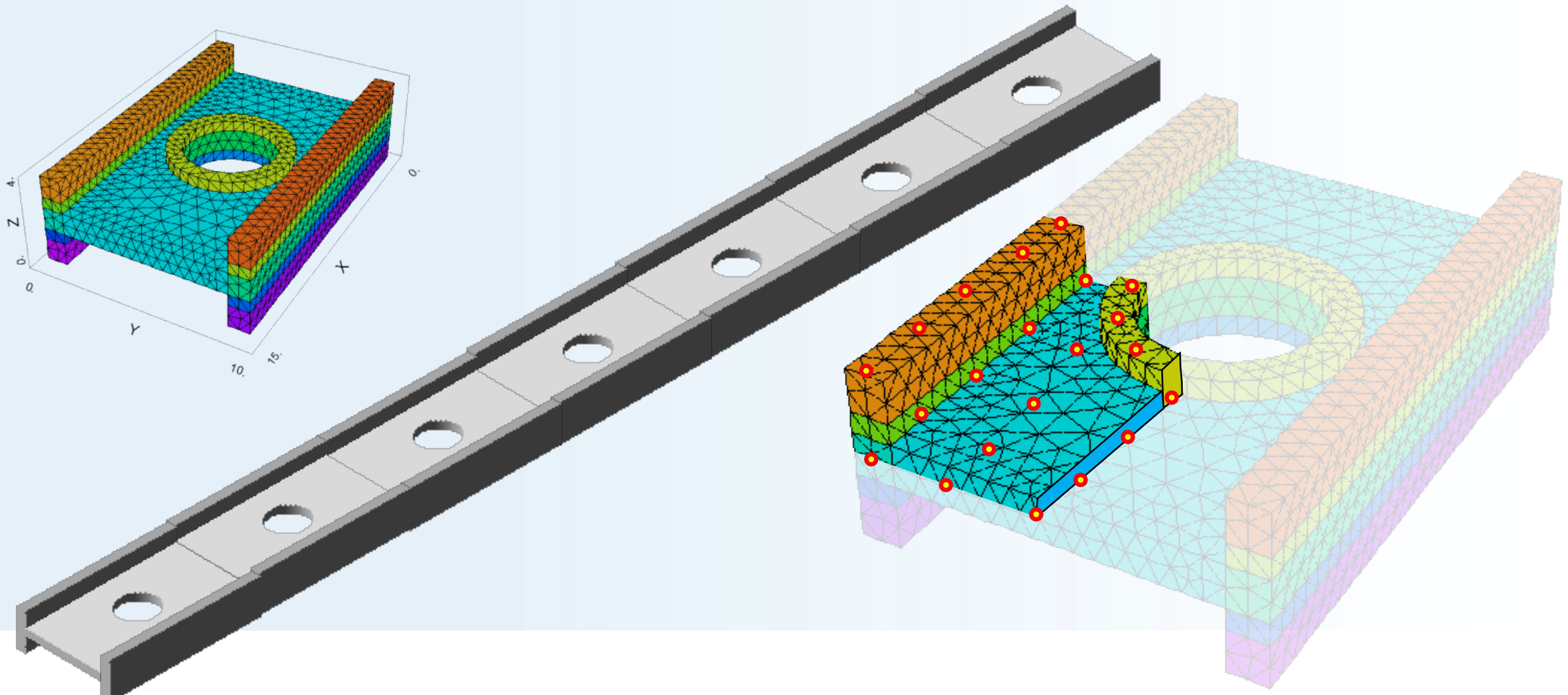


k_{xx11}	k_{xy11}	k_{xz11}	k_{xx12}	k_{xy12}	k_{xz12}	k_{xx13}	k_{xy13}	k_{xz13}	k_{xx14}	k_{xy14}	k_{xz14}
k_{yx11}	k_{yy11}	k_{yz11}	k_{yx12}	k_{yy12}	k_{yz12}	k_{yx13}	k_{yy13}	k_{yz13}	k_{yx14}	k_{yy14}	k_{yz14}
k_{zx11}	k_{zy11}	k_{zz11}	k_{zx12}	k_{zy12}	k_{zz12}	k_{zx13}	k_{zy13}	k_{zz13}	k_{zx14}	k_{zy14}	k_{zz14}
k_{xx21}	k_{xy21}	k_{xz21}	k_{xx22}	k_{xy22}	k_{xz22}	k_{xx23}	k_{xy23}	k_{xz23}	k_{xx24}	k_{xy24}	k_{xz24}
k_{yx21}	k_{yy21}	k_{yz21}	k_{yx22}	k_{yy22}	k_{yz22}	k_{yx23}	k_{yy23}	k_{yz23}	k_{yx24}	k_{yy24}	k_{yz24}
k_{zx21}	k_{zy21}	k_{zz21}	k_{zx22}	k_{zy22}	k_{zz22}	k_{zx23}	k_{zy23}	k_{zz23}	k_{zx24}	k_{zy24}	k_{zz24}
k_{xx31}	k_{xy31}	k_{xz31}	k_{xx32}	k_{xy32}	k_{xz32}	k_{xx33}	k_{xy33}	k_{xz33}	k_{xx34}	k_{xy34}	k_{xz34}
k_{yx31}	k_{yy31}	k_{yz31}	k_{yx32}	k_{yy32}	k_{yz32}	k_{yx33}	k_{yy33}	k_{yz33}	k_{yx34}	k_{yy34}	k_{yz34}
k_{zx31}	k_{zy31}	k_{zz31}	k_{zx32}	k_{zy32}	k_{zz32}	k_{zx33}	k_{zy33}	k_{zz33}	k_{zx34}	k_{zy34}	k_{zz34}
k_{xx41}	k_{xy41}	k_{xz41}	k_{xx42}	k_{xy42}	k_{xz42}	k_{xx43}	k_{xy43}	k_{xz43}	k_{xx44}	k_{xy44}	k_{xz44}
k_{yx41}	k_{yy41}	k_{yz41}	k_{yx42}	k_{yy42}	k_{yz42}	k_{yx43}	k_{yy43}	k_{yz43}	k_{yx44}	k_{yy44}	k_{yz44}
k_{zx41}	k_{zy41}	k_{zz41}	k_{zx42}	k_{zy42}	k_{zz42}	k_{zx43}	k_{zy43}	k_{zz43}	k_{zx44}	k_{zy44}	k_{zz44}

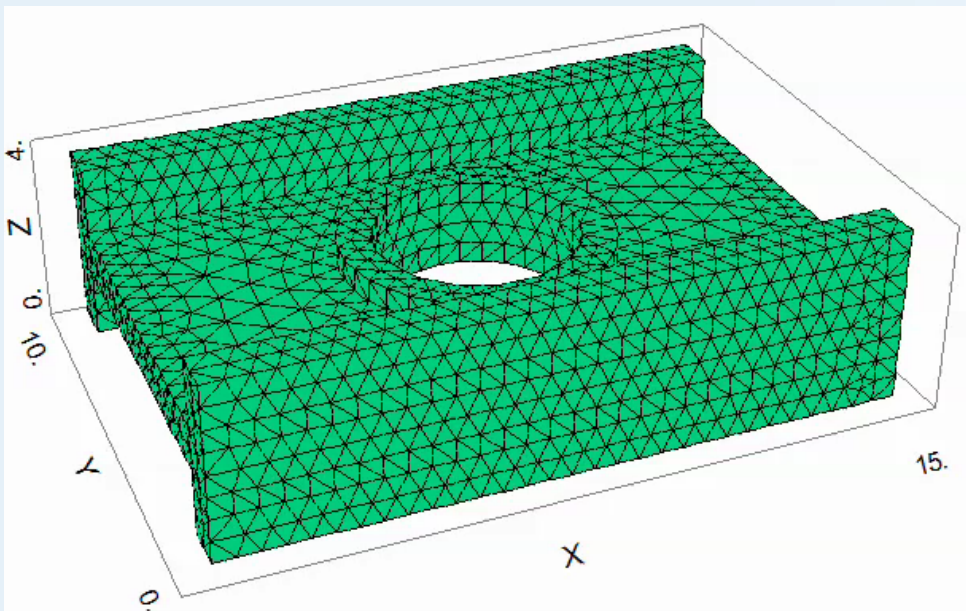
Modeling Mechanical Vibrations and Thermal Conduction in Simulink



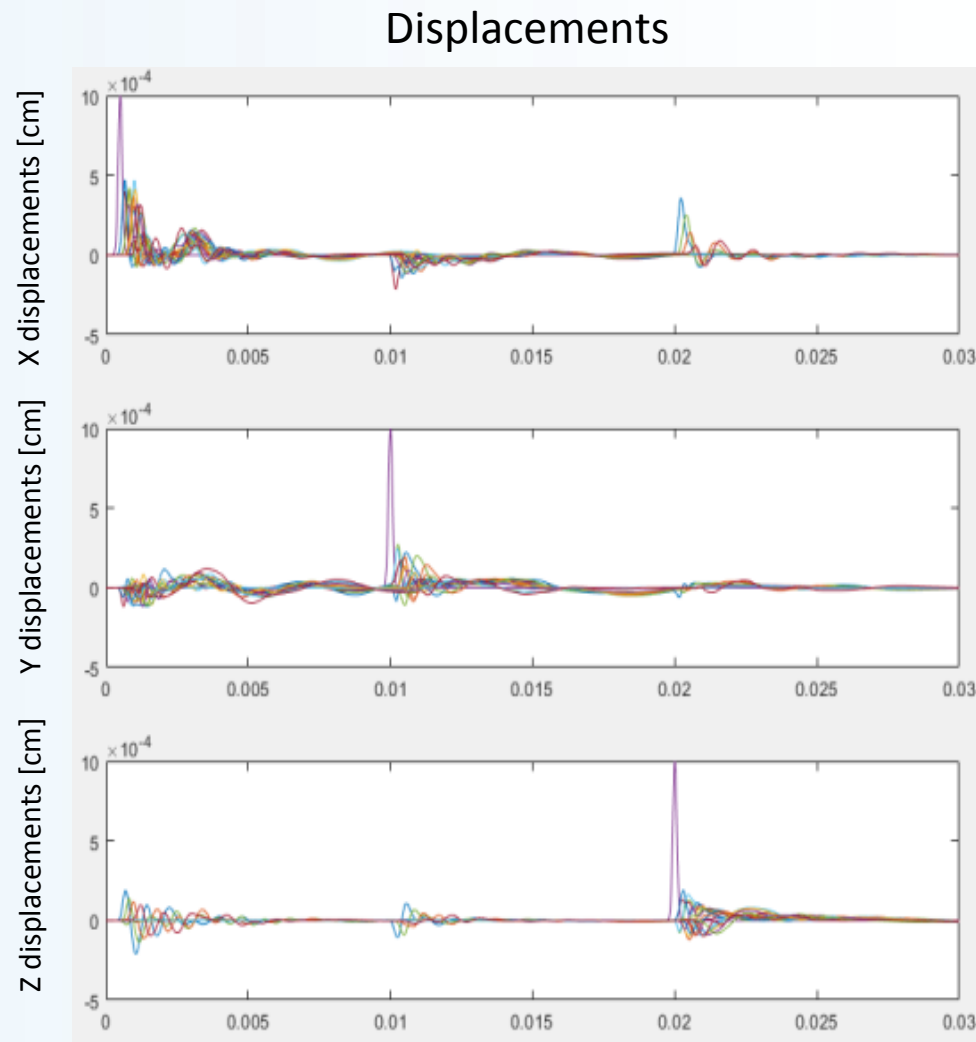
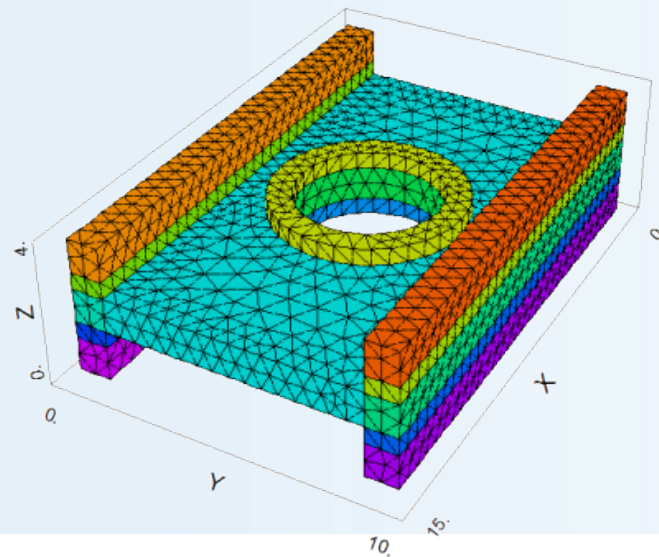
Vibration Example – Shell



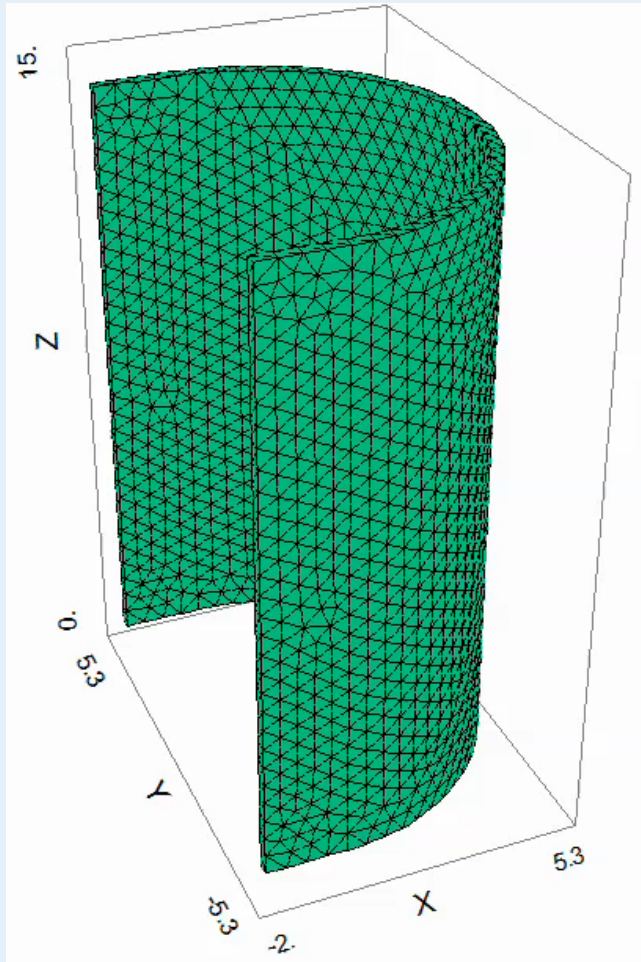
Vibration Example – Beam



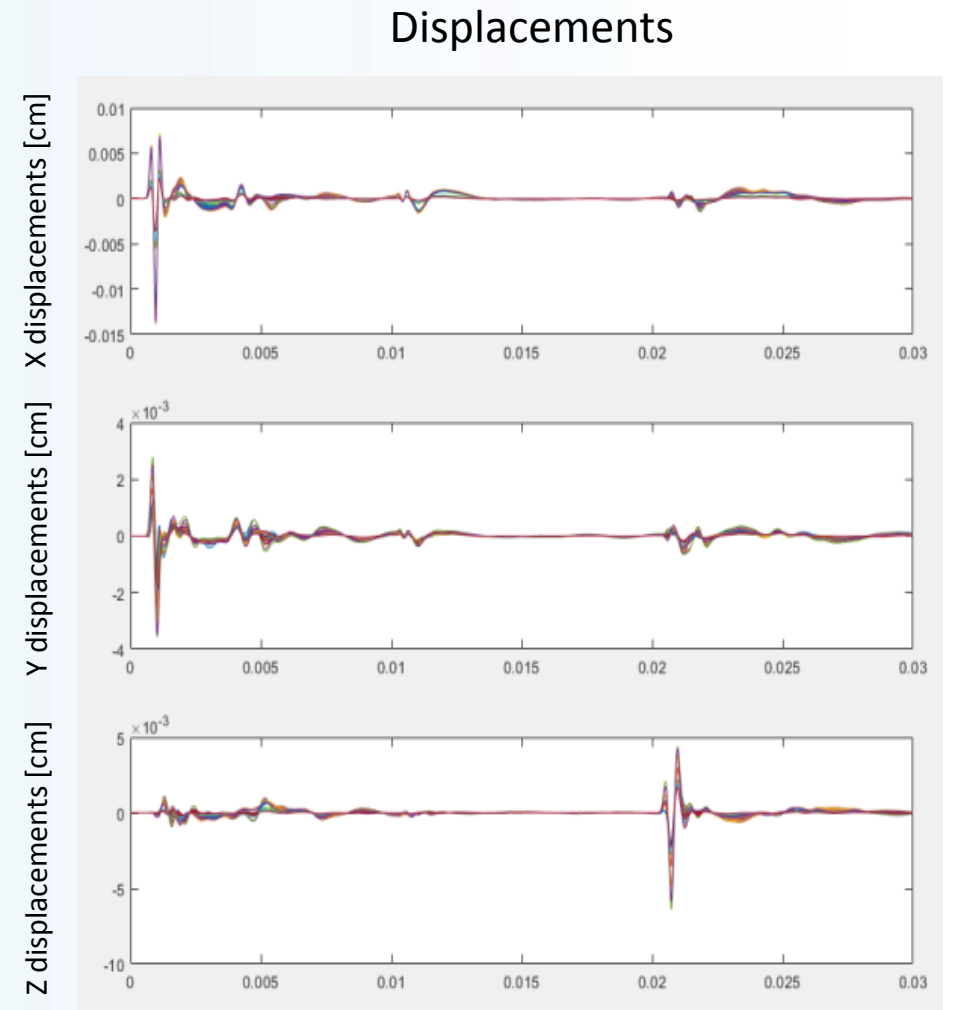
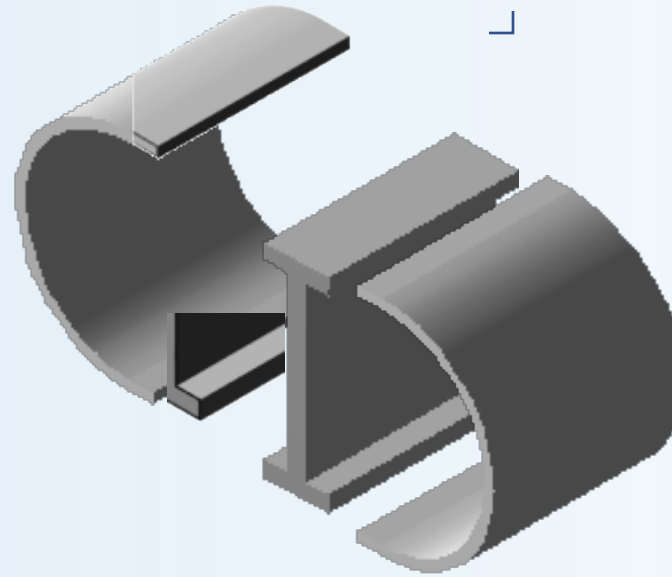
[Click on Video]



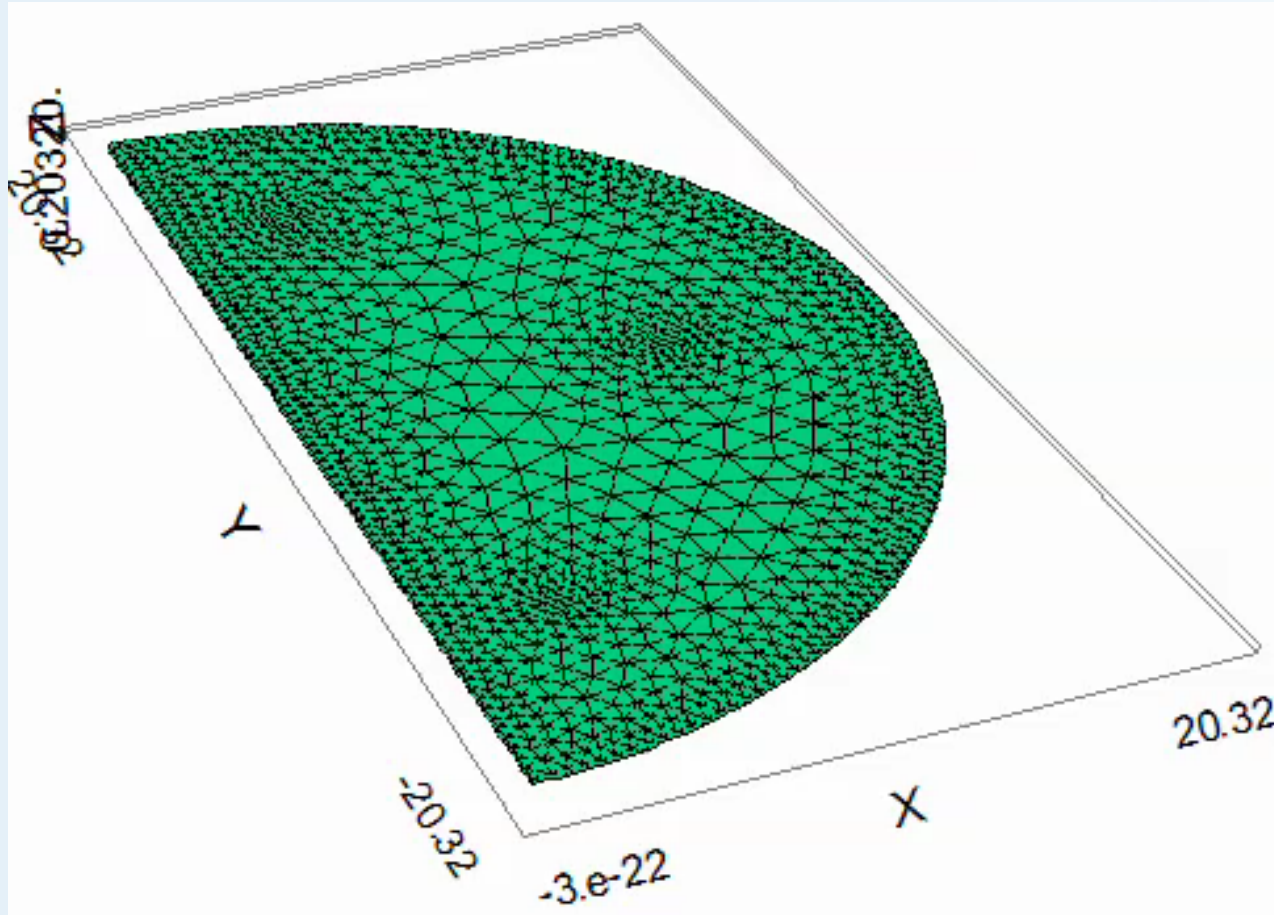
Vibration Example – Shell



[Click on Video]

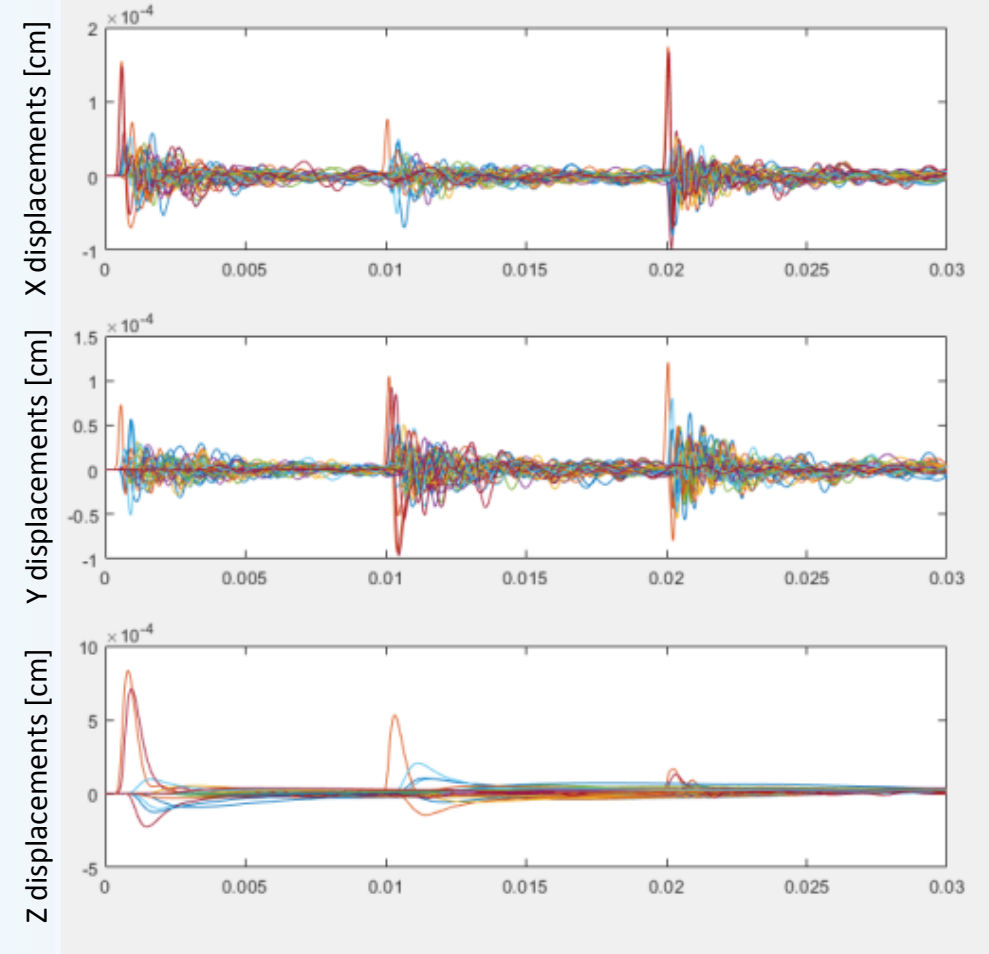


Vibration Example – Circuit Board

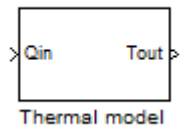
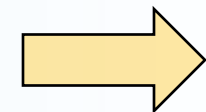
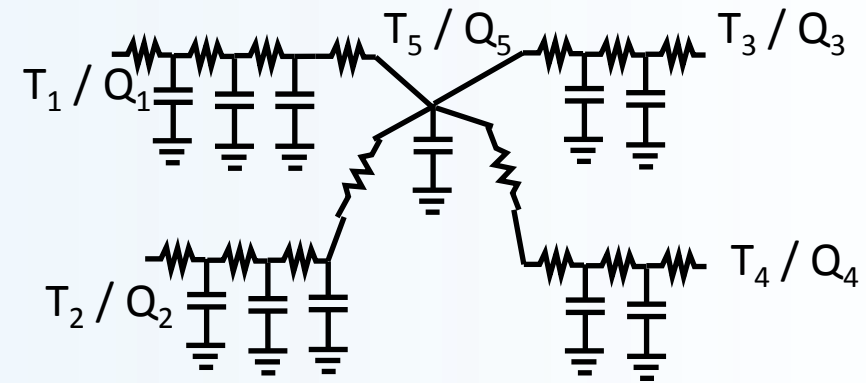
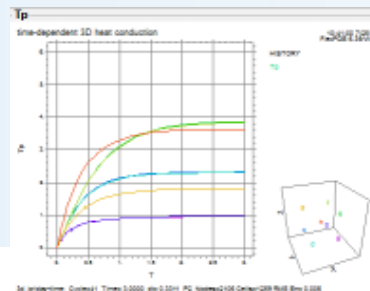
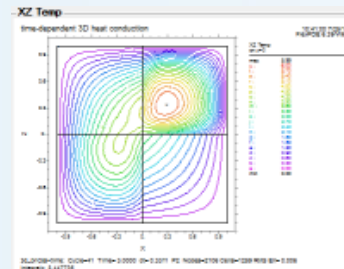
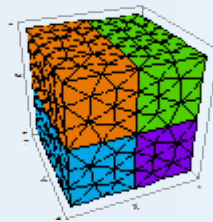


[Click on Video]

Displacements



- Conduction
 - Thermal Resistance
 - Thermal Capacitance
- Convection
 - Free
 - Forced
- Radiation

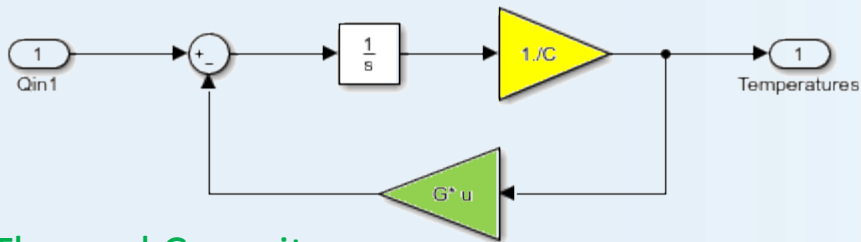


Thermal Modeling - Conduction

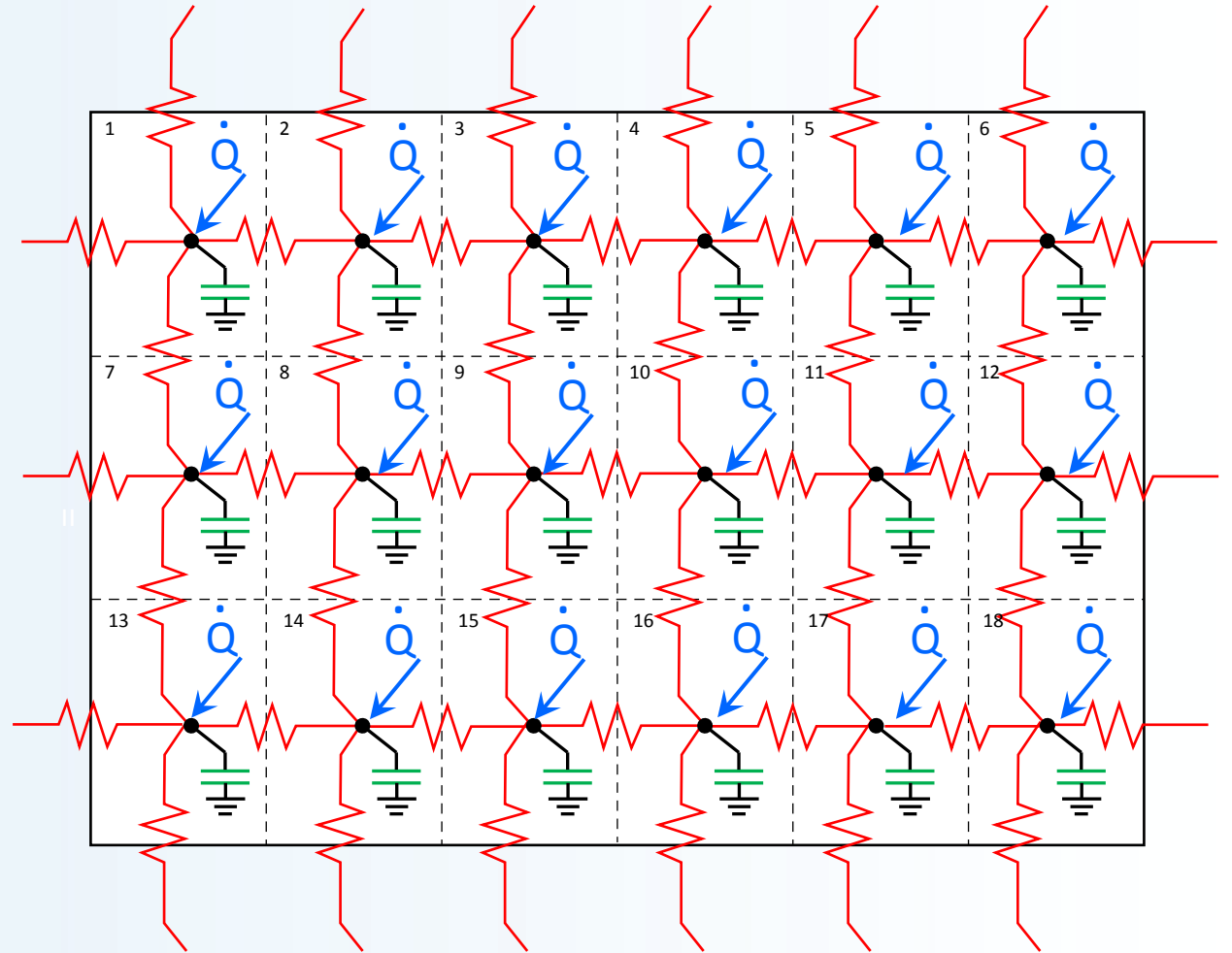


$$\begin{bmatrix} Q_1 \\ Q_2 \\ Q_3 \\ Q_4 \\ Q_5 \\ Q_6 \\ Q_7 \\ Q_8 \\ \vdots \\ \vdots \\ \vdots \\ Q_{18} \end{bmatrix} = \mathbf{G} \begin{bmatrix} T_1 \\ T_2 \\ T_3 \\ T_4 \\ T_5 \\ T_6 \\ T_7 \\ T_8 \\ \vdots \\ \vdots \\ \vdots \\ T_{18} \end{bmatrix} = \mathbf{S} \begin{bmatrix} C_1 \\ C_2 \\ C_3 \\ C_4 \\ C_5 \\ C_6 \\ C_7 \\ C_8 \\ \vdots \\ \vdots \\ \vdots \\ C_{18} \end{bmatrix} \cdot \begin{bmatrix} T_1 \\ T_2 \\ T_3 \\ T_4 \\ T_5 \\ T_6 \\ T_7 \\ T_8 \\ \vdots \\ \vdots \\ \vdots \\ T_{18} \end{bmatrix}$$

Thermal Capacitances



Thermal Capacitances



$$\left[\mathbf{G} \right] = \begin{bmatrix}
 -\Sigma_{row} & -1/R_{12} & 0 & 0 & 0 & 0 & -1/R_{17} & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\
 -1/R_{12} & -\Sigma_{row} & -1/R_{23} & 0 & 0 & 0 & 0 & -1/R_{28} & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\
 0 & -1/R_{23} & -\Sigma_{row} & -1/R_{34} & 0 & 0 & 0 & 0 & -1/R_{39} & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\
 0 & 0 & -1/R_{34} & -\Sigma_{row} & -1/R_{45} & 0 & 0 & 0 & 0 & -1/R_{410} & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\
 0 & 0 & 0 & -1/R_{45} & -\Sigma_{row} & -1/R_{56} & 0 & 0 & 0 & 0 & -1/R_{511} & 0 & 0 & 0 & 0 & 0 & 0 \\
 0 & 0 & 0 & 0 & -1/R_{56} & -\Sigma_{row} & 0 & 0 & 0 & 0 & 0 & -1/R_{612} & 0 & 0 & 0 & 0 & 0 \\
 -1/R_{17} & 0 & 0 & 0 & 0 & -1/R_{67} & -\Sigma_{row} & -1/R_{67} & 0 & 0 & 0 & 0 & -1/R_{713} & 0 & 0 & 0 & 0 \\
 0 & -1/R_{28} & 0 & 0 & 0 & 0 & -1/R_{78} & -\Sigma_{row} & -1/R_{89} & 0 & 0 & 0 & 0 & -1/R_{814} & 0 & 0 & 0 \\
 0 & 0 & -1/R_{39} & 0 & 0 & 0 & 0 & -1/R_{89} & -\Sigma_{row} & -1/R_{910} & 0 & 0 & 0 & 0 & -1/R_{915} & 0 & 0 \\
 0 & 0 & 0 & -1/R_{410} & 0 & 0 & 0 & 0 & -1/R_{910} & -\Sigma_{row} & -1/R_{1011} & 0 & 0 & 0 & 0 & -1/R_{1016} & 0 \\
 0 & 0 & 0 & 0 & -1/R_{511} & 0 & 0 & 0 & 0 & -1/R_{910} & -\Sigma_{row} & -1/R_{1011} & 0 & 0 & 0 & 0 & -1/R_{1117} \\
 0 & 0 & 0 & 0 & 0 & -1/R_{612} & 0 & 0 & 0 & 0 & -1/R_{1011} & -\Sigma_{row} & -1/R_{1112} & 0 & 0 & 0 & -1/R_{1218} \\
 0 & 0 & 0 & 0 & 0 & 0 & -1/R_{713} & 0 & 0 & 0 & 0 & -1/R_{1112} & -\Sigma_{row} & -1/R_{1213} & 0 & 0 & 0 \\
 0 & 0 & 0 & 0 & 0 & 0 & 0 & -1/R_{814} & 0 & 0 & 0 & 0 & -1/R_{1213} & -\Sigma_{row} & -1/R_{1314} & 0 & 0 \\
 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & -1/R_{915} & 0 & 0 & 0 & 0 & -1/R_{1314} & -\Sigma_{row} & -1/R_{1415} & 0 \\
 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & -1/R_{1016} & 0 & 0 & 0 & 0 & -1/R_{1415} & -\Sigma_{row} & -1/R_{1516} \\
 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & -1/R_{1117} & 0 & 0 & 0 & 0 & -1/R_{1516} & -\Sigma_{row} & -1/R_{1617} \\
 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & -1/R_{1218} & 0 & 0 & 0 & 0 & -1/R_{1617} & -\Sigma_{row}
 \end{bmatrix}$$

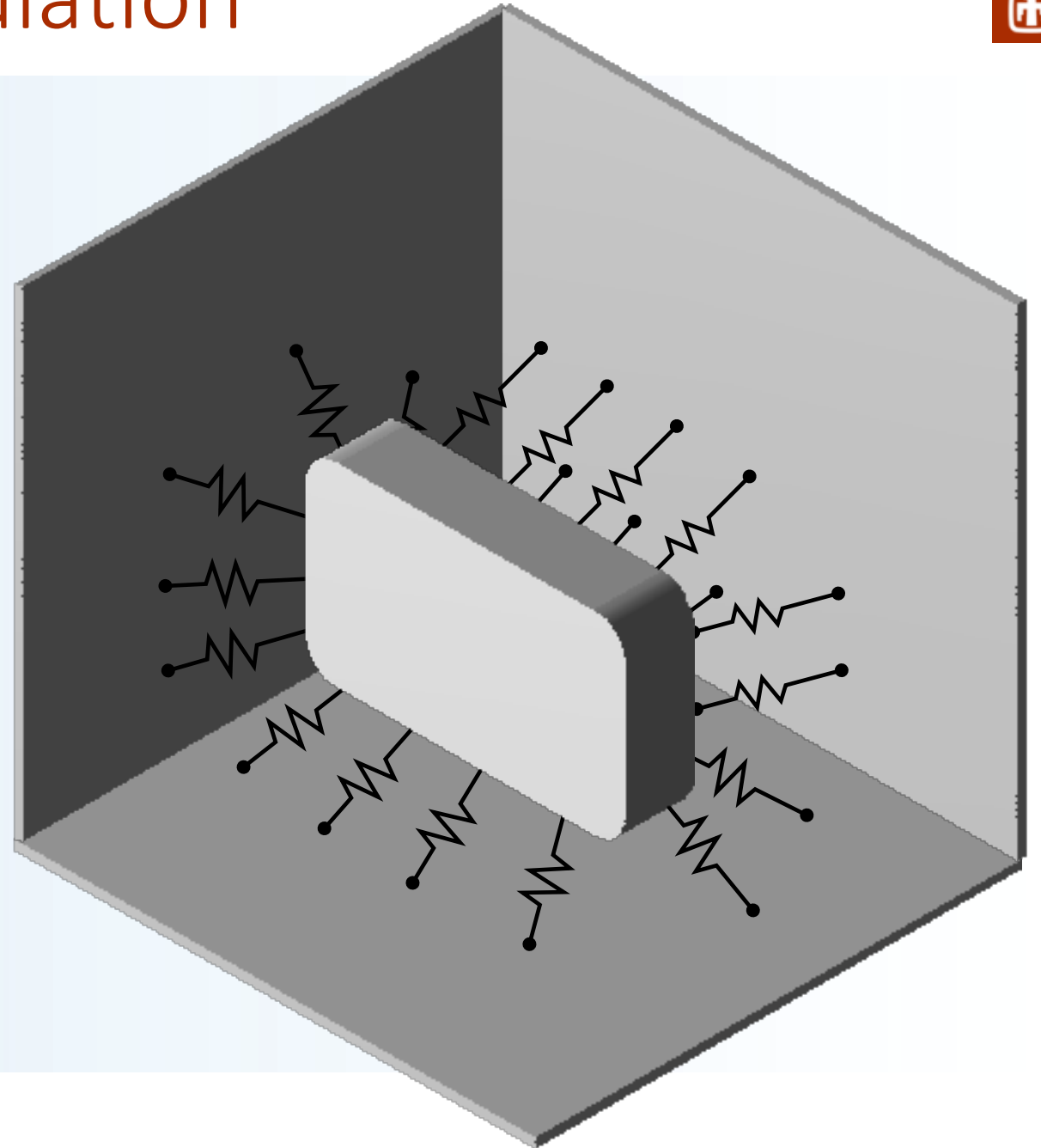
Thermal Modeling - Radiation



$$\frac{q}{A} = \varepsilon k_b (T_1^4 - T_2^4) = \frac{\Delta T}{R}$$



$$R = \frac{(T_1 - T_2)}{\varepsilon k_b (T_1^4 - T_2^4)}$$





- Motors / Actuators
- Electrical Connectors ← Thermal ← shock/vibe
- Pyro ← Thermal ← Pressure Waves



Gasses / Pneumatics
Pressure Waves / Pyrotechnics

G



Radiated EMI (Power Converters)

Radar

Other..



Four Element Example in 1D

$$\underline{M}_1 (k_{01} + sb_{01})(x_0 - x_1) + (k_{21} + sb_{21})(x_2 - x_1) + (k_{31} + sb_{31})(x_3 - x_1) + (k_{41} + sb_{41})(x_4 - x_1) = M_1 s^2 x_1$$

$$\underline{M}_2 (k_{02} + sb_{02})(x_0 - x_2) + (k_{21} + sb_{21})(x_1 - x_2) + (k_{32} + sb_{32})(x_3 - x_2) + (k_{42} + sb_{42})(x_4 - x_2) = M_2 s^2 x_2$$

$$\underline{M}_3 (k_{03} + sb_{03})(x_0 - x_3) + (k_{13} + sb_{13})(x_1 - x_3) + (k_{23} + sb_{23})(x_2 - x_3) + (k_{43} + sb_{43})(x_4 - x_3) = M_3 s^2 x_3$$

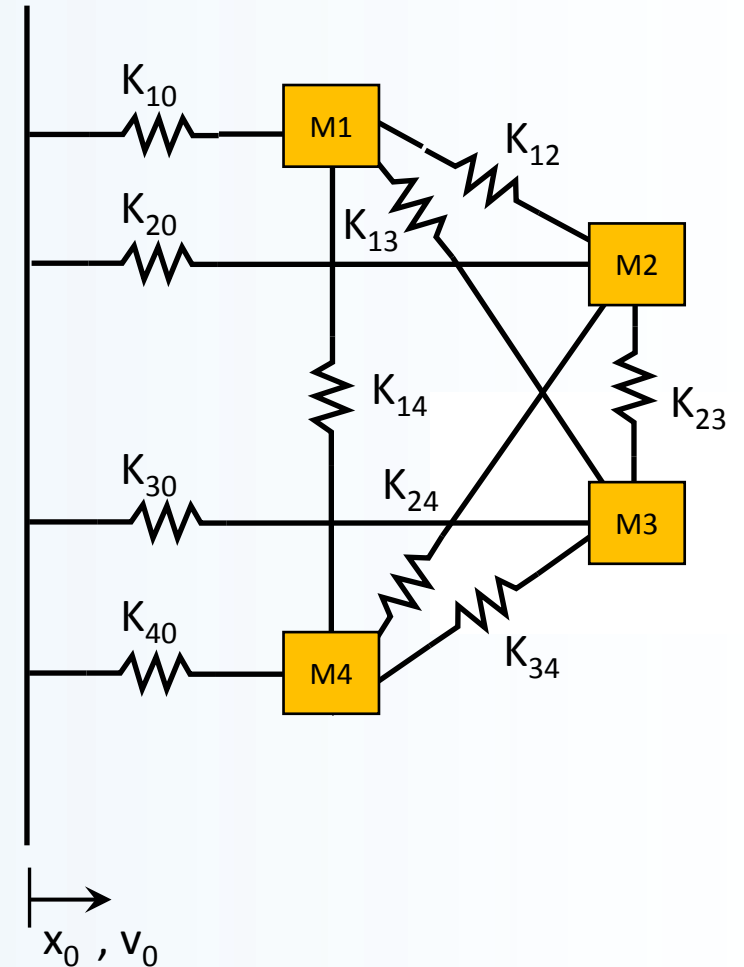
$$\underline{M}_4 (k_{04} + sb_{04})(x_0 - x_4) + (k_{14} + sb_{14})(x_1 - x_4) + (k_{24} + sb_{24})(x_2 - x_4) + (k_{34} + sb_{34})(x_3 - x_4) = M_4 s^2 x_4$$

Multivariable Regression

$$\underline{M}_1 \left(\frac{k_{01}}{M_1}(x_0 - x_1) + \frac{b_{01}}{M_1}(v_0 - v_1) + \frac{k_{21}}{M_1}(x_2 - x_1) + \frac{b_{21}}{M_1}(v_2 - v_1) + \frac{k_{31}}{M_1}(x_3 - x_1) + \frac{b_{31}}{M_1}(v_3 - v_1) + \frac{k_{41}}{M_1}(x_4 - x_1) + \frac{b_{41}}{M_1}(v_4 - v_1) \right) = a_1$$

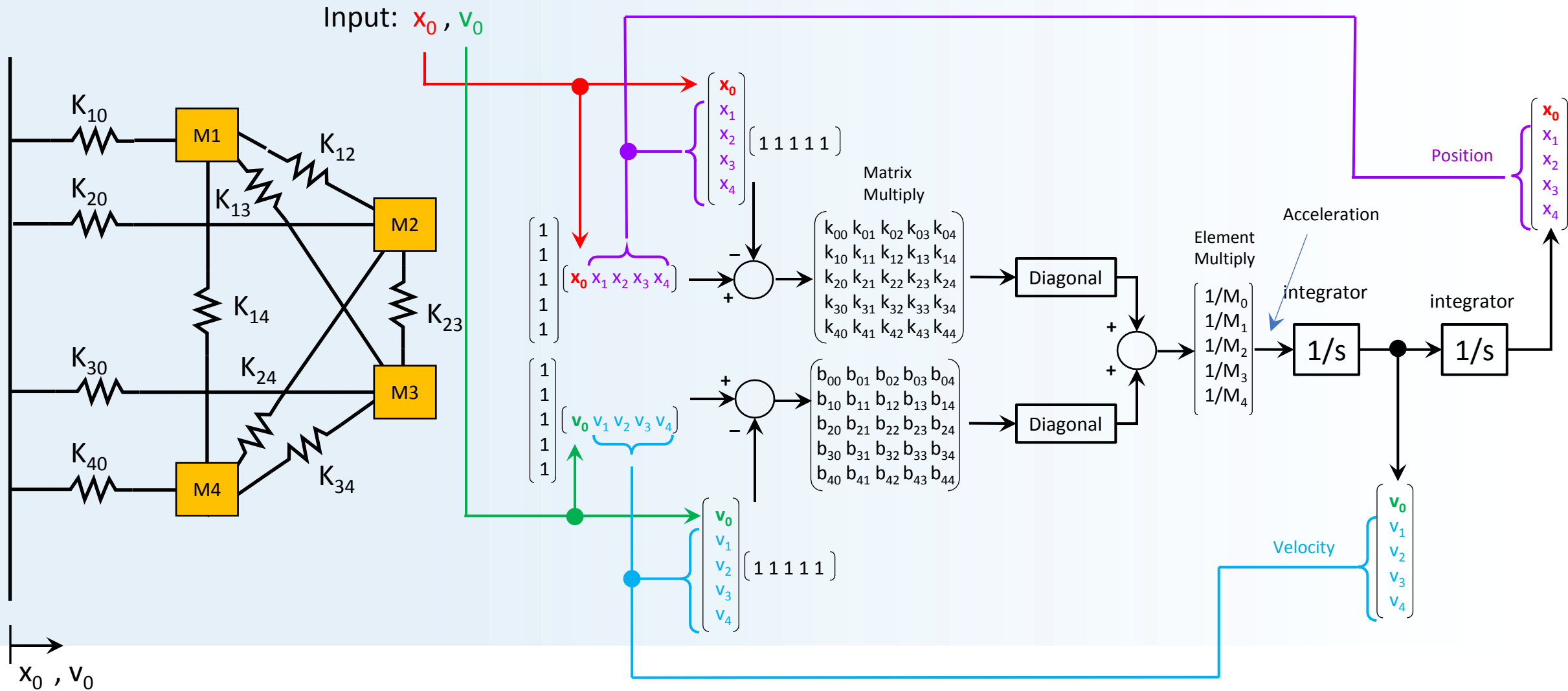
Known

Unknown



Solve for Unknowns \rightarrow Extract Stiffness and Damping tensor components

4 Element System in 1D



Full System Model Simulation Indicates when Model Components go out of spec

